



88ALP01

PCI to NAND, SD and Camera Host
Controller

Datasheet

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PRODUCT OVERVIEW

Overview

The Marvell® single-chip 88ALP01 triple function device integrates a NAND flash controller (with Reed-Solomon ECC), an SD/SDIO controller, and a CMOS Camera Module Interface Controller (CCIC). The device is ideally suited for laptop computing devices and other embedded applications.

The 88ALP01 package is optimized for 32-bit PCI clients. The small 128-pin TQFP package with low pin count minimizes board space, simplifies signal routing, and reduces the number of required PCB layers, resulting in cost-effective motherboard and low profile system implementations.

The 88ALP01 is optimized for maximum throughput and low PCI Bus and CPU utilization. Adequate on-chip memory buffers enable efficient PCI bus cycles and data buffering and eliminates the need for external memory. Direct Memory Address (DMA)-based burst data transfer reduces CPU and PCI bus utilization and improves overall system performance.

General Features

PCI Interface

- Fully compliant with PCI v2.3, 32-bit, 33 MHz



Note

66 MHz support is pending final analysis of PCI timing.

- Programmable cache line size
- 3.3V signalling
- PCI Bus master
- Burst transfer
- Supports DMA and PIO operations
- Supports PCI power states
- Supports three functions in a chip:
 - NAND Flash Controller

- SD/SDIO controller
- Standard camera interface controller
- Each function operating independently:
 - Dedicated driver
 - Separated configuration registers
 - Separated buffers
 - Separated controls
- All functions have host interrupt capability
- Interrupts OR together and sent to INTAn
- On-chip generated power-on reset
- NAND Flash controller supports both DMA and PIO modes
- SD controller supports DMA and PIO modes
- Camera interface controller supports DMA data transfer

NAND Controller

- Configurable to interface with different 8-bit NAND Flash devices (Samsung and Toshiba)
- Supports either 512 byte or 2 KB page sizes
- Configurable to work with different single chip NAND Flash sizes from 128 Mbit to 64 Gbit
- Basic NAND Flash functions:
 - Page program/read
 - Block erase
 - Random program/read
 - ID read
 - Status read
 - Reset and lock
- Supports hardware ECC (Reed-Solomon algorithm)
 - 4 bit-symbol detection and correction
 - 12-bit per symbol with data automatic packing

SD/SDIO

- Supports 1-bit/4-bit SD, SDIO cards
- Up to 48 MHz for SD
- Supports interrupts for information exchange between host and cards

- Supports read wait commands in SD cards
- Hardware Cyclic Redundancy Check (CRC) generating and checking
- Supports DMA and PIO operations
- Suspend and resume in SDIO cards

**Note**

Only SDMEM card has been tested at this time.

Camera Interface

- Supports high-resolution CMOS camera module
- Supports both RGB and YUV formats
- Standard 8-wire camera interfaces
- DMA pixel data transfer
- Host interrupt capability
- Supports programmable pixel clock

Package

- 14mm x 14mm, 128 TQFP (EPAD)
- Lead-free package available

Table of Contents

Product Overview	3
1 Signal Description	21
1.1 Signal Diagram	21
1.2 128-Pin TQFP Package	22
1.3 Pin Description	23
2 Functional Description.....	29
2.1 System Overview	29
2.1.1 System Component Description	29
2.1.1.1 Power Supplies	29
2.1.1.2 External Reference Clock.....	30
2.1.1.3 External TWSI EEPROM (VPD).....	30
2.2 Functional Overview.....	30
2.2.1 PCI Bus Interface Unit	30
2.2.1.1 Slave Access to Configuration Space	31
2.2.1.2 Slave Access to Memory Resources.....	31
2.2.1.3 Master Access	31
2.2.1.4 Parity Generation/Check	32
2.2.2 NAND Flash Controller	33
2.2.2.1 Write Operations	33
2.2.2.2 Read Operations	33
2.2.3 SDIO Host Controller	38
2.2.3.1 Features	39
2.2.3.2 SD Bus Protocol Description	39
2.2.3.3 Special Bus Transactions	40
2.2.3.4 Card Detection	44
2.2.4 CMOS Camera Interface Controller.....	45
2.2.4.1 Features	45
2.2.4.2 I/O Signals.....	45
2.2.4.3 Interface Modes.....	46
2.2.4.4 Input/Output Matrix.....	47
2.2.4.5 Video Timing Reference Codes (SAV and EAV).....	47
2.2.4.6 RGB Input Data Formats.....	48
2.2.4.7 CCIC Recommended Programming Sequence	49
2.2.5 VPD Serial EEPROM.....	49
2.2.5.1 VPD Serial EEPROM Loader	50
2.2.5.2 VPD Two-Wire Serial Interface	51
2.2.6 Device Reset	52
2.2.7 Reset Configuration	52
2.2.8 Clock Generation/Distribution	52
2.2.9 PME on Wake up event	52
2.2.9.1 Power Management Support.....	53
2.2.9.2 PCI Device Power States	53
2.2.9.3 Wake-Up Sequence	53
2.2.10 Clock Run (CLK_RUNn)	54
2.2.11 Power on Reset Delay	54

3	Register Description	55
3.1	Registers Introduction	55
3.1.1	Register Conventions	55
3.2	PCI Configuration Register File	56
3.2.1	Configuration Data Access	56
3.2.2	PCI Header Region	57
3.2.2.1	Vendor ID Register	60
3.2.2.2	Device ID Register	60
3.2.2.3	Command Register	60
3.2.2.4	Status Register	62
3.2.2.5	Revision ID Register	63
3.2.2.6	Class Code Register	63
3.2.2.7	Cache Line Register	64
3.2.2.8	Latency Timer Register	64
3.2.2.9	Header Type Register	65
3.2.2.10	Built-in Self Test Register	65
3.2.2.11	Base Address Register (1st)	65
3.2.2.12	Subsystem Vendor ID Register	66
3.2.2.13	Subsystem ID Register	66
3.2.2.14	New Capabilities Pointer	67
3.2.2.15	Interrupt Line Register	67
3.2.2.16	Interrupt Pin Register	67
3.2.2.17	Min_Gnt Register	68
3.2.2.18	Max_Lat Register	68
3.2.2.19	Expansion ROM Base Address Register	68
3.2.3	Device Dependent Region	68
3.2.3.1	SD Slot Information Register	69
3.2.3.2	Access Control and VPD Control Registers	69
3.2.3.3	Power Management Capability ID Register	71
3.2.3.4	Power Management Next Item Pointer	71
3.2.3.5	Power Management Capabilities Register	72
3.2.3.6	Power Management Control/Status Register	73
3.2.3.7	Power Management Data Register	74
3.2.3.8	Power Management Data Table	74
3.2.3.9	VPD Capability ID Register	75
3.2.3.10	VPD Next Item Pointer	75
3.2.3.11	VPD Address Register	75
3.2.3.12	VPD Data Register	76
3.2.3.13	VPD Serial EEPROM Loader Control Register	76
3.2.3.14	MSI Capability ID Register (MSI Cap ID)	76
3.2.3.15	MSI Next Item Pointer	77
3.2.3.16	MSI Message Control	77
3.2.3.17	MSI Message Address	78
3.2.3.18	MSI Message Data	79
3.2.3.19	Calibration Control Register	79
3.2.3.20	Calibration Status Register	80
3.2.3.21	Discard Counter Register	80
3.2.3.22	Retry Counter Register	80
3.3	Global Control Registers	81
3.3.1	Register Map	81
3.3.2	Register Descriptions	81
3.3.2.1	Control/Status	81
3.3.2.2	Interrupt Source Register	83
3.3.2.3	Interrupt Mask Register	83

3.3.2.4	Interrupt HW Error Source Register	84
3.3.2.5	Interrupt HW Error Mask Register	85
3.3.2.6	PLL Control Register	85
3.3.2.7	Block Control Register	86
3.3.2.8	GPIO Functional Control Register	86
3.3.2.9	Test Control Register	87
3.3.2.10	General Purpose I/O Register	87
3.3.2.11	VPD TWSI (HW) Registers	88
3.3.2.12	VPD TWSI (SW) Register	89
3.4	NAND Flash Unit	90
3.4.1	Register Map	90
3.4.2	Registers	91
3.5	SDIO Host Controller Registers	101
3.5.1	Register Map	101
3.6	CMOS Camera Interface Controller	124
3.6.1	Register Map	124
3.6.2	Register Descriptions	125
4	Mechanical Drawings	140
5	Electrical Specifications	141
5.1	Absolute Maximum Ratings	141
5.2	Recommended Operating Conditions	141
5.3	Package Thermal Conditions	142
5.4	DC Electrical Characteristics	142
5.4.1	Current Consumption AVDD_PLL	142
5.4.2	Current Consumption VDD	143
5.4.3	Current Consumption VDDO	143
5.4.4	Current Consumption VDDOC	143
5.5	Input Clock Specifications	143
5.6	Internal Resistors	144
5.7	PCI Bus Interface Unit	144
5.7.1	DC Electricals	144
5.7.2	AC Electricals	145
5.7.3	Protocol Timing	145
5.8	NAND Flash Controller	146
5.8.1	DC Electricals	146
5.8.2	Protocol Timing	146
5.9	SDIO	149
5.9.1	DC Electricals	149
5.9.2	Protocol Timing	150
5.10	CMOS Camera Interface	152
5.10.1	DC Electricals	152
5.10.2	Protocol Timing	152
5.11	JTAG Test Interface	153
5.11.1	DC Electricals	153
5.11.2	Protocol Timing	154
5.12	GPIO	155
5.12.1	DC Electricals	155
5.12.2	LED Mode	155



6	Part Order Numbering/Package Marking	156
6.1	Part Order Numbering	156
6.2	Package Marking	157
A	Acronyms and Abbreviations.....	158

List of Tables

1	Signal Description	21
1.1	Signal Diagram	21
1.2	128-Pin TQFP Package	22
1.3	Pin Description	23
	Table 1: Pin Type Definitions	23
	Table 2: SD/SDIO Interface (3.3V)	23
	Table 3: PCI Interface (3.3V)	24
	Table 4: NAND Flash (3.3V)	25
	Table 5: Camera Interface (2.5 or 3.3V)	26
	Table 6: VPD TWSI (Serial EEPROM, 3.3V)	26
	Table 7: Main Clock Interface (PLL, 3.3V)	27
	Table 8: GPIO Interface (3.3V)	27
	Table 9: Joint Test Action Group (JTAG) and Test Interface (3.3V)	27
	Table 10: Core VDD Control (1.2V)	28
	Table 11: Power and Ground	28
2	Functional Description	29
2.1	System Overview	29
2.2	Functional Overview	30
	Table 12: Samsung Type 1 NAND Flash Device Command Sets and Support	35
	Table 13: Samsung Type 2 NAND Flash Device Command Sets and Support	35
	Table 14: CCIC Chip-Level I/O Signal Descriptions (2.5V or 3.3V)	45
	Table 15: Supported Interface Modes	46
	Table 16: Color I/O Matrix	47
	Table 17: Video Timing Reference Codes	47
	Table 18: Bits States	47
	Table 19: 8-bit RGB 5:6:5 Input Data Format	48
	Table 20: 8-bit YCbCr 4:2:2 Input Data Format	48
	Table 21: Data Format of First 8 byte Block within Serial EEPROM	51
	Table 22: 88ALP01 Configuration Pins	52
	Table 23: Device Power Status	53
3	Register Description	55
3.1	Registers Introduction	55
	Table 24: Register Type Definitions	55
3.2	PCI Configuration Register File	56
	Table 25: PCI Header Region Overview	57
	Table 26: PCI Header Region Register Map	58
	Table 55: Power Management Data Table	74
3.3	Global Control Registers	81

Table 71: Global Control Register Map	81
3.4 NAND Flash Unit.....	90
Table 86: NAND Flash Unit Registers	90
3.5 SDIO Host Controller Registers	101
Table 114: SDIO Host Controller Register Map.....	101
3.6 CMOS Camera Interface Controller	124
Table 159: CMOS Camera Interface Controller Register Map	124
4 Mechanical Drawings	140
5 Electrical Specifications	141
5.1 Absolute Maximum Ratings	141
Table 183: Absolute Maximum Ratings	141
5.2 Recommended Operating Conditions	141
Table 184: Recommended Operating Conditions.....	141
5.3 Package Thermal Conditions	142
Table 185: 14 x 14 mm TQFP Package	142
5.4 DC Electrical Characteristics.....	142
Table 186: Current Consumption AVDD_PLL	142
Table 187: Current Consumption VDD	143
Table 188: Current Consumption VDDO	143
Table 189: Current Consumption VDDOC.....	143
5.5 Input Clock Specifications	143
Table 190: 24 MHz Reference Clock Timing	143
5.6 Internal Resistors	144
Table 191: Internal Resistors	144
5.7 PCI Bus Interface Unit.....	144
Table 192: PCI Bus Interface Unit DC Specifications	144
Table 193: PCI Bus Interface Unit AC Specifications	145
Table 194: 66 and 33 MHz PCI Timing.....	145
5.8 NAND Flash Controller.....	146
Table 195: NAND Flash DC Specifications	146
Table 196: NAND Flash Timing	148
5.9 SDIO	149
Table 197: SDIO DC Specifications.....	149
Table 198: SDIO Low Speed Timing	150
Table 199: SDIO High Speed Timing	151
5.10 CMOS Camera Interface.....	152
Table 200: CMOS Camera Interface DC Specifications	152
Table 201: CMOS Camera Timing	153
5.11 JTAG Test Interface	153
Table 202: JTAG Test Interface DC Specifications for 3.3V Signaling.....	153
Table 203: JTAG Timing	154
5.12 GPIO	155

Table 204: GPIO DC Specifications for 3.3V Signaling	155
Table 205: LED Mode	155
6 Part Order Numbering/Package Marking.....	156
6.1 Part Order Numbering	156
Table 206: 88ALP01 Part Order Options	156
6.2 Package Marking	157
Table 207: Acronyms and Abbreviations	158

List of Figures

1	Signal Description	21
1.1	Signal Diagram.....	21
	Figure 1: Signal Diagram	21
1.2	128-Pin TQFP Package	22
	Figure 2: TQFP Pinout	22
1.3	Pin Description	23
2	Functional Description	29
2.1	System Overview	29
	Figure 3: 88ALP01 System Diagram	29
2.2	Functional Overview	30
	Figure 4: 88ALP01 Functional Block Diagram	30
	Figure 5: NAND Flash Controller Block Diagram	34
	Figure 6: NAND Flash	34
	Figure 7: Reed-Solomon ECC Diagram	36
	Figure 8: SDIO Host Block Diagram	39
	Figure 9: "No Response" and "No Data" Operation	40
	Figure 10: Multiple Block Read Operation	40
	Figure 11: Multiple Block Write with Card Busy Operation	40
	Figure 12: Read Wait Controlled by Stopping Clock	41
	Figure 13: Command Token Format	41
	Figure 14: Response Token Format	42
	Figure 15: Data Packet Format, Standard Bus (Only DAT0 Used)	42
	Figure 16: Data Packet Format, Wide Bus (All Four Data Lines Used)	42
	Figure 17: Host Initialization Flow Chart	44
	Figure 18: CCIC Block Diagram	46
	Figure 19: Internal Structure of Serial EEPROM	50
3	Register Description	55
3.1	Registers Introduction	55
	Figure 20: Register Conventions	55
3.2	PCI Configuration Register File	56
3.3	Global Control Registers	81
3.4	NAND Flash Unit	90
3.5	SDIO Host Controller Registers	101
3.6	CMOS Camera Interface Controller	124
4	Mechanical Drawings	140
	Figure 21: 128-pin TQFP Mechanical Drawing	140

5	Electrical Specifications	141
5.1	Absolute Maximum Ratings	141
5.2	Recommended Operating Conditions	141
5.3	Package Thermal Conditions	142
5.4	DC Electrical Characteristics	142
5.5	Input Clock Specifications	143
5.6	Internal Resistors	144
5.7	PCI Bus Interface Unit	144
5.8	NAND Flash Controller	146
	Figure 22: NAND Flash Command Write	147
	Figure 23: NAND Flash Address Write	147
	Figure 24: NAND Flash Data Write	148
	Figure 25: NAND Flash Data Read	148
5.9	SDIO	149
	Figure 26: SDIO Low Speed Timing Diagram	150
	Figure 27: SDIO High Speed Timing Diagram	151
5.10	CMOS Camera Interface	152
	Figure 28: CMOS Camera Interface TWSI Timing Diagram	152
	Figure 29: CMOS Camera Interface Timing Diagram	152
5.11	JTAG Test Interface	153
	Figure 30: JTAG Timing Diagram	154
5.12	GPIO	155
6	Part Order Numbering/Package Marking	156
6.1	Part Order Numbering	156
	Figure 31: Sample Part Number	156
6.2	Package Marking	157
	Figure 32: Commercial Package Marking and Pin 1 Location	157

List of Registers

1	Signal Description	21
1.1	Signal Diagram.....	21
1.2	128-Pin TQFP Package	22
1.3	Pin Description	23
2	Functional Description.....	29
2.1	System Overview	29
2.2	Functional Overview.....	30
3	Register Description	55
3.1	Registers Introduction	55
3.2	PCI Configuration Register File.....	56
	Table 27: Vendor ID Register.....	60
	Offset: 0x00	
	Table 28: Device ID Register.....	60
	Offset: 0x02	
	Table 29: Command Register.....	60
	Offset: 0x04	
	Table 30: Status Register	62
	Offset: 0x06	
	Table 31: Revision ID Register.....	63
	Offset: 0x08	
	Table 32: Programming Interface Register, Lower Byte.....	63
	Offset: 0x09	
	Table 33: Sub-Class Register, Middle Byte.....	63
	Offset: 0x0A	
	Table 34: Base-Class Register, Upper Byte.....	63
	Offset: 0x0B	
	Table 35: Cache Line Size Register	64
	Offset: 0x0C	
	Table 36: Latency Timer Register	64
	Offset: 0x0D	
	Table 37: Base-Class Register	65
	Offset: 0x0E	
	Table 38: Built-in Self Test Register	65
	Offset: 0x0F	
	Table 39: Base Address Register (1st).....	65
	Offset: 0x10	
	Table 40: Subsystem Vendor ID Register	66
	Offset: 0x2C	
	Table 41: Subsystem ID Register.....	66
	Offset: 0x2E	
	Table 42: New Capabilities Pointer Register	67
	Offset: 0x34	

Table 43:	Interrupt Line Register	67
Offset:	0x3C	
Table 44:	Interrupt Pin Register.....	67
Offset:	0x3D	
Table 45:	Min_Gnt Register.....	68
Offset:	0x3E	
Table 46:	Max_Lat Register	68
Offset:	0x3F	
Table 47:	SD Slot Information Register	69
Offset:	0x40	
Table 48:	Access Control Register	69
Offset:	0x80	
Table 49:	VPD Control Register	70
Offset:	0x84	
Table 50:	Power Management Capability ID Register.....	71
Offset:	0x88	
Table 51:	Power Management Next Item Pointer.....	71
Offset:	0x89	
Table 52:	Power Management Capabilities Register	72
Offset:	0x8A	
Table 53:	Power Management Control/Status Register	73
Offset:	0x8C	
Table 54:	Power Management Data Register	74
Offset:	0x8F	
Table 56:	VPD Capability ID Register	75
Offset:	0x90	
Table 57:	VPD Next Item Pointer	75
Offset:	0x91	
Table 58:	VPD Address Register.....	75
Offset:	0x92	
Table 59:	VPD Data Registers	76
Offset:	0x94	
Table 60:	VPD Serial EEPROM Loader Control Register	76
Offset:	0x9A	
Table 61:	MSI Capability ID Register (MSI Cap ID)	76
Offset:	0x9C	
Table 62:	MSI Next Item Pointer Register	77
Offset:	0x9D	
Table 63:	MSI Message Control Register.....	77
Offset:	0x9E	
Table 64:	MSI Message Lower Address Register	78
Offset:	0xA0	
Table 65:	MSI Message Upper Address Register	78
Offset:	0xA4	
Table 66:	MSI Message Data Register.....	79
Offset:	0xA8	
Table 67:	Calibration Control Register	79
Offset:	0xB4	
Table 68:	Calibration Status Register	80
Offset:	0xB6	
Table 69:	Discard Counter Register	80
Offset:	0xB8	

Table 70:	Retry Counter Register	80
Offset:	0xBA	
3.3	Global Control Registers	81
Table 72:	Control/Status Register	81
Offset:	0x3004	
Table 73:	Interrupt Source Register	83
Offset:	0x3008	
Table 74:	Interrupt Mask Register	83
Offset:	0x300C	
Table 75:	Interrupt HW Error Source Register	84
Offset:	0x3010	
Table 76:	Interrupt HW Error Mask Register	85
Offset:	0x3014	
Table 77:	PLL Control Register	85
Offset:	0x3030	
Table 78:	Block Control Register	86
Offset:	0x3034	
Table 79:	GPIO Functional Control Register	86
Offset:	0x3038	
Table 80:	Test Control Register	87
Offset:	0x3158	
Table 81:	General Purpose I/O Register	87
Offset:	0x315C	
Table 82:	VPD TWSI (HW) Control Register	88
Offset:	0x3160	
Table 83:	VPD TWSI (HW) Data Register	89
Offset:	0x3164	
Table 84:	VPD TWSI (HW) IRQ Register	89
Offset:	0x3168	
Table 85:	VPD TWSI (SW) Register	90
Offset:	0x316C	
3.4	NAND Flash Unit	90
Table 87:	Control Register	91
Offset:	0x00	
Table 88:	Control Register 2	92
Offset:	0x04	
Table 89:	Control Register 3	93
Offset:	0x08	
Table 90:	Status Register	93
Offset:	0x0C	
Table 91:	Interrupt Register	93
Offset:	0x10	
Table 92:	Interrupt Mask Register	94
Offset:	0x14	
Table 93:	Data Length Register	94
Offset:	0x18	
Table 94:	Address Register	94
Offset:	0x1C	
Table 95:	Address Register 2	95
Offset:	0x20	

Table 96:	Timing Parameter Register 1	95
Offset:	0x24	
Table 97:	Timing Parameter Register 2	96
Offset:	0x28	
Table 98:	Timing Parameter Register 3	96
Offset:	0x2C	
Table 99:	Non-Memory Read Data Register	97
Offset:	0x30	
Table 100:	Read ECC Generated Code Register	97
Offset:	0x34	
Table 101:	Read ECC Read Code Register	97
Offset:	0x38	
Table 102:	Read ECC Result Register	97
Offset:	0x3C	
Table 103:	DMA Control Register	98
Offset:	0x40	
Table 104:	DMA Address Register 0	98
Offset:	0x44	
Table 105:	RS ECC Decode CRC Register	98
Offset:	0x4C	
Table 106:	RS ECC Decode Syndrome 0 and 1 Register	99
Offset:	0x50	
Table 107:	RS ECC Decode Syndrome 2 and 3 Register	99
Offset:	0x54	
Table 108:	RS ECC Decode Syndrome 4 and 5 Register	99
Offset:	0x58	
Table 109:	RS ECC Decode Syndrome 6 and 7 Register	100
Offset:	0x5C	
Table 110:	Control Register 4	100
Offset:	0x60	
Table 111:	NAND I/O Drive Strength Register	100
Offset:	0x64	
Table 112:	Read Data Registers	100
Offset:	0x1000 to 0x183C	
Table 113:	Write Data Registers	101
Offset:	0x2000 to 0x283C	
3.5	SDIO Host Controller Registers	101
Table 115:	System Address Low Register	103
Offset:	0x00	
Table 116:	System Address High Register	103
Offset:	0x02	
Table 117:	Block Size Register	103
Offset:	0x04	
Table 118:	Block Count Register	104
Offset:	0x06	
Table 119:	Argument Low Register	104
Offset:	0x08	
Table 120:	Argument High Register	104
Offset:	0x0A	
Table 121:	Transfer Mode Register	104
Offset:	0x0C	

Table 122: Command Register.....	105
Offset: 0x0E	
Table 123: Response Register 0.....	106
Offset: 0x10	
Table 124: Response Register 1.....	106
Offset: 0x12	
Table 125: Response Register 2.....	106
Offset: 0x14	
Table 126: Response Register 3.....	106
Offset: 0x16	
Table 127: Response Register 4.....	107
Offset: 0x18	
Table 128: Response Register 5.....	107
Offset: 0x1A	
Table 129: Response Register 6.....	107
Offset: 0x1C	
Table 130: Response Register 7.....	107
Offset: 0x1E	
Table 131: Buffer Data Port0 Register	107
Offset: 0x20	
Table 132: Buffer Data Port1 Register	108
Offset: 0x22	
Table 133: Present State Register 0	108
Offset: 0x24	
Table 134: Present State Register 1	109
Offset: 0x26	
Table 135: Host Control Register	110
Offset: 0x28	
Table 136: Block Gap Control Register	111
Offset: 0x2A	
Table 137: Clock Control Register.....	112
Offset: 0x2C	
Table 138: Timeout Control/Software Reset Register	113
Offset: 0x2E	
Table 139: Normal Interrupt Status Register	114
Offset: 0x30	
Table 140: Error Interrupt Status Register.....	115
Offset: 0x32	
Table 141: Normal Interrupt Status Enable Register.....	116
Offset: 0x34	
Table 142: Error Interrupt Status Enable Register	117
Offset: 0x36	
Table 143: Normal Interrupt Status Interrupt Enable Register	118
Offset: 0x38	
Table 144: Error Interrupt Status Interrupt Enable Register	119
Offset: 0x3A	
Table 145: Auto CMD12 Error Status Register	120
Offset: 0x3C	
Table 146: Capabilities Register.....	120
Offset: 0x40	
Table 147: Capabilities Register 1.....	121
Offset: 0x42	

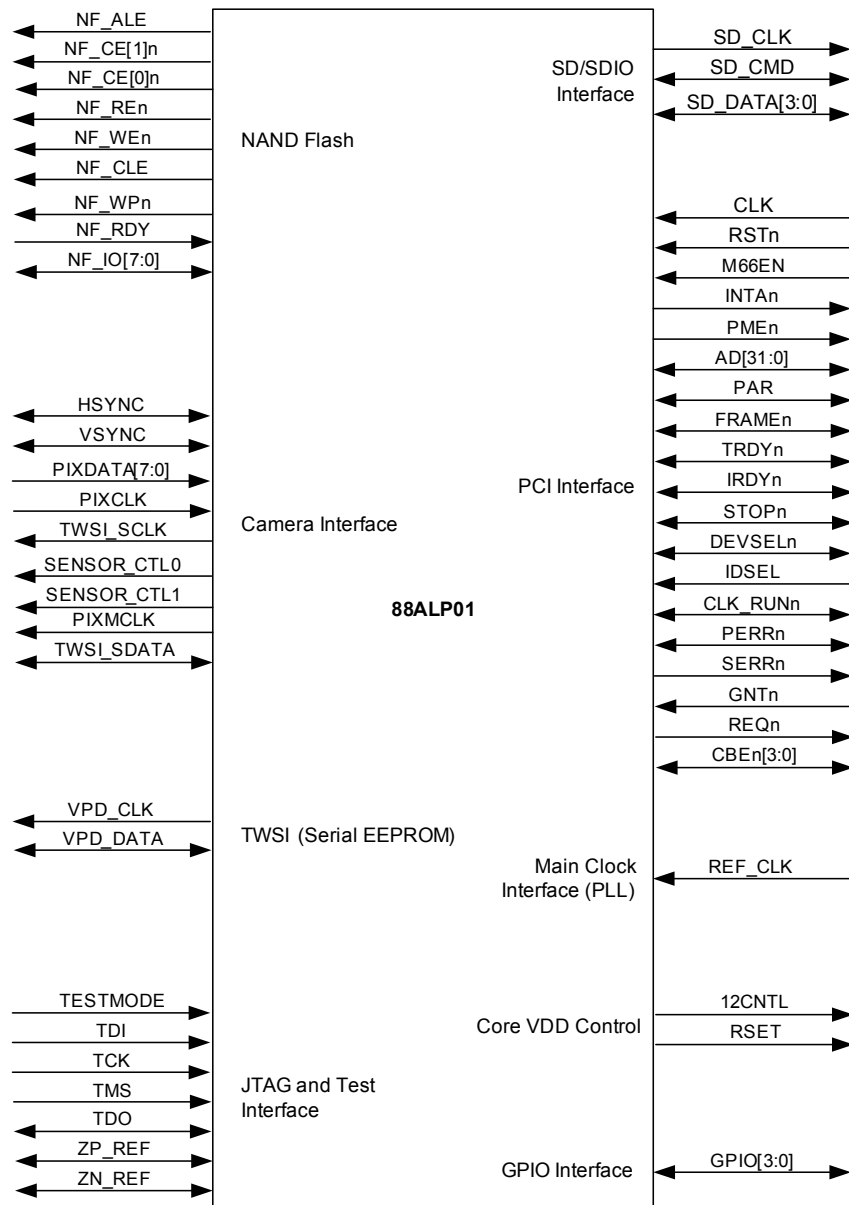
Table 148: Capabilities Register 2.....	121
Offset: 0x44	
Table 149: Capabilities Register 3.....	121
Offset: 0x46	
Table 150: Maximum Current Register 0.....	122
Offset: 0x48	
Table 151: Maximum Current Register 1.....	122
Offset: 0x4A	
Table 152: Maximum Current Register 2.....	122
Offset: 0x4C	
Table 153: Maximum Current Register 3.....	122
Offset: 0x4E	
Table 154: I/O Control Register.....	123
Offset: 0x60	
Table 155: Command 1 Register.....	123
Offset: 0x6A	
Table 156: SD Drive Strength Register	123
Offset: 0x7C	
Table 157: Slot Interrupt Status Register	123
Offset: 0xFC	
Table 158: Host Control Version Register	124
Offset: 0xFE	
3.6 CMOS Camera Interface Controller	124
Table 160: Y0-Base Address Register	125
Offset: 0x00	
Table 161: Y1-Base Address Register	125
Offset: 0x04	
Table 162: Y2-Base Address Register	125
Offset: 0x08	
Table 163: U0-Base Address Register	126
Offset: 0x0C	
Table 164: U1-Base Address Register	126
Offset: 0x10	
Table 165: U2-Base Address Register	126
Offset: 0x14	
Table 166: V0-Base Address Register	126
Offset: 0x18	
Table 167: V1-Base Address Register	127
Offset: 0x1C	
Table 168: V2-Base Address Register	127
Offset: 0x20	
Table 169: Image Pitch Register	127
Offset: 0x24	
Table 170: IRQ RAW Status Register	127
Offset: 0x28	
Table 171: IRQ Mask Register	128
Offset: 0x2C	
Table 172: IRQ Status Register.....	129
Offset: 0x30	
Table 173: Image Size Register	131
Offset: 0x34	

Table 174: Image Offset Register.....	131
Offset: 0x38	
Table 175: Control 0 Register.....	132
Offset: 0x3C	
Table 176: Control 1 Register.....	135
Offset: 0x40	
Table 177: Clock Control Register.....	136
Offset: 0x88	
Table 178: SRAM TC0 Register (Test Only)	137
Offset: 0x8C	
Table 179: SRAM TC1 Register (Test Only)	137
Offset: 0x90	
Table 180: General Purpose (GPR) Register	137
Offset: 0xB4	
Table 181: TWSI Control 0 Register.....	138
Offset: 0xB8	
Table 182: TWSI Control 1 Register.....	139
Offset: 0xBC	
4 Mechanical Drawings	140
5 Electrical Specifications	141
5.1 Absolute Maximum Ratings	141
5.2 Recommended Operating Conditions	141
5.3 Package Thermal Conditions	142
5.4 DC Electrical Characteristics	142
5.5 Input Clock Specifications	143
5.6 Internal Resistors	144
5.7 PCI Bus Interface Unit.....	144
5.8 NAND Flash Controller.....	146
5.9 SDIO	149
5.10 CMOS Camera Interface.....	152
5.11 JTAG Test Interface	153
5.12 GPIO	155
6 Part Order Numbering/Package Marking.....	156
6.1 Part Order Numbering	156
6.2 Package Marking	157

1 Signal Description

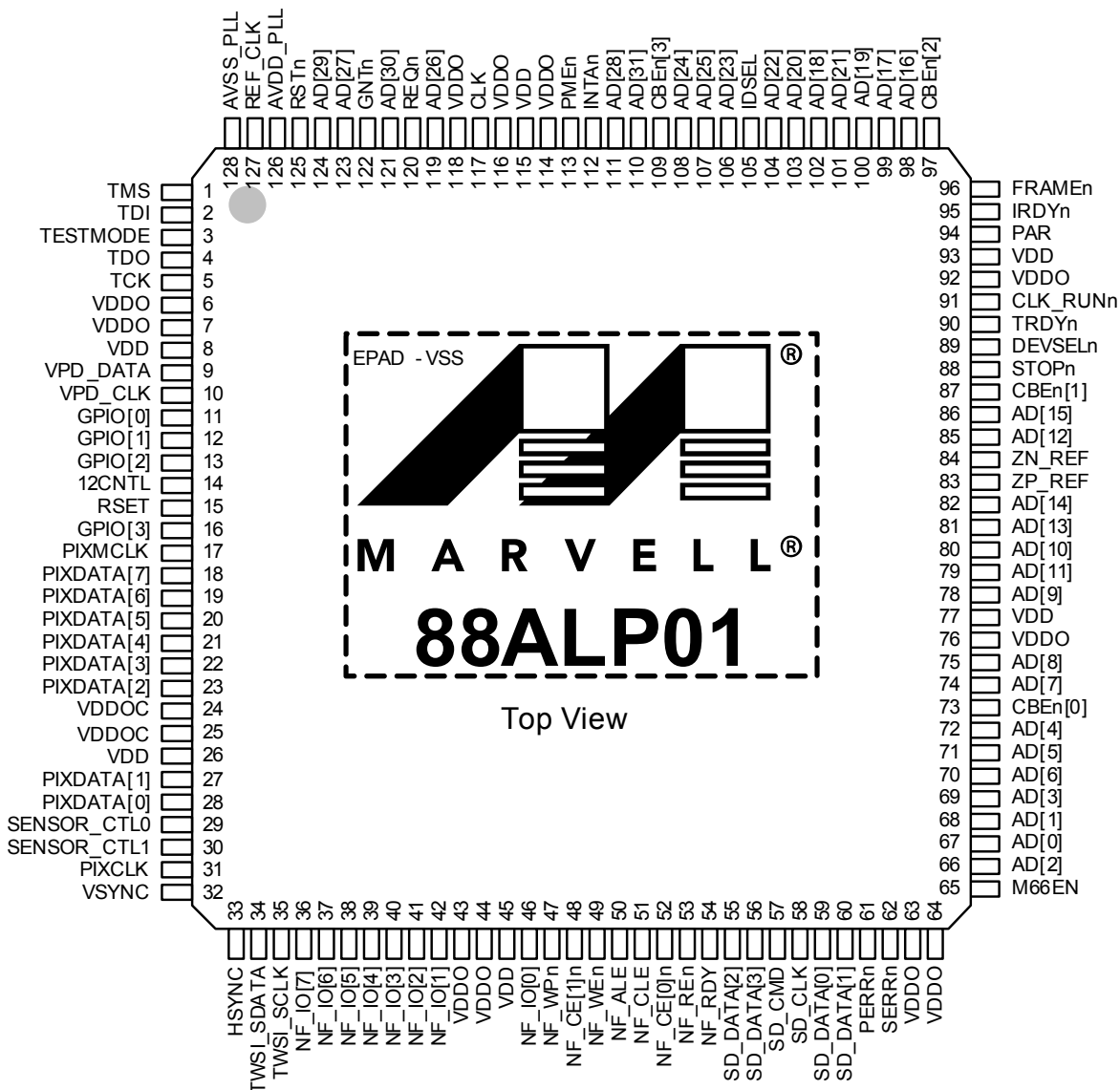
1.1 Signal Diagram

Figure 1: Signal Diagram



1.2 128-Pin TQFP Package

Figure 2: TQFP Pinout



1.3 Pin Description

Table 1: Pin Type Definitions

Pin Type	Definition
A	Analog
D	Open drain output
H	Input with hysteresis
I	Input
I/O	Input/output
mA	DC sink capability
n	Active low
O	Output
PD	Weak internal pull down
PU	Weak internal pull up
Z	Tri-state output

**Note**

For resistor strengths, refer to [Section 5.6, Internal Resistors, on page 144](#).

Table 2: SD/SDIO Interface (3.3V)

Package Pin #	Pin Name	Pin Type	Description
58	SD_CLK	O	SD/SDIO Clock Output
57	SD_CMD	I/O	SD/SDIO Command/Response
56, 55, 60, 59	SD_DATA[3:0]	I/O	SD/SDIO Data Line [3:0]

Table 3: PCI Interface (3.3V)

Package Pin #	Pin Name	Pin Type	Description
110, 121, 124, 111, 123, 119, 107, 108, 106, 104, 101, 103, 100, 102, 99, 98, 86, 82, 81, 85, 79, 80, 78, 75, 74, 70, 71, 72, 69, 66, 68, 67	AD[31:0]	I/O	Multiplexed Data and Address Lines
109, 97, 87, 73	CBEn[3:0]	I/O, Z	Bus Command and Byte Enable Lines, active low
117	CLK	I	PCI Bus Clock Frequency from 0 to 66 MHz.
91	CLK_RUNn	I/O	Clock Run, active low The CLK_RUNn pin is a mobile device clock management signal. CLK_RUNn is an active low pin that follows the guidelines described in the PCI Mobile Design Guide.
89	DEVSELn	I/O, Sustained Z	Device Select, active low Asserted by the adapter with medium DEVSELn timing.
96	FRAMEn	I/O, Sustained Z	Cycle Frame, active low
122	GNTn	I, Z	Bus Grant, active low
105	IDSEL	I	Initialization Device Select
112	INTAn	O, D	Interrupt Signal, active low Indicates an Interrupt request from the adapter to the system. The assertion and deassertion of the INTAn is asynchronous to CLK. A pending request is cleared by the interrupt service of the device driver. External 4.7 k Ω pull up
95	IRDYn	I/O, Sustained Z	Initiator Ready, active low
65	M66EN	I	66 MHz Enable Indicates to a device whether the bus segment is operating at 66 or 33 MHz.
94	PAR	I/O, Z	Even Parity over AD[31:0] and CBEn[3:0]
61	PERRn	I/O, Sustained Z	Parity Error, active low Asserted by the adapter for all data parity errors detected, if enabled.
113	PMEn	O, D	Power Management Event, active low

Table 3: PCI Interface (3.3V) (Continued)

Package Pin #	Pin Name	Pin Type	Description
120	REQn	O, Z	Bus Request, active low Asserted by the adapter to gain bus ownership, kept asserted until second last data phase of a transaction.
125	RSTn	I	Reset Signal, active low
62	SERRn	O, D	System Error Signal, active low Asserted by adapter for all address parity errors detected, if enabled.
88	STOPn	I/O, Sustained Z	Target Stop Request, active low Used by the adapter only for target disconnect with/without data.
90	TRDYn	I/O, Sustained Z	Target Ready, active low

Table 4: NAND Flash (3.3V)

Package Pin #	Pin Name	Pin Type	Description
50	NF_ALE	O, PU	NAND Flash Address Enable When this signal is high, writes to NAND Flash indicates address configuration write.
48	NF_CE[1]n	O, PU	NAND Flash Chip Enable 2, active low When this signal is high, the NAND Flash is enabled for access.
52	NF_CE[0]n	O, PU	NAND Flash Chip Enable, active low When this signal is high, the NAND Flash is enabled for access.
51	NF_CLE	O, PU	NAND Flash Command Latch Enable
36, 37, 38, 39, 40, 41, 42, 46	NF_IO[7:0]	I/O, PU	NAND Flash Data I/O [7:0] When NF_IO[0] is strapped low during power-on reset, serial EEPROM load is enabled. When NF_IO[1] is strapped low during power-on reset, the internal PLL is bypassed.
54	NF_RDY	I, PU	NAND Flash Ready This input signal indicates status of Flash operations to the controller. External 4.7 kΩ pull up
53	NF_REn	O, PU	NAND Flash Read Enable, active low
49	NF_WEn	O, PU	NAND Flash Write Enable, active low
47	NF_WPn	O, PU	NAND Flash Write Protect, active low Protects against inadvertent program and erase options. All program and erase operations are disabled when this signal is asserted low.

Table 5: Camera Interface (2.5 or 3.3V)

Package Pin #	Pin Name	Pin Type	Description
33	HSYNC	I/O	Horizontal Sync driven by external CMOS sensor
31	PIXCLK	I	Pixel Clock
18, 19, 20, 21, 22, 23, 27, 28	PIXDATA[7:0]	I	Pixel Data [7:0] Synchronous to PIXCLK. PIXDATA[7:6], PD (Default)
17	PIXMCLK	O	Pixel Master Clock
29	SENSOR_CTL0	O	Sensor Control 0 This output signal is used to control the external CMOS sensor's reset or power down pin. It requires an external pull-up or pull-down to put the external CMOS sensor into reset/power-down mode after boot.
30	SENSOR_CTL1	O	Sensor Control 1 This output signal is used to control the external CMOS sensor's reset or power down pin. It requires an external pull-up or pull-down to put the external CMOS sensor into reset/power-down mode after boot.
35	TWSI_SCLK	O	TWSI Serial Clock An external pull-up resistor is needed, for example, 2k Ω .
34	TWSI_SDATA	I/O	TWSI Serial Data An external pull-up resistor is needed, for example, 2k Ω .
32	VSYNC	I/O	Vertical Sync driven by external CMOS sensor

Table 6: VPD TWSI (Serial EEPROM, 3.3V)

Package Pin #	Pin Name	Pin Type	Description
10	VPD_CLK	O	TWSI Bus Clock Line to Serial EEPROM External 4.7 k Ω pull up When VPD_CLK is strapped high during power-on reset, it signals the capability to operate in 66 MHz.
9	VPD_DATA	I/O	TWSI Bus Data Line to Serial EEPROM External 4.7 k Ω pull up

Table 7: Main Clock Interface (PLL, 3.3V)

Package Pin #	Pin Name	Pin Type	Description
127	REF_CLK	I	Input from 24 MHz Reference Clock (external oscillator)

Table 8: GPIO Interface (3.3V)

Package Pin #	Pin Name	Pin Type	Description
16, 13, 12, 11	GPIO[3:0]	I/O	General Purpose I/O The GPIO pins have the following functions: GPIO[3]: Camera power enable GPIO[2]: SD socket power enable GPIO[1]: SD card write protection, active low. A 100 k Ω pull up is required. GPIO[0]: SD card active, active low (for LED)

Table 9: Joint Test Action Group (JTAG) and Test Interface (3.3V)

Package Pin #	Pin Name	Pin Type	Description
5	TCK	I	Test Clock Used to clock state information and test data into and out of the device during operation of the TAP. Pull down for normal operation
2	TDI	I	Test Data In for JTAG Boundary Scan Test Path Used to serially shift test data and instructions into the device during TAP operation. Pull down for normal operation
4	TDO	I/O	Test Data Out for JTAG Boundary Scan Test Path, active low Used to shift test data and test instructions serially out of the device during TAP operation. SD card detect for normal operation A 100 k Ω pull up to 3.3V is required.
3	TESTMODE	I	Selection of Internal Test 4.7 k Ω pull down for normal operation
1	TMS	I	Test Mode Select Used to control the state of the TAP controller in the device. Pull down
84	ZN_REF	I/O	Calibration Pad, Reference for PCIZN 27.1 Ω 1% pull up

Table 9: Joint Test Action Group (JTAG) and Test Interface (3.3V) (Continued)

Package Pin #	Pin Name	Pin Type	Description
83	ZP_REF	I/O	Calibration Pad, Reference for PCIZP 33.4 Ω 1% pull down

Table 10: Core VDD Control (1.2V)

Package Pin #	Pin Name	Pin Type	Description
14	12CNTL	O	Regulator Control This signal controls an external PNP transistor to generate the 1.2V power supply.
15	RSET	A	RSET 6 k Ω 1% resistor pull down

Table 11: Power and Ground

Package Pin #	Pin Name	Pin Type	Description
126	AVDD_PLL	A, Power	Analog 3.3V Power Supply
128	AVSS_PLL	A, Ground	Analog Ground
8, 26, 45, 77, 93, 115	VDD	Power	1.2V ($\pm 5\%$) Power Supply
6, 7, 43, 44, 63, 64, 76, 92, 114, 116, 118	VDDO	Power	3.3V ($\pm 5\%$) Power Supply
24, 25	VDDOC	Power	2.5V to 3.3V ($\pm 5\%$) Power Supply I/O supply for camera interface Needed to match camera I/O level but always on

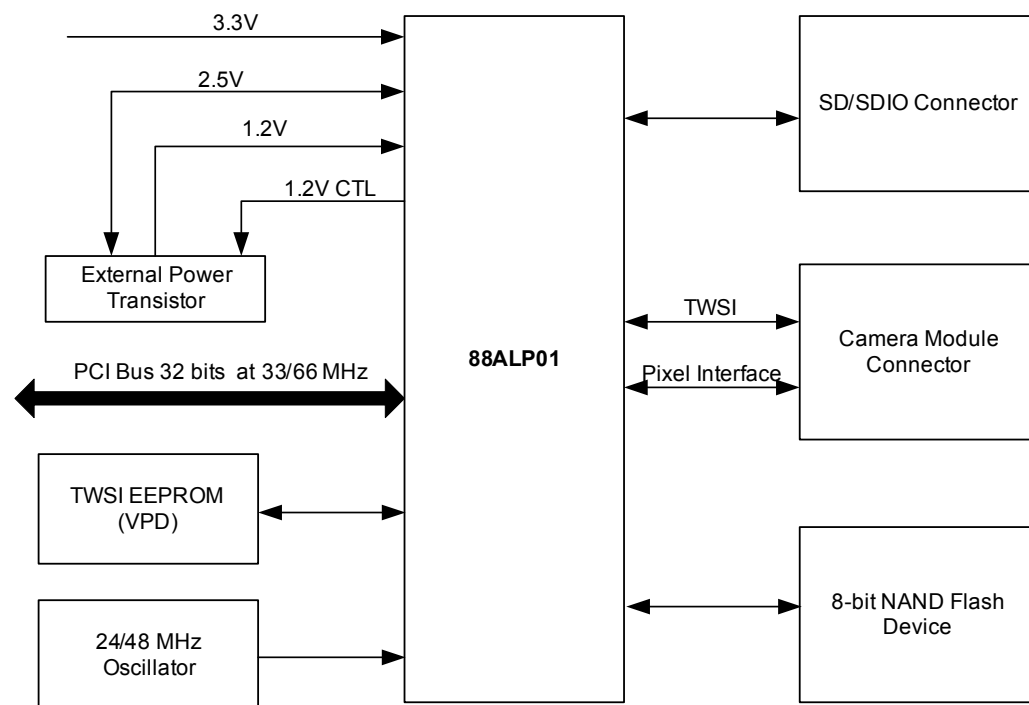
2 Functional Description

2.1 System Overview

The 88ALP01 is a single-chip, triple function device for PCI Local Bus system and is designed to address high-performance, low power system requirements. The 88ALP01 integrates a NAND Flash controller, an SD/SDIO host controller, and a CMOS Camera Interface Controller.

Figure 3 shows the main components of a PCI sub-system using the 88ALP01. Each component is described in the following sections.

Figure 3: 88ALP01 System Diagram



2.1.1 System Component Description

2.1.1.1 Power Supplies

The 88ALP01 requires 3.3V, 2.5V, and 1.2V external supplies. The 2.5V supply is required for 2.5V camera interface. If the camera interface supports 3.3V, then the 2.5V supply can be eliminated. The 88ALP01 also has an internal voltage regulator that provides a 1.2V output to be used with an external transistor to provide the 1.2V supply for the on-chip digital logics. If the system has 1.2V supply, the internal regulator output should be left floating.

2.1.1.2 External Reference Clock

The 88ALP01 requires a 24 MHz external reference clock (from an external oscillator). The 88ALP01 has an internal programmable PLL that provides the core clock for different on-chip modules. The 88ALP01 generates a 96 MHz clock for NAND Flash and a 48 MHz clock for SD and the camera interface.

The 88ALP01 can also be configured to bypass the internal PLL and use a 48 MHz clock input. In this case, the 48 MHz clock is connected to all modules.

2.1.1.3 External TWSI EEPROM (VPD)

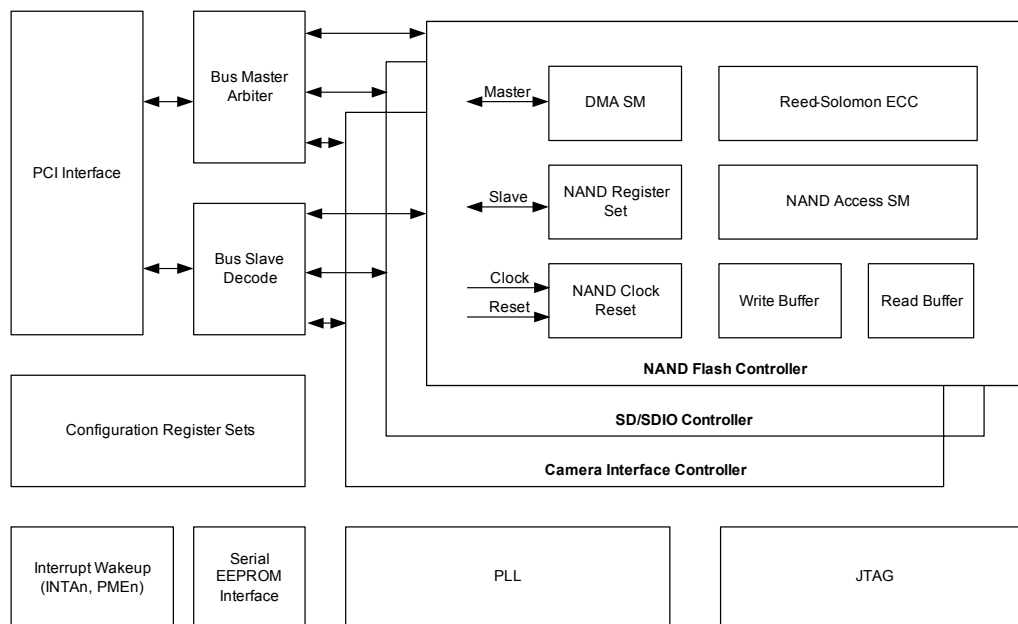
The 88ALP01 can optionally use an external serial EEPROM (1 or 2 KB). After PCI reset, the 88ALP01 will automatically overwrite PCI Configuration Registers (and other registers) with data from the EEPROM. This is how a system manufacturer alters the default PCI information.

2.2 Functional Overview

Figure 4 shows the main blocks of the 88ALP01. Each interface and block is described in the following sections. The functions are as follows:

- Function 0—NAND Flash Controller
- Function 1—SD/SDIO Controller
- Function 2—CMOS Camera Interface Controller

Figure 4: 88ALP01 Functional Block Diagram



2.2.1 PCI Bus Interface Unit

The PCI Bus Interface Unit (BIU) provides the framework for interfacing with the PCI Local Bus. It comprises several state machines running synchronously with the PCI bus clock signal (CLK). Except for the interrupt signal that is independent from the PCI bus clock, all outputs are synchronously generated with the rising edge of CLK. All inputs are synchronously sampled.

The BIU handles:

- Access to the configuration data
- Access to memory mapped resources
- PCI bus master operation of 88ALP01

Data transfers via the PCI bus are 4 bytes wide (32 bit). The transfer rate also depends on the bus clock (0 to 33 MHz / up to 66 MHz).

The BIU handles the basic protocol for accesses via the PCI bus. It is built of several state machines running synchronously with the PCI bus CLK signal. All inputs are synchronously sampled. All outputs are synchronously generated on the rising edge of CLK to assure that interrupts are serviced independently of the PCI clock speed.

The 88ALP01 is a 32-bit device. It is mapped into the lower 4 GB of the address space and therefore ignores all dual address cycles.

The master section of the BIU is treated in more detail when data transfer over the PCI bus is discussed. It is not of interest in connection with the programming interface since bus master operations are performed by the 88ALP01 hardware according to the preconfigured control registers.

2.2.1.1 Slave Access to Configuration Space

Slave access to the configuration space is also not of primary interest for the programming interface. However, it may be valuable for troubleshooting with PCI bus analyzers and exerciser tools. This bus operation is performed by the target sequencer state machine. Acceptance and termination of a transaction is determined by a backend consisting of the configuration decoder and the Configuration Register File.

The adapter responds to type 0 configuration accesses (AD[1:0] = "00", IDSELn). If the configuration space is targeted for a burst operation, it responds with a disconnect on the first data transfer.

The Configuration Register File can be accessed with 8-bit, 16-bit, or 32-bit transfers.

Configuration transactions are not aborted (target initiated termination).

On read transactions, all data is driven as defined for full 32-bit accesses independent of CBEn[3:0].

2.2.1.2 Slave Access to Memory Resources

There is only one accessible resource, the Memory Mapped I/O-Resources.

Accesses to memory mapped I/O-Resources are performed by the target sequencer state machine. Acceptance and termination of a transaction is determined by a backend consisting of the control decoder and the control register file.

The control registers have to be accessed with the minimum data width (8-, 16-, or 32-bit) transfers depending on the definition of the registers.

On read transactions, all data is driven as defined for full 32-bit accesses independently of CBEn[3:0]. If the memory resources are targeted for a burst operation, the BIU responds with a disconnect on the first data transfer.

All PCI memory cycles are preset to simple memory read and memory write cycles.

2.2.1.3 Master Access

The master sequencer state machine is controlled by giving address, guaranteed number of bytes to be transferred (plus minor additional informations) on a per-cycle basis from one of the three master backends (queues). If not owner of the PCI bus already, bus is requested.

The BIU releases ownership of the bus for several reasons:

- Number of bytes to transfer is zero

- Cache line size boundary is reached and the remaining number of bytes to be transferred is below cache line size
- Latency counter has expired

Servicing one of the backends is reported to the bus arbiter. The number of transferred bytes is reported to the backend on a per cycle base. The default transfer is burst transfer unless disabled by Disable Burst.

Supported commands are:

- Memory Write
- Memory Write And Invalidate
- Memory Read
- Memory Read Line
- Memory Read Multiple

Memory Write And Invalidate is used instead of Memory Write, if the guaranteed number of bytes to be transferred is higher than the cache line size. Memory Read Line is used instead of Memory Read, if the guaranteed number of bytes to be transferred is higher than eight. If the guaranteed number of bytes to be transferred is higher than one cache line size at least, Memory Read Multiple is used instead of Memory Read Line. The commands Memory Write And Invalidate, Memory Read Line, and Memory Read Multiple may be disabled individually by setting the appropriate bits in Access Control (Configuration Register File).

If a cycle is terminated by Target or Master Abort, this fact is reported to RTABORT or RMABORT (Status Register), interrupt IRQ Master and IRQ Status are set and the master sequencer state machine is locked. This situation must be solved by resetting the state machine using a master reset. A target retry is serviced by retrying the terminated cycle.

2.2.1.4 Parity Generation/Check

Parity is generated and checked on transmit and receive data paths with respect to the system logic. This condition applies both to the PCI Interface and to the internal RAM interface. Parity on the PCI bus is generated, checked, and reported according to the PCI specification. PCI parity generation and checking follows the PCI specification for even parity on 32-bit words. All other parity generation and checking performs even parity on bytes.

Parity Checking/Generating on PCI as Target

Read data parity is generated for read accesses to adapter resources in the system logic. Write data parity is checked for write accesses to adapter resources in the system logic. Address parity is checked for all address phases running on the bus. If a write data parity error is detected, Parity Error is set. Bus signal PERRn is asserted, if Parity Report Response Enable is set. If an address parity error is detected, Parity Error is set. Bus signal SERRn is asserted and Signaled Error is set, if SERRn Enable and Parity Report Response Enable are set.

Parity Checking/Generating on PCI as Master

Write data parity is generated for all write accesses to the system memory. Read data parity is checked for all read accesses from the system memory. Address parity is generated for all address phases generated on the bus. If a read data parity error is detected, Parity Error is set. Data Parity Error detected is set, if Parity Report Response Enable is set. If on a write access, PERRn is sampled as asserted, Parity Error is set. Data Parity Error detected is set, if enabled by Parity Report Response Enable. If Data Parity Error Detected is set, interrupt [<IRQ Master Error>](#) field in the Interrupt HW Error Source Register ([Table 75 p. 84](#)) is set. If Parity Error is set, interrupt IRQ Status is set (see also Status Register ([Table 30 p. 62](#))).

2.2.2 NAND Flash Controller

The NAND Flash Controller (NFC) provides interfaces to regular NAND Flash-based storage (for example, Samsung K9F5616Q0C, Toshiba TC58DVM82A1FT100, and more). It supports:

- Configurability to interface with different 8-bit NAND Flash devices
- Either 512 byte or 2 KB page sizes
- Configurability to work with different single-chip NAND Flash sizes from 128 Mb to 64 Gb
- Basic NAND Flash functions, including page program/read, block erase, random program/read, ID read, status read, reset, and lock commands
- ECC:
 - Hardware ECC (24 bits code Hamming Algorithm), 1-bit error correctable, 2-bit error detection
 - Reed Solomon from 1 to 4 bits
- Copy-Back Programming and Cache Programming for performance enhancement
- CEn pin de-assertion during Flash busy and idle to save power consumption
- Two chip enables for interface to two NAND Flash devices

2.2.2.1 Write Operations

For write operations, erase the block before the write. The bus master first fills up the internal write buffer through the Write Data Registers ([Table 113 p. 101](#)). software then programs the Address registers and Data Length Register ([Table 93 p. 94](#)) to setup the address and data transfer length. It then programs the Control Register to setup the write command and other control parameters and starts the write operation.

When the NAND Flash Controller receives the write command, it generates the necessary program command and address on the Flash bus, and writes the input data from the internal write buffer onto the Flash bus. Typically, the NAND Flash Controller should be allowed to finish programming the entire page. Refer to [Section , NAND Flash Access Examples, on page 37](#) for a NAND Flash write example.

If ECC check is enabled, the NAND Flash Controller must be allowed to program the entire page, and it will insert the computed ECC bytes at the end of the page.

2.2.2.2 Read Operations

For read operations, the software first programs the Address registers and Data Length Register ([Table 93 p. 94](#)) to setup the address and data transfer length. software then programs the Control Registers to setup the read command and other control parameters and then starts the read operation.

When the NAND Flash receives the read command, it generates the necessary program command and address on the Flash bus. When read data is available, the NAND Flash Controller toggles the NF_REn signal to read the data from the Flash and puts the data into the internal read buffer. Typically, the NAND Flash Controller should be allowed to finish reading the entire page.

The software waits for the interrupt and checks the `<nand_dev_bsy>` field in the Status Register ([Table 90 p. 93](#)) then reads the data through the Read Data Registers ([Table 112 p. 100](#)). Refer to [Section , NAND Flash Access Examples, on page 37](#) for a NAND Flash read example.

If ECC check is enabled, the NAND Flash Controller must be allowed to read the entire page, and it will run the ECC correction scheme at the end of the page.

Figure 5: NAND Flash Controller Block Diagram

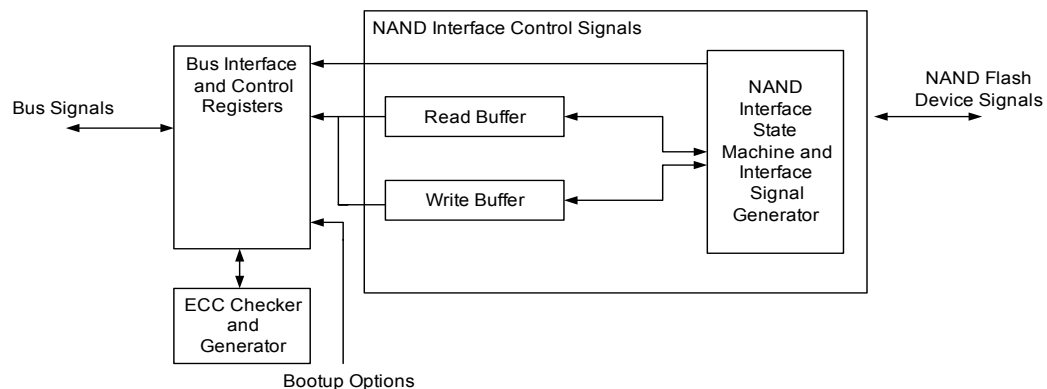
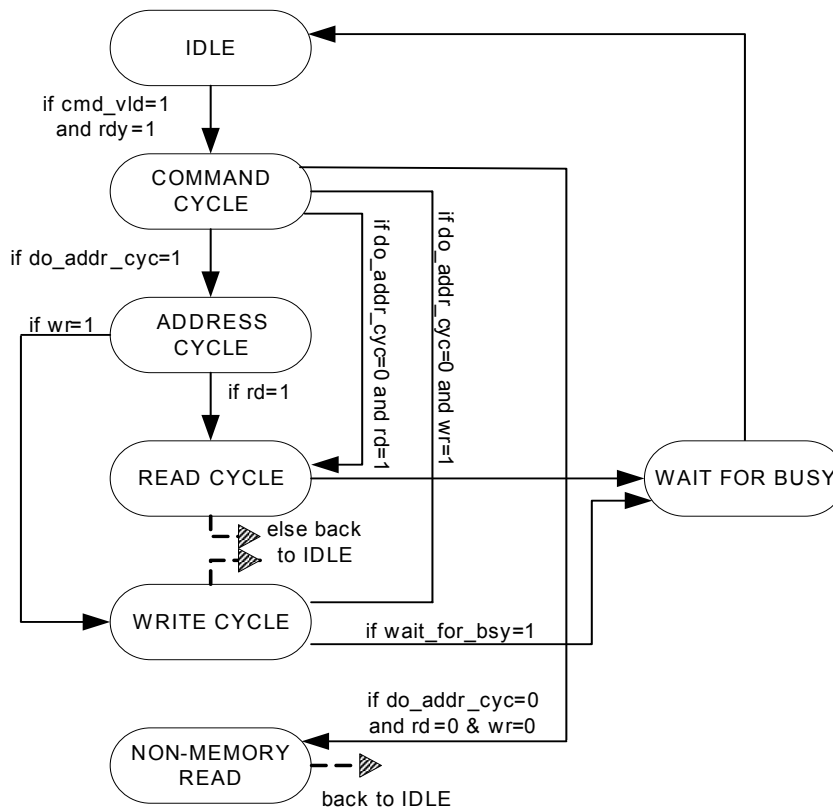


Figure 6: NAND Flash



System Data Flow

Data Storage

All NAND Flash access starts with a command. [Table 12](#) shows the command sets for Samsung Type 1 NAND Flash devices; [Table 13](#) shows the command sets for Samsung Type 2 NAND Flash devices.

Table 12: Samsung Type 1 NAND Flash Device Command Sets and Support

Flash Command	1st Cycle (hex)	2nd Cycle (hex)	NFC Support
Read 1	0x00 / 0x01		Yes
Read 2	0x50		Yes
Read ID	0x90		Yes
Reset	0xFF		Yes
Page Program	0x80	0x10	Yes
Copy_Back Program	0x00	0x8A	Yes
Lock	0x2A		Yes
Unlock	0x23	0x24	Yes
Lock-tight	0x2C		No
Read Block Lock Status	0x7A		Yes
Block Erase	0x60	0xD0	Yes
Read Status	0x70		Yes

Table 13: Samsung Type 2 NAND Flash Device Command Sets and Support

Flash Command	1st Cycle (hex)	2nd Cycle (hex)	NFC Support
Read	0x00	0x30	Yes
Read for Copy Back	0x00	0x35	Yes
Read ID	0x90		Yes
Reset	0xFF		Yes
Page Program	0x80	0x10	Yes
Cache Program	0x80	0x15	Yes
Copy_Back Program	0x85	0x10	Yes
Block Erase	0x60	0xD0	Yes
Random Data Input	0x85		Yes
Random Data Output	0x05	0xE0	Yes
Read Status	0x70		Yes

ECC

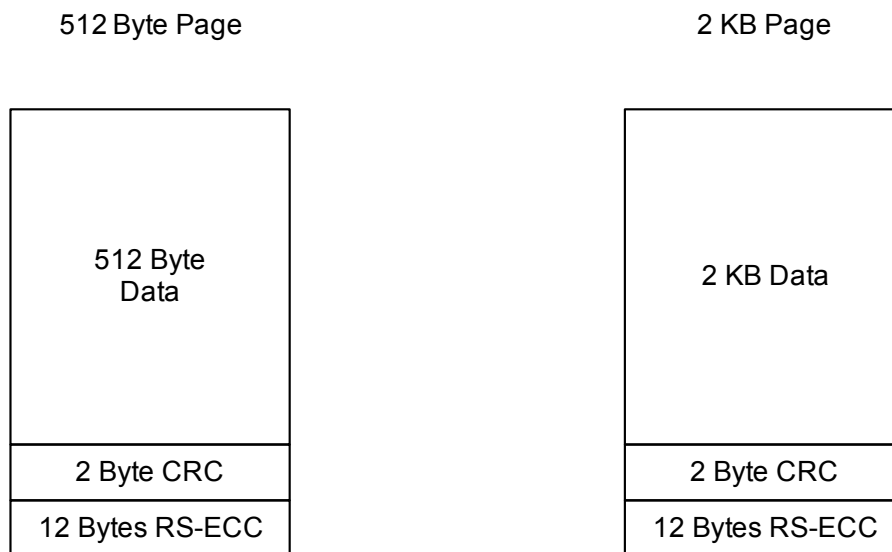
There are two types of ECC:

- **Hamming (1or 2-bit)**—Hardware is used. The whole page must be read to do ECC. When page read transfer is done, the **<result>** field in the Read ECC Result Register (Table 102 p. 97) should be read determine if an error has occurred. If **<result>=0x0**, no errors occurred. If **<result>=0x1**, a 1-bit error occurred, and the **<fail bit location>** field in the Read ECC Result Register (Table 102 p. 98) indicates the failed bit location. If **<result>=0x2**, an uncorrectable error occurred.
- **Reed-Solomon (4-bit)**, as shown in Figure 7—Hardware checks for error, and software corrects the error. The whole page must be read to do ECC. When page read transfer is done, **<RS ECC result>** field in the Read ECC Result Register (Table 102 p. 97)=0x0 indicates no errors occurred. If **<RS ECC result>=0x1**, software must read the RS ECC Decode Syndrome 0 and 1 Register (Table 106 p. 99) through RS ECC Decode Syndrome 6 and 7 Register (Table 109 p. 100) and run the 4-bit decoding algorithm to determine the error locations and error patterns.

If using Hamming Code, depending upon page size (512 byte page or 2 KB page), perform either 515-byte read (page size + 3 byte) or 2051-byte read (page size + 3 byte). If using Reed-Solomon Code, depending on page size (512 byte page or 2 KB page), perform either 526-byte read (page size + 2 byte CRC + 12 byte ECC) or 2062-byte read (page size + 2 byte CRC + 12 byte ECC). Note: 2 byte CRC is always inserted and checked by hardware. Wait for read operation to complete. If using Hamming Code, check the **<result>** field in the Read ECC Result Register (Table 102 p. 97). The **<fail bit location>** field in the Read ECC Result Register (Table 102 p. 98) are only applicable when Hamming Code is used. If using Reed-Solomon Code, check the **<RS ECC result>** field in the Read ECC Result Register (Table 102 p. 97).

The CRC can detect patterns that the RS-ECC cannot detect.

Figure 7: Reed-Solomon ECC Diagram



Concerns Regarding the Use of RDY Input from NAND Device

After each Program command, software can rely on the NAND RDY input to trigger an interrupt to signal the software to proceed to the next command. However, after each Block Erase command, software cannot rely on the NAND RDY input as a signal to proceed if the next command depends

on the completion of this particular Block Erase. This means if the software has issued a Block Erase command and received an Interrupt triggered by NAND RDY, the software can Program/Read pages other than the ones inside the block in question. To ensure the Block Erase has completed, software must periodically issue the Read Status command (a non-memory read) and see that the Status Ready bit is set in the return 8-bit status word.

NAND Flash Access Examples

Data Transfer

- **Slave interface only**—To read 250 bytes from column address 0x1abcd and row address 0x120 (data length and starting row address must not cross page boundary) of Samsung NAND Flash K9F2G08Q0M, the software must do the following:
 1. Set **<DMA active>** field in the DMA Control Register (Table 103 p. 98) = 0.
 2. Set Data Length Register (Table 93 p. 94) to decimal 250.
 3. Set Control Register 2 (Table 88 p. 92) to 0x130.
 4. Set Control Register (Table 87 p. 91) to 0xe4000000.
 5. Wait for **<cmd_done>** field in the Interrupt Register (Table 91 p. 93)= 1.
 6. Retrieve 250 bytes of data through Read Data Registers (Table 112 p. 100).
- **Slave interface only**—To write 250 bytes to column address 0x1abcd and row address 0x120 (data length and starting row address must not cross page boundary) of Samsung NAND Flash K9F2G08Q0M, the software must do the following:
 1. Set **<DMA active>** field in the DMA Control Register (Table 103 p. 98) = 0.
 2. Set Data Length Register (Table 93 p. 94) to decimal 250.
 3. Set Address Register (Table 94 p. 94) to 0x120 and Address Register 2 (Table 95 p. 95) to 0x1abcd.
 4. Set Control Register 2 (Table 88 p. 92) to 0x20000110.
 5. Set Control Register (Table 87 p. 91) to 0xe2000080.
 6. Wait for **<cmd_done>** field in the Interrupt Register (Table 91 p. 93)= 1.
- **Master interface only**—To read 250 bytes from column address 0x1abcd and row address 0x120 (data length and starting row address must not cross page boundary) of Samsung NAND Flash K9F2G08Q0M, the software must do the following:
 1. Set **<DMA active>** field in the DMA Control Register (Table 103 p. 98) = 1 and **<DMA op>** field in the DMA Control Register (Table 103 p. 98) = 0.
 2. Set DMA Address Register 0 (Table 104 p. 98) to desired address.
 3. Set Data Length Register (Table 93 p. 94) to decimal 250.
 4. Set Control Register 2 (Table 88 p. 92) to 0x130.
 5. Set Control Register (Table 87 p. 91) to 0xe4000000.
 6. Wait for **<dma_done>** field in the Interrupt Register (Table 91 p. 93).
 7. Read data is completely transferred to set DMA Address.
- **Master interface only**—To write 250 bytes to column address 0x1abcd and row address 0x120 (data length and starting row address must not cross page boundary) of Samsung NAND Flash K9F2G08Q0M, the software must do the following:
 1. Set **<DMA active>** field in the DMA Control Register (Table 103 p. 98) = 1 and **<DMA op>** field in the DMA Control Register (Table 103 p. 98) = 1.
 1. Set DMA Address Register 0 (Table 104 p. 98) to desired address
 2. Set Data Length Register (Table 93 p. 94) to decimal 250.
 3. Set Address Register (Table 94 p. 94) to 0x120 and Address Register 2 (Table 95 p. 95) to 0x1abcd.
 4. Set Control Register 2 (Table 88 p. 92) to 0x20000110.
 5. Set Control Register (Table 87 p. 91) to 0xe2000080.
 6. Wait for **<cmd_done>** field in the Interrupt Register (Table 91 p. 93).



Note

Software waits for `<dma_done>` field in the Interrupt Register (Table 91 p. 93) for read operation because DMA is the last step of read operation and waits for `<cmd_done>` field in the Interrupt Register (Table 91 p. 93) for write operation because Command execution is the last step of write operation.

Read Status Command Each Flash device contains an 8-bit Status Register that can be read to determine whether a program or erase operation completed successfully. To issue a read status command, first set the `<cmd>` field in the Control Register (Table 87 p. 92) to 0x70 (hex) and the `<num_nonmem_rd[3:1]>` field in the Control Register (Table 87 p. 91) to 0x1. Wait for the `<cmd_done>` field in the Interrupt Register (Table 91 p. 93), then read the Non-Memory Read Data Register (Table 99 p. 97) for the status.

Read ID Command Use this command to read the product identification code. Devices have either a 2-byte or 4-byte ID. Follow the same flow as in the Read Status Command example, but set `<cmd>` field in the Control Register (Table 87 p. 92) to 0x90 and the `<num_nonmem_rd[3:1]>` field in the Control Register (Table 87 p. 91) to obtain either 2-byte or 4-byte ID.

Reset Command The Flash device can be reset with the reset command. When the device is in the Busy state during read/program/erase modes, the reset operation aborts the operation.

Lock/Unlock Command Some Flash devices provide Lock/Unlock commands to allow the software to control which block is locked or unlocked. The lock command is typically applied to the entire Flash memory, and the unlock command allows a specific block or group of consecutive blocks to be unlocked.

Block Erase Command An erase operation sets all bits in the addressed block to 1s. To issue a block erase command, first set the targeted block location in the corresponding Address Registers, then set the `<cmd2>` field in the Control Register 2 (Table 88 p. 92) to 0x1d0, then the `<cmd>` field in the Control Register (Table 87 p. 92) to 0x60 and the number of address bits to device specific values and the `<cmd_vld>` field in the Control Register (Table 87 p. 91) to 1. Wait for device not busy, then issue a read status command to check the status of the block erase command just issued.

2.2.3

SDIO Host Controller

The SD host controller is a hardware block and acts as a host of the SD bus to transfer data between SD memory or SDIO cards and internal buffers and the internal bus master.

One side of this block interfaces with a standard SD host bus. The other side internally interfaces with two programmable mode interfaces:

- DMA interface: In this mode, this block acts as an internal master which accesses the SDRAM using the DMA engine.
- CPU interface: The CPU accesses through the internal bus. This interface is most likely used for debugging purposes.

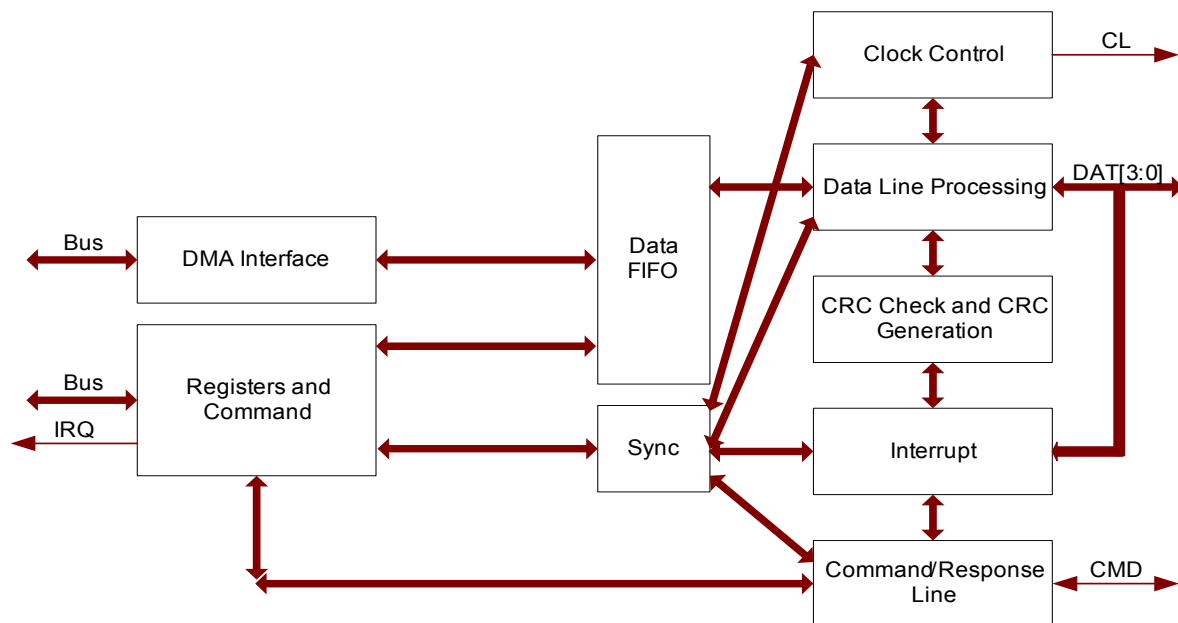
Figure 8 shows the SDIO host controller block diagram.

2.2.3.1 Features

- 1-bit/4-bit SDmem and SDIO
- High speed mode supported for SD at 48 MHz
- Supports interrupts for information exchange between host and cards
- Supports read wait control in SDIO cards
- Programmable internal interfaces
- Hardware generation/checking of CRC on all command and data transaction on the card bus
- True dual-port data FIFO (128x32) used as internal buffer. One side of the FIFO interfaces with the host bus. The other side is programmable to interface with a DMA engine or directly from the CPU.
- Suspend/resume in SDIO cards
- Card insertion/removal detection for SD cards

Figure 8 shows the SDIO host block diagram.

Figure 8: SDIO Host Block Diagram



2.2.3.2 SD Bus Protocol Description

Communication over the SD bus is based on commands and data bit streams that are initiated by a start bit and terminated by a stop bit.

- Command: A command is a token that starts an operation. It is sent from the host to the card(s) and is transferred serially on the CMD line (1 bit).
- Command Response: A command response is a token that is sent from an addressed card to the host as an answer to a previously received host command. It is transferred serially on the CMD line since the CMD line is a bidirectional signal.
- Data: There are four data lines. Data can be transferred from the card to the host or vice versa. Data is transferred via Data line, and they are bidirectional signals. In 1-bit mode, SD_DATA[0] is used, and the other is in Z-state.

Figure 9, Figure 10, and Figure 11 show basic operations of the SD cards.

Figure 9: “No Response” and “No Data” Operation

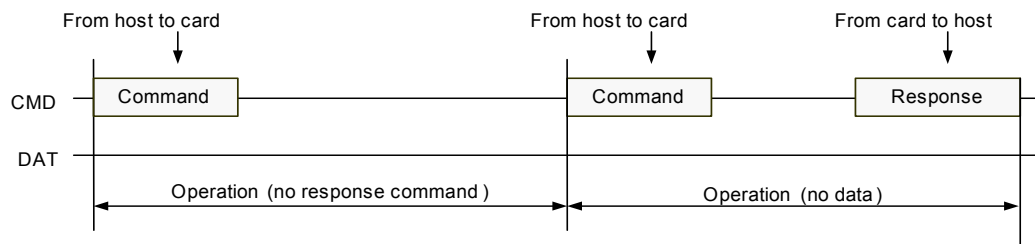


Figure 10: Multiple Block Read Operation

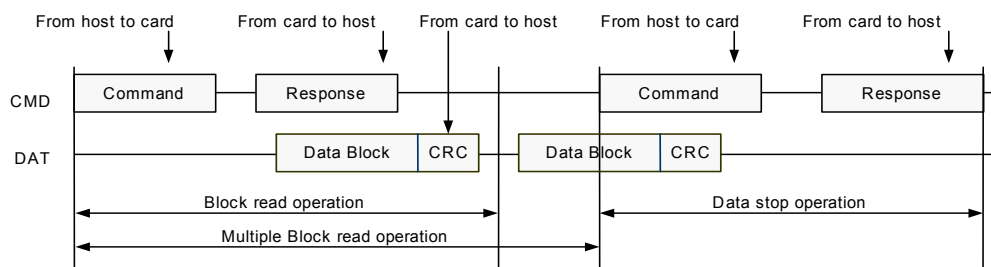
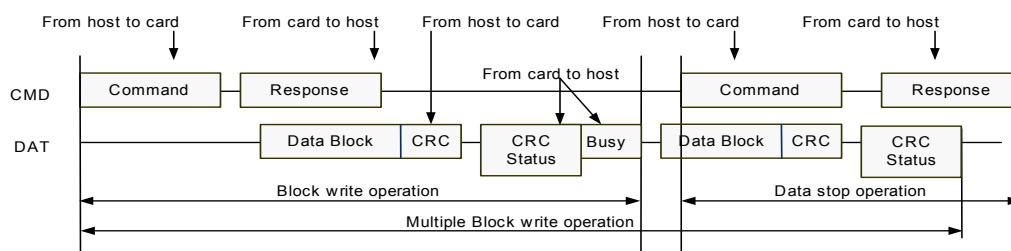


Figure 11: Multiple Block Write with Card Busy Operation

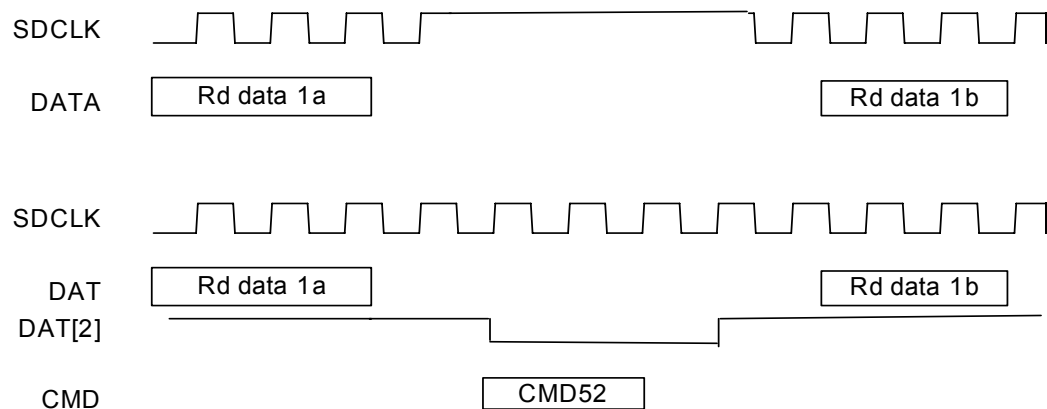


2.2.3.3 Special Bus Transactions

Read Wait Command

The host usually stops the clock to stop the read data output from the card whenever the host cannot accept any more data. During the clock stop, the host capabilities are limited as it cannot issue commands during read. A Read Wait command allows the host to stop the read data while the clock is still on. A Read Wait command is issued after the data block end.

Figure 12: Read Wait Controlled by Stopping Clock



Packet Format

Figure 13, Figure 14, Figure 15, and Figure 16 show the formats of commands from the host and responses from cards and data.

Figure 13: Command Token Format

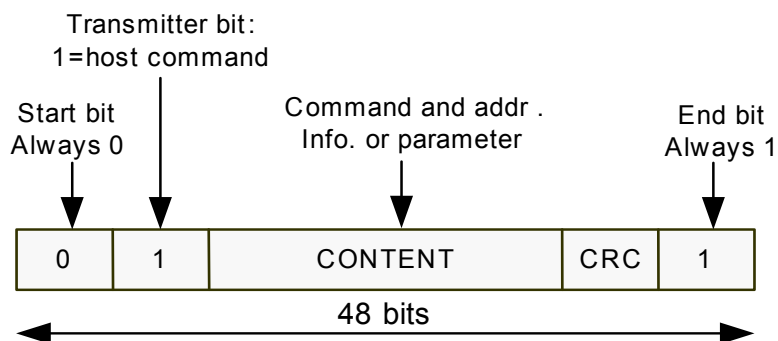


Figure 14: Response Token Format

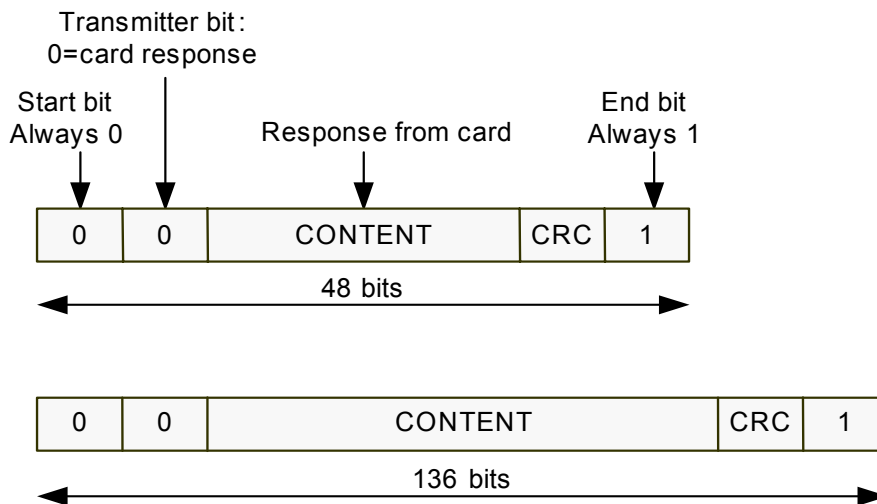


Figure 15: Data Packet Format, Standard Bus (Only DAT0 Used)

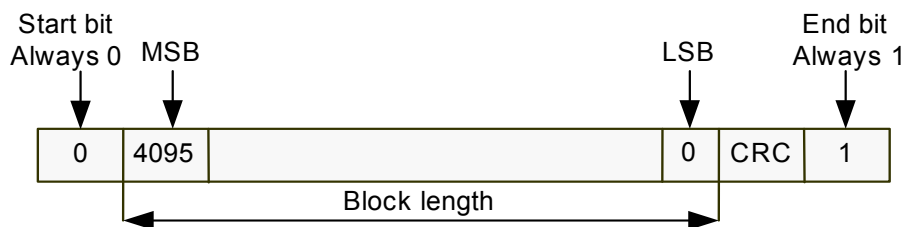
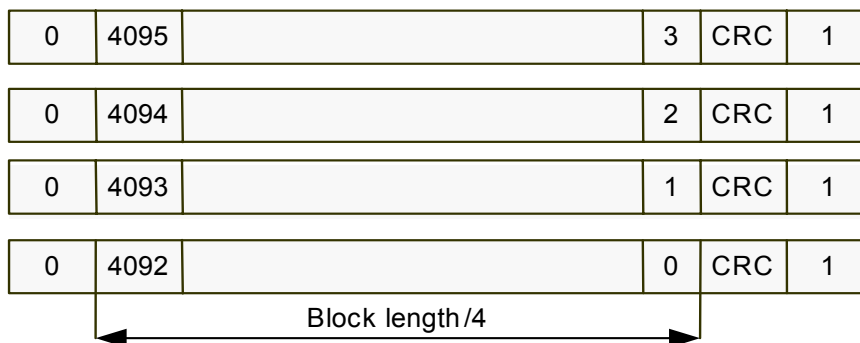


Figure 16: Data Packet Format, Wide Bus (All Four Data Lines Used)



Sequences of Host and Card Interaction

SD cards are connected to the host with a dedicated interface, such as its own CLK, CMD, or DATA lines.

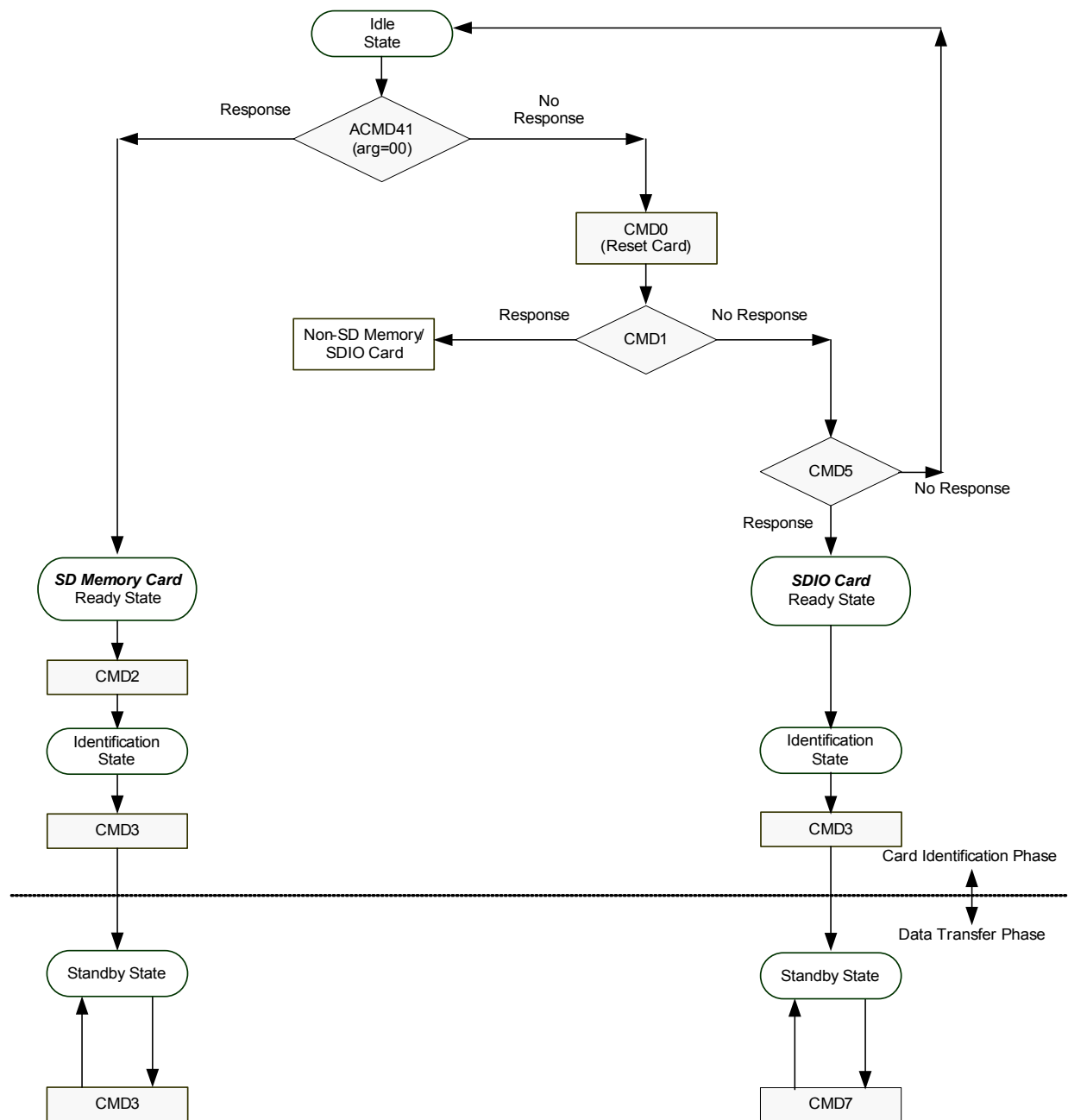
The host and SD cards go through two phases after power on reset, software reset, or if a new card is plugged in:

- Card identification phase: The host looks for new cards on the bus. While in this phase, the host resets all the cards that are in card identification mode. Any card already identified will not be reset. Then the host sends the command to validate operation voltage range, identifies cards and asks them to publish the Relative Card Address (RCA). This operation is done to each card separately on its own CMD line in the case of SD memory,. All data communication in the Card Identification phase uses the CMD line only.
- Data transfer phase: The host enters this phase after identifying all the cards on the bus. In this phase, the host is ready to transfer data.

After the host driver sets up the host controller, it starts the transfer by writing to the Command Register, which is written last.

The host initialization flow chart is shown in [Figure 17](#).

Figure 17: Host Initialization Flow Chart



2.2.3.4 Card Detection

The 88ALP01 design supports card detection (insertion/removal) based on the card detect switch level on the SD socket. This card detection features can be accessed through the Normal Interrupt Status Enable bits. If this feature is enabled, an interrupt is generated when a logic change is detected on the card detect switch input. This logic change is debounced before generating an interrupt.

2.2.4 CMOS Camera Interface Controller

2.2.4.1 Features

- Still images up to 2.0 Megapixels
- Interfaces:
 - Parallel input: interface support for 8 bits
 - Supports embedded hsync/vsync format (BT-656)
- Capture modes:
 - RGB 4:4:4
 - RGB 5:5:5
 - RGB 5:6:5
 - YCbCr 4:2:2
 - Raw capture modes: Bayer
- Output formats:
 - YCbCr 4:2:2 (planar and packed)
 - Raw Bayer packed: 8-bit/pix (4-pix in 32-bit)
 - RGB 16-bit/pix (4:4:4, 5:5:5, 5:6:5)
 - YCbCr 4:2:0 (planar)
- Frame buffers in system memory with up to three ping-pong buffers
- Interrupts (interrupts are optional, system can work with all interrupts masked out)
 - Frame-start
 - Frame-end
 - FIFO overrun
- 2x downscale on YCbCr and RGB output formats

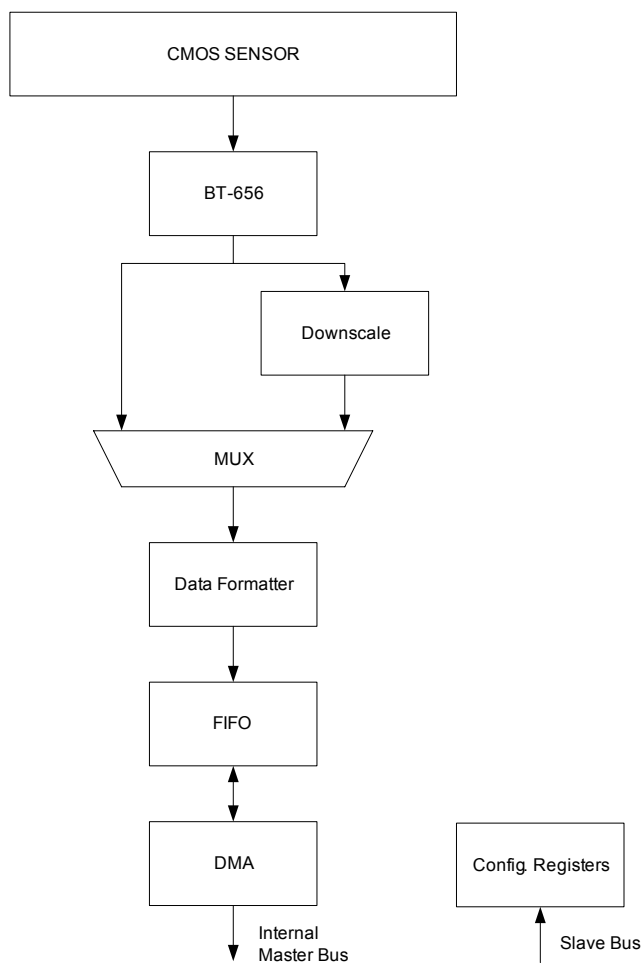
2.2.4.2 I/O Signals

The CCIC chip-level I/O signals are described in [Table 14](#).

Table 14: CCIC Chip-Level I/O Signal Descriptions (2.5V or 3.3V)

Pin Name	Pin Type	I/O Type	Definition
HSYNC	I/O	CMOS 2.5V or 3.3V	Horizontal Sync driven by external CMOS sensor
VSYNC	I/O	CMOS 2.5V or 3.3V	Vertical Sync driven by external CMOS sensor
PIXDATA[7:0]	I	CMOS 2.5V or 3.3V	Pixel Data Synchronous to PIXCLK.
PIXCLK	I	CMOS 2.5V or 3.3V	Pixel Clock
PIXMCLK	O	CMOS 2.5V or 3.3V	Pixel Master Clock
SENSOR_CTL0	O	CMOS 2.5V or 3.3V	Sensor Control 0
SENSOR_CTL1	O	CMOS 2.5V or 3.3V	Sensor Control 1
TWSI_SCLK	O	CMOS 2.5V or 3.3V	TWSI Serial Clock
TWSI_SDATA	I/O	Open Drain	TWSI Serial Data

Figure 18: CCIC Block Diagram



2.2.4.3 Interface Modes

Table 15: Supported Interface Modes

Data Bus Width	hsync and vsync	Descriptions
8-bit	Yes	External CMOS Sensor drives PIXCLK, HSYNC, VSYNC, and PIXDATA[7:0]
8-bit	No	External CMOS Sensor drives PIXCLK and PIXDATA[7:0]. Start-of-Active-Video (SAV) and End-of-Active-Video (EAV) are encoded in the data stream.

2.2.4.4 Input/Output Matrix

Table 16 shows the color I/O matrix.

Table 16: Color I/O Matrix

Input	Output	Note
RGB 5:6:5	RGB 5:6:5	RGB Endianness is programmable.
YCbCr 4:2:2	YCbCr 4:2:2 YCbCr 4:2:0	YCbCr 4:2:2 output can be packed or planarized.
RGB 4:4:4	ARGB 4:4:4:4	Alpha value and RGB Endianness are programmable.
RGB 5:5:5	ARGB 1:5:5:5	Alpha value and RGB Endianness are programmable.
Raw Bayer 8-bit	Raw Bayer	Raw Bayer pixels are packed into 32-bit.

2.2.4.5 Video Timing Reference Codes (SAV and EAV)

This section is derived from the ITU-R BT.656-R specification, section 2.4.

There are two timing reference signals:

- SAV, which occurs at the beginning of each video data block
- EAV, which occurs at the end of each video data block

Each timing reference signal consists of a four-word sequence in the following format: FF 00 00 XY. (Values are expressed in hexadecimal notation. FF 00 values are reserved for use in the timing reference signals.) The first three words are a fixed preamble. The fourth word contains information defining field two identification, the state of field blanking, and the state of line blanking. The bit assignments within the timing reference signal are shown in Table 17.

Table 17: Video Timing Reference Codes

Data Bit Number	1st Word (FF)	2nd Word (00)	3rd Word (00)	4th Word (XY)
7	1	0	0	1
6	1	0	0	F
5	1	0	0	V
4	1	0	0	H
3	1	0	0	P3
2	1	0	0	P2
1	1	0	0	P1
0	1	0	0	P0

Bits P0, P1, P2, and P3, have states dependent on the states of the bits F, V, and H, as shown in Table 18. At the receiver, this arrangement permits correction of 1-bit errors and detection of 2-bit errors.

Table 18: Bits States

F	V	H	P3	P2	P1	P0	Descriptions
0	0	0	0	0	0	0	SAV: Field 1 Active Video
0	0	1	1	1	0	1	EAV: Field 1 Active Video
0	1	0	1	0	1	1	SAV: Field 1 Blanking

Table 18: Bits States (Continued)

F	V	H	P3	P2	P1	P0	Descriptions
0	1	1	0	1	1	0	EAV: Field 1 Blanking
1	0	0	0	1	1	1	SAV: Field 2 Active Video
1	0	1	1	0	1	0	EAV: Field 2 Active Video
1	1	0	1	1	0	0	SAV: Field 2 Blanking
1	1	1	0	0	0	1	EAV: Field 2 Blanking

The CCIC starts capturing data when it detects either one of the following sequences:

1. FF 00 00 80 (SAV: Field 1 Active Video)
2. FF 00 00 C7 (SAV: Field 2 Active Video)

It stops capturing data when it detects either one of the following sequences:

1. FF 00 00 9D (EAV: Field 1 Active Video)
2. FF 00 00 DA (EAV: Field 2 Active Video)

2.2.4.6

RGB Input Data Formats

The following tables provide the RGB and YCbCr input data formats:

- [Table 19](#) for 8-bit RGB 5:6:5
- [Table 20](#) for 8-bit YCbCr 4:2:2

Table 19: 8-bit RGB 5:6:5 Input Data Format

Pixdata Bit Number	RGB 5:6:5 Byte Sequence					
7 (MSB)	G0[2]	B0[4]	G0[2]	B1[4]	G2[2]	B2[4]
6	G0[1]	B0[3]	G0[1]	B1[3]	G2[1]	B2[3]
5	G0[0]	B0[2]	G0[0]	B1[2]	G2[0]	B2[2]
4	R0[4]	B0[1]	R1[4]	B1[1]	R2[4]	B2[1]
3	R0[3]	B0[0]	R1[3]	B1[0]	R2[3]	B2[0]
2	R0[2]	G0[5]	R1[2]	G1[5]	R2[2]	G2[5]
1	R0[1]	G0[4]	R1[1]	G1[4]	R2[1]	G2[4]
0 (LSB)	R0[0]	G0[3]	R1[0]	G1[3]	R2[0]	G2[3]
Byte Sequence	0	1	2	3	4	5
Pixel	0	1		2		

Table 20: 8-bit YCbCr 4:2:2 Input Data Format

Pixdata Bit Number	YCbCr 4:2:2 Byte Sequence					
7 (MSB)	Cb0[7]	Y0[7]	Cr0[7]	Y1[7]	Cb1[7]	Y2[7]
6	Cb0[6]	Y0[6]	Cr0[6]	Y1[6]	Cb1[6]	Y2[6]

Table 20: 8-bit YCbCr 4:2:2 Input Data Format (Continued)

Pixdata Bit Number	YCbCr 4:2:2 Byte Sequence					
5	Cb0[5]	Y0[5]	Cr0[5]	Y1[5]	Cb1[5]	Y2[5]
4	Cb0[4]	Y0[4]	Cr0[4]	Y1[4]	Cb1[4]	Y2[4]
3	Cb0[3]	Y0[3]	Cr0[3]	Y1[3]	Cb1[3]	Y2[3]
2	Cb0[2]	Y0[2]	Cr0[2]	Y1[2]	Cb1[2]	Y2[2]
1	Cb0[1]	Y0[1]	Cr0[1]	Y1[1]	Cb1[1]	Y2[1]
0 (LSB)	Cb0[0]	Y0[0]	Cr0[0]	Y1[0]	Cb1[0]	Y2[0]
Byte Sequence	0	1	2	3	4	5
Y Pixel	0		1		2	
Cb, Cr Pixel	0 and 1				2 and 3	

2.2.4.7

CCIC Recommended Programming Sequence

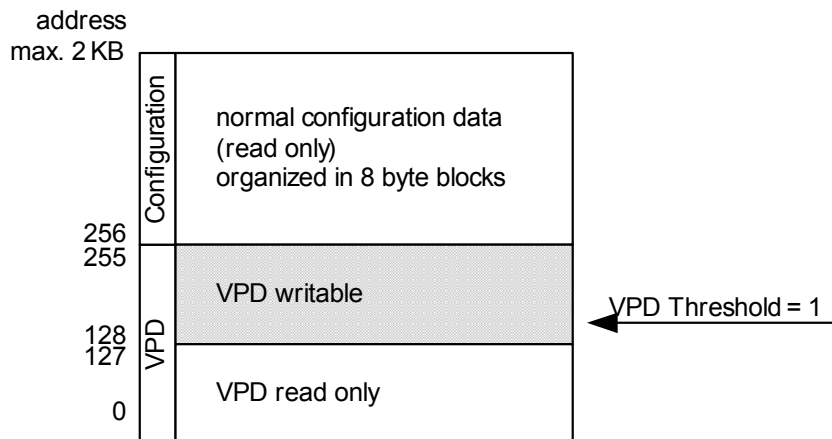
1. Configure external CMOS sensor resume and power down modes:
 - Configure SENSOR_CTL0 pin to 0 to put external CMOS sensor in reset mode.
 - Configure SENSOR_CTL1 pin to 1 to put external CMOS sensor in power-down mode.
 - Program the General Purpose (GPR) Register (Table 180 p. 137) to 0x32.
2. Power up external CMOS sensor:
 - Program Global Register 0x3058 bit [3] = 1.
 - Program Global Register 0x315C bit [19] and bit [3] to 1.
 - Allow some time for voltage to ramp up.
3. Configure CCIC in normal mode by programming the <PWRDNEN> field in the Control 1 Register (Table 176 p. 135) = 0.
4. Release external CMOS sensor reset and power down.
 - Program General Purpose (GPR) Register (Table 180 p. 137) to 0x31.
5. Configure external CMOS sensor input clock by programming the Clock Control Register (Table 177 p. 136).
6. Configure TWSI Control 0 Register (Table 181 p. 138).
7. Configure external CMOS sensor registers through TWSI Control 1 Register (Table 182 p. 139). Either polling mode or interrupt mode can be used.
8. Configure CCIC (video buffer addresses, video modes, etc.), while keeping <EN> field in the Control 0 Register (Table 175 p. 135) = 0.
9. Enable CCIC DMA.
 - Program <EN> = 1.

2.2.5

VPD Serial EEPROM

The serial EEPROM is an external memory device for application-dependent configuration data and Vital Product Data (VPD). Its address space is divided into two parts as shown in Figure 19.

Figure 19: Internal Structure of Serial EEPROM



The VPD data is located within the lower address region (0 to 255). This data contains the read only and writable section of VPD separated by VPD Threshold. The normal configuration data are stored in higher EEPROM addresses. Following RSTn, if enabled, the 88ALP01 uses its internal serial EEPROM Loader to load these data automatically.

The VPD serial EEPROM is read from and written to via the VPD TWSI bus at TWSI address 0b101000.

A serial EEPROM such as Atmel's AT24C02 or equivalent may be used.

For manufacturing programming of the read only part of the serial EEPROM, testmode (En Config Write) must be set. Then the whole serial EEPROM is writable. Programming of the serial EEPROM is managed with ASIC internal registers, VPD Address Register (Table 58 p. 75) and VPD Data Registers (Table 59 p. 76).

After the next power cycle, the read only areas within the serial EEPROM are write protected again.

2.2.5.1 VPD Serial EEPROM Loader

The Serial EEPROM Loader accesses the external serial EEPROM for configuration data.

- The serial EEPROM Loader is active after RSTn if enabled.
- Startup data is loaded out of the serial EEPROM into Configuration and Control Register File.
- Serial EEPROM load is for loading startup data into the Configuration and Control Register File (where needed):
 - The loader is capable of accessing potentially all registers in the Control Register File space.
 - The register address and data are stored in 8-byte entries in the Serial EEPROM.
 - The 8-byte entries are located on 8-byte boundaries up from address 256 of the serial EEPROM in increasing order. Each entry is marked with a key byte (0x55).

Table 21: Data Format of First 8 byte Block within Serial EEPROM

TWSI Access Cycle Number	Serial EEPROM Address	Content
2	0x107	Data<3>
	0x106	Data<2>
	0x105	Data<1>
	0x104	Data<0>
1	0x103	Address/upper
	0x102	Bit [7:2]: Address/lower Bit [1:0]: Function number
	0x101	Bit [7:4]: Opcode Bit [3:0]: CBEn[3:0]
	0x100	Key = 0x55

- The ASIC internal registers may be written with dword, word, or byte accesses.
- The loader, if started, reads subsequent entries starting with the initial value of the serial EEPROM address counter as long as a valid key is found.
- Loading is started right after reset or by setting the flag to start the Serial EEPROM Loader.
- The Flag in the serial VPD Serial EEPROM Loader Control Register (Table 60 p. 76) is intended for testing purposes only. Reloading the Configuration Register File using this command is not recommended.
- Accesses to any resource of the 88ALP01 are terminated by Target Retry Cycles while loading.
- The data transferred after RSTn in this way is limited to fulfilling the requirements of the PCI bus. T_{rhfa} RSTn High to First configuration Access is limited to 2^{25} clock cycles. PCI clock 66 MHz: $T_{rhfa} = 0.5 \text{ s} \rightarrow \text{max. } 5.6 \text{ KB}$
PCI clock 33 MHz: $T_{rhfa} = 1 \text{ s} \rightarrow \text{max } 2.8 \text{ KB}$
- This reading via TWSI bus may be deactivated during RSTn.
- Transformation of the serial EEPROM data (8 bytes) into multiple byte/dword memory read accesses from the bus.
 - The 8-byte serial EEPROM data is loaded over the TWSI-Bus using multiple byte/dword memory read accesses. For example, one 64-bit internal register write requires two 32-bit bus reads of the EEPROM contents through the bus.

2.2.5.2 VPD Two-Wire Serial Interface

The VPD TWSI is controlled either by software with the Interface Register or by hardware with the VPD TWSI (HW) Control Register (Table 82 p. 88) and the VPD TWSI (HW) Data Register (Table 83 p. 89). If hardware-controlled TWSI accesses are used, the Interface Register must be set to inactive values (Clock = 1, Direction = 0, Data = 0).

The hardware controlled interface can be controlled in different ways. The size of the target device of the VPD TWSI access (and implicitly the number of address bytes/bits to be used) and its devsel byte, together with the address, must be written to the VPD TWSI (HW) Control Register (Table 82 p. 88). If the TWSI Burst bit is set, the TWSI runs four byte bursts in page mode, assuming pages of eight bytes. Invalid or erroneous HW controlled TWSI accesses that are not completed, can be stopped by writing a one to TWSI Stop. On completion of a hardware controlled TWSI access an interrupt IRQ TWSI Ready is asserted.

The VPD TWSI connects to an EEPROM that utilizes VPD as suggested by PCI Rev. 2.3. VPD is stored in a serial EEPROM and may be accessed through the VPD Address Register (Table 58 p. 75) and VPD Data Registers (Table 59 p. 76). These registers are mapped writable both into configuration and I/O address space.

2.2.6 Device Reset

The 88ALP01 supports PCI power management. When in Sleep mode, PCI reset may be active but parts of the device observe SD card assertion for wake up event.

The 88ALP01 is completely reset by the “power on reset”. The PCI reset is applied to all logics except the PCI sleep control (PME) and wake up parts.

2.2.7 Reset Configuration

The 88ALP01 uses the following pins as configuration inputs to set parameters following a power-on reset. The definition of these pins change immediately after power-on reset to their normal function.



Note

To set a configuration bit to 0, attach a 10 kΩ resistor from the appropriate pin to ground. No external circuitry is required to set a configuration bit to 1.

Table 22: 88ALP01 Configuration Pins

Configuration Bits	88ALP01 Pin	Configuration Function
CON[7]	VPD_CLK	66 MHz PCI capability 0 = Capability is not present 1 = 66 MHz PCI capability present
CON[6:2]	Reserved	Reserved for future use
CON[1]	NF_DATA[1]	PLL Bypass Disable 0 = PLL bypass enabled 1 = PLL bypass disabled
CON[0]	NF_DATA[0]	EEPROM Load Disable 0 = Load enabled 1 = Load disabled

2.2.8 Clock Generation/Distribution

There are two main clock domains in the 88ALP01 (not counting divided down clocks in sub modules).

- The PCI section driven with PCI CLK (0 to 66 MHz)
- The core logic is driven with core clock generated by on chip PLL from 24 MHz external reference.

The PCI Clock is driven from PCI and runs all state machines and registers which have to be synchronous with the PCI Clock, that is, the Master and Target state machines and the PCI Configuration Registers. This group also includes the external VPD TWSI.

2.2.9 PME on Wake up event

The 88ALP01 can be configured to assert the PMEn signal under the following conditions:

- PCI bus in sleep mode with VDDO still applied (D3-hot)
- SD card is inserted, removed or SD card asserts an interrupt

2.2.9.1 Power Management Support

The 88ALP01 supports power management as defined in the PCI Bus Power Management Interface Specification v1.1. The PCI power management interface includes the capabilities data structure and power management register block definitions.

When the system is in a power-down mode, PCI bus power is on, the PCI clock may be slowed down or stopped, and the wake-up output pin may drive the PME pin on the PCI bus to cause the hardware on the system device to put the computer into the working (D0) mode.

The device only supports SD card insertion wake-up event.

2.2.9.2 PCI Device Power States

The 88ALP01 function 1 supports all of the following PCI device power states, as defined in [Table 23](#). Function 0 and function 2 only support D0 and D3_{hot}.

Table 23: Device Power Status

Device State	VDDO	PCI Clock	Bus PCI Activity	Function Support
D0 (Fully On) ¹	On	Free running	Any PCI transaction, function, interrupt, or PME event	Function 0, 1, and 2
D1	On	Free running	PME event, config cycles	Function 1
D2	On	Free running or stopped	PME event, config cycles	Function 1
D3 _{hot}	On	Free running or stopped	PME event, config cycles	Function 0, 1, and 2

1. In the D0 state, all hardware on the 88ALP01 is fully functional.

In the D1, D2, and D3_{hot} states, the PCI bus activities are restricted to config cycles and PME events. If a wake-up event occurs, the PME signal is raised under hardware control. The 88ALP01 does not require a PCI clock to generate a PME.

2.2.9.3 Wake-Up Sequence

The system software enables the PME pin by setting the [<PME En>](#) field in the Power Management Control/Status Register ([Table 53 p. 73](#)) to 1. When a wake-up event is detected, the 88ALP01 sets the PME_STATUS bit in the PMCSR register (PCI configuration registers, [<PME Status>](#) field in the Power Management Control/Status Register ([Table 53 p. 73](#))). Setting this bit causes the PME signal to be asserted. Assertion of the PME signal causes external hardware to wake up the host system CPU. The host system software then reads the PMCSR register of every PCI device in the system to determine which device asserted the PME signal.

When the host software determines that the signal was caused by the 88ALP01, it writes to the 88ALP01 PMCSR to put the device into power state D0. This software then writes a ONE to the PME_STATUS bit to clear the bit and turn off the PME signal, and it calls the device's software driver to tell that the device is now in state D0. The system software can clear the PME_STATUS bit either before, after, or at the same time as the 88ALP01 is put back into the D0 state.

2.2.10 Clock Run (CLK_RUNn)

The CLK_RUNn pin conforms with the Clock Run specification as described in the PCI Mobile Design Guide Revision 1.1. The CLK_RUNn pin is used for stopping and starting the PCI clock. The following is a list of conditions that trigger a request (via CLK_RUNn) for the clock to be restarted. The 88ALP01 attempts to maintain the PCI clock under the following conditions even if the central resource tries to stop or slow it down.

- The 88ALP01 has active PCI transactions.
- The device has received fewer than 20 PCI clocks after hardware reset is deasserted.
- Configuration from the Serial EEPROM is being loaded.
- Any of the three bus master (DMA) units (from all 3 functions) are not idle.

2.2.11 Power on Reset Delay

Upon power up, the 88ALP01 has an internal POR counter to extend the POR for more than 21.67 ms based on a 24 MHz reference clock. It is triggered by voltage crossing a pre-determined threshold and is intended to cause the 88ALP01 to wait for power to stabilize before releasing the reset at power up. The counter is counting on input reference clock; therefore, an increase in reference clock speed would decrease this POR delay.

3 Register Description

3.1 Registers Introduction

The registers included in this section are:

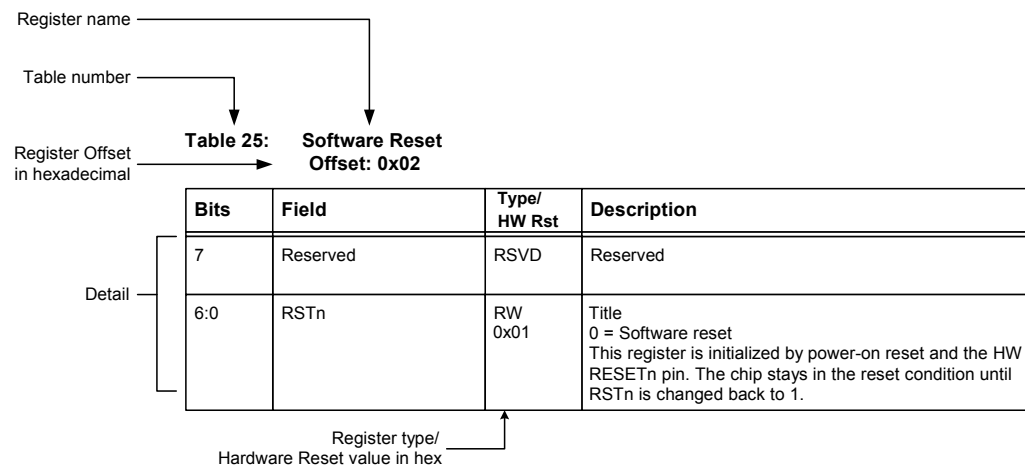
- [PCI Configuration Register File](#)
- [Global Control Registers](#)
- [NAND Flash Unit](#)
- [SDIO Host Controller Registers](#)
- [CMOS Camera Interface Controller](#)

Register maps are provided at the start of each register section.

3.1.1 Register Conventions

[Figure 20](#) shows how to read the register tables in the register map.

Figure 20: Register Conventions



The registers in the 88ALP01 are made up of one or more fields. The way in which each of these fields operate is defined by the field's Type. The function of each Type is described in [Table 24](#).

Table 24: Register Type Definitions

Type	Description
EXEC	Execution of this command if appropriate bit is set
ROC	Read on clear
RSVD	Reserved for future use. All reserved bits are read as zero unless otherwise noted.
RO	Read only.
RW	Read and Write.
RW1C	

Table 24: Register Type Definitions (Continued)

Type	Description
SH	Special Handling as described
WO	Write only. Reads to this type of register field return undefined data.
W1AC	

The following conventions are used:

- Commands (single bit) in Control Registers:
 - Commands are executed, if appropriate bit is set
 - Read value as defined.
- Exclusive commands (xxx Start/Stop, xxx On/Off):
 - Commands are executed, if appropriate bit is set to 1.
 - Setting both commands to 1, has no effect.
 - Status is readable: 0x1 or 0x2.
- Reset Value:
 - <blank> = fixed value or value directly from input pin
 - <value> = reset to <value> only by Power on and **HW Reset**
 - <value> (HW) = reset to <value> only by Power on and **HW Reset**
 - <value> (SW) = reset to <value> by Power on, **HW Reset** and **SW Reset**

3.2 PCI Configuration Register File

Providing configuration information and supporting access to configuration information is mandatory for any PCI adapter. This data is available in the PCI Configuration Register File. The Vital Product Data (VPD) implemented in the 88ALP01 is an optional PCI extension attached to the Configuration Register File. The implementation follows an Engineering Change Request (ECR) according to the PCI Specification Revision 2.2. PCI Power Management information and Vital Product Data are the PCI “New Capabilities” implemented in this adapter.

The PCI Configuration Register File holds information about the PCI adapter for a smooth integration into the PCI bus system. The file holds data to identify the PCI adapter, about the I/O and memory requirements, and about other system resources needed, that is, interrupt lines and maximum power consumption.

For read/write accesses, the configuration space is physically located in the ASIC. Its default/start values can be loaded from the VPD serial EEPROM by the VPD serial EEPROM Loader during startup with the exception of the Vital Product Data that is located in TWSI EEPROM as required by the PCI ECR. It is read through a VPD address port in the PCI configuration register file.

The configuration registers are set to their default values by RSTn. Reloading out of the VPD serial EEPROM is initiated with the deassertion of RSTn if strapping input for EEPROM loading is set.

The 88ALP01 device supports the 256-byte configuration space as defined by the PCI Specification Revision 2.2.

3.2.1 Configuration Data Access

The configuration space of a PCI adapter is usually accessed by using BIOS routines as described in the PCI BIOS specification. The configuration space of a adapter, for example, is addressed by selecting the IDSEL (detected by reading the unique DeviceID) plus an address in the 256 bytes configuration space address range. This is translated into Configuration Read / Configuration Write cycles executed on the PCI bus hardware level.

The 88ALP01 responds to type 0 configuration accesses, i.e. AD[1:0] = "00", IDSELn asserted.

The Configuration Register File can be accessed with 8-, 16-, or 32-bit transfers. On read transactions, all data is driven as defined for full 32-bit accesses independent of CBEn[3:0]. All multi-byte numeric fields follow little-endian order, if accessed by PCI configuration cycles.

Write operations to reserved or not implemented registers are completed normally on the bus and the data is discarded. If the configuration space is targeted for a burst operation, it responds with a disconnect with the first data transfer.

Configuration transactions are not aborted (Target Initiated Termination). Read operations to reserved or not implemented registers are completed normally on the bus and a data value of 0 is returned.

3.2.2 PCI Header Region

Table 25 depicts the layout of the configuration space of one of the three functions implemented in the 88ALP01, this 256-byte configuration space has been implemented separately for each of the three functions. Besides the mandatory configuration information in the configuration space header, the 88ALP01 provides access to two 32-bit registers called Access Control Register and VPD Control Register in the device dependent region of the adapter's configuration space. These registers contain information that is only important for initialization and not for the "run-time" driver tasks.

Table 26 shows the address map of the configuration space in a 32-bit (maximum access width for configuration data) register representation.

Table 25: PCI Header Region Overview

Register Name				Offset
Header Portion				
Device ID		Vendor ID		0x00
Status		Command		0x04
Class Code			Revision ID	0x08
BIST	Base-Class	Latency Timer	Cache Line Size	0x0C
Base Address (1st)				0x10
Reserved				0x14 to 0x2B
Subsystem ID		Subsystem Vendor ID		0x2C
Reserved				0x30
Reserved			New Capabilities Pointer	0x34
Reserved				0x38
Max_Lat	Min_Gnt	Interrupt Pin	Interrupt Line	0x3C
Reserved				0x41 to 0x7C
Device Dependent Region				
SD Slot Information Register				0x40
Access Control				0x80
VPD Control				0x84
Power Management Capabilities		Power Management Next Item Pointer	Power Management Capability ID	0x88

Table 25: PCI Header Region Overview (Continued)

Register Name			Offset
Power Management Data	Reserved	Power Management Control/Status	0x8C
VPD Address		VPD Next Item Pointer	VPD Capability ID
VPD Data			0x94
VPD Serial EEPROM Loader Control		Reserved	0x98
MSI Message Control		MSI Next Item Pointer	MSI Capability ID (MSI Cap ID)
MSI Message Lower Address			0xA0
MSI Message Upper Address			0xA4
MSI Message Data			0xA8
Reserved			0xAC to 0xB0
Calibration Control Register		Calibration Status Register	0xB4
Discard Counter Register		Retry Counter Register	0xB8
Reserved			0xBC to 0xFC

Table 26: PCI Header Region Register Map

Register Name	Offset	Table and Page
Vendor ID Register	0x00	Table 27, p. 60
Device ID Register	0x02	Table 28, p. 60
Command Register	0x04	Table 29, p. 60
Status Register	0x06	Table 30, p. 62
Revision ID Register	0x08	Table 31, p. 63
Programming Interface Register, Lower Byte	0x09	Table 32, p. 63
Sub-Class Register, Middle Byte	0x0A	Table 33, p. 63
Base-Class Register, Upper Byte	0x0B	Table 34, p. 63
Cache Line Size Register	0x0C	Table 35, p. 64
Latency Timer Register	0x0D	Table 36, p. 64
Base-Class Register	0x0E	Table 37, p. 65
Built-in Self Test Register	0x0F	Table 38, p. 65
Base Address Register (1st)	0x10	Table 39, p. 65
Reserved	0x1C to 0x28	--
Subsystem Vendor ID Register	0x2C	Table 40, p. 66
Subsystem ID Register	0x2E	Table 41, p. 66
Reserved	0x30	--
New Capabilities Pointer Register	0x34	Table 42, p. 67
Reserved	0x38	--
Interrupt Line Register	0x3C	Table 43, p. 67
Interrupt Pin Register	0x3D	Table 44, p. 67
Min_Gnt Register	0x3E	Table 45, p. 68

Table 26: PCI Header Region Register Map (Continued)

Register Name	Offset	Table and Page
Max_Lat Register	0x3F	Table 46, p. 68
SD Slot Information Register	0x40	Table 47, p. 69
Access Control Register	0x80	Table 48, p. 69
VPD Control Register	0x84	Table 49, p. 70
Power Management Capability ID Register	0x88	Table 50, p. 71
Power Management Next Item Pointer	0x89	Table 51, p. 71
Power Management Capabilities Register	0x8A	Table 52, p. 72
Power Management Control/Status Register	0x8C	Table 53, p. 73
Power Management Data Register	0x8F	Table 54, p. 74
VPD Capability ID Register	0x90	Table 56, p. 75
VPD Next Item Pointer	0x91	Table 57, p. 75
VPD Address Register	0x92	Table 58, p. 75
VPD Data Registers	0x94	Table 59, p. 76
Reserved	0x58	--
VPD Serial EEPROM Loader Control Register	0x9A	Table 60, p. 76
MSI Capability ID Register (MSI Cap ID)	0x9C	Table 61, p. 76
MSI Next Item Pointer Register	0x9D	Table 62, p. 77
MSI Message Control Register	0x9E	Table 63, p. 77
MSI Message Lower Address Register	0xA0	Table 64, p. 78
MSI Message Upper Address Register	0xA4	Table 65, p. 78
MSI Message Data Register	0xA8	Table 66, p. 79
Calibration Control Register	0xB4	Table 67, p. 79
Calibration Status Register	0xB6	Table 68, p. 80
Discard Counter Register	0xB8	Table 69, p. 80
Retry Counter Register	0xBA	Table 70, p. 80

3.2.2.1 Vendor ID Register

The Vendor ID Register comprises 16 bits.

Table 27: Vendor ID Register
Offset: 0x00

Bits	Field	Type/ Init Val	Description
15:0	Vendor ID	RO 0x11AB	Identifies manufacturer of the device (Marvell)

3.2.2.2 Device ID Register

The Device ID Register comprises 16 bits that uniquely identifies the device within the product line. It is reloadable from the VPD serial EEPROM.

Table 28: Device ID Register
Offset: 0x02

Bits	Field	Type/ Init Val	Description
15:0	Device ID	RO Function 0: 0x4100 Function 1: 0x4101 Function 2: 0x4102	Identifies the device within the product line

3.2.2.3 Command Register

The Command Register comprises 16 bits. It is used to control the overall functionality of the adapter. It controls the adapter's ability to generate and respond to PCI bus cycles.

To disconnect the adapter logically from all PCI bus cycles except the configuration cycles, a value of ZERO should be written to this register.

All bits are reloadable from the VPD serial EEPROM, except for fixed value bits.

Table 29: Command Register
Offset: 0x04

Bits	Field	Type/ Init Val	Description
15:11	Reserved	RSVD	Reserved for future use
10	INTDIS	RW 0	Disable asserting INT 1 = INT is disabled 0 = INT is enabled

Table 29: Command Register (Continued)
Offset: 0x04

Bits	Field	Type/ Init Val	Description
9	FBTEN	RW 0	Fast Back-to-Back enable 1 = fast back-to-back transactions to different agents are allowed (adapter as master runs fast back-to-back write cycles). 0 = fast back-to-back transactions are only allowed to the same agent (adapter as master does not run fast back-to-back write cycles).
8	SERREN	RW 0	SERRn enable, controls the assertion of SERRn pin 1 = SERRn is enabled 0 = SERRn is disabled
7	ADSTEP	RO 0	Address/Data Stepping Fixed value adapter does not use address/data stepping.
6	PERREN	RW 0	Parity Report Response Enable 1 = Parity error reporting is enabled.
5	VGASNOOP	RO 0	VGA Palette Snoop Fixed value
4	MWIEN	RW 0	Memory Write and Invalidate Cycle Enable 1 = Memory Write and Invalidate Cycle is enabled. 0 = Memory Write must be used instead.
3	SCYCEN	RO 0	Special Cycle Enable Fixed value adapter ignores all Special Cycle operations.
2	BMEN	RW 0	Bus Master Enable 1 = bus master accesses are enabled. 0 = bus master accesses are disabled.
1	MEMEN	RW 0	Memory Space Access Enable 1 = memory accesses are responded. 0 = memory accesses are not responded.
0	IOEN	RO 0	I/O Space Access Not Supported

3.2.2.4 Status Register

The Status Register comprises 16 bits. It contains status information for the PCI bus related events.

Reads to this register behave normally. Writes are different, that is, bits can be reset but not set. A bit is reset whenever the register is written, and the data in the corresponding bit location is ONE. This behavior is marked with SH, special handling in the table below.

All bits are reloadable from the VPD serial EEPROM, except for fixed value bits.

Table 30: Status Register
Offset: 0x06

Bits	Field	Type/ Init Val	Description
15	PERR	SH 0	Parity Error Is set whenever a parity error is detected (data or address), even if parity error handling is disabled (PERREN)
14	SERR	SH 0	Signaled SERRn Is set whenever an address parity error is detected and both, SERREN and PERREN are enabled
13	RMABORT	SH 0	Received Master Abort Is set when a master transaction is terminated with a master abort sequence
12	RTABORT	SH 0	Received Target Abort Is set when a adapter's master transaction is terminated with a Target Abort sequence
11	Reserved	RSVD	Reserved for future use
10:9	DEVSEL	RO 01b	DEVSELn Timing Fixed value = 01b (medium), DEVSELn is asserted two CLK periods after FRAMEEn is asserted
8	DATAPERR	SH 0	Data Parity Error Detected Set, if a data parity error is detected running master cycles and PERREN is set
7	FB2BCAP	RO 1	Fast Back-to-Back Capable Fixed value = 1, target is capable of accepting fast back-to-back transactions
6	UDF	RO 0	UDF supported
5	66MHZCAP	RO 1	66 MHz PCI Bus Clock Capable (see section 66 MHz Operation) The default value for this field can be changed by strapping input.
4	NEWCAP	RO 1	New Capabilities Bit New capabilities list implemented
3:0	Reserved	RSVD	Reserved for future use

3.2.2.5 Revision ID Register

The Revision ID Register comprises 8 bits. It is reloadable from the VPD serial EEPROM.

Table 31: Revision ID Register
Offset: 0x08

Bits	Field	Type/ Init Val	Description
7:0	Revision ID	RO 0x10	Specifies the adapter revision number/Rev. 1.0.

3.2.2.6 Class Code Register

The Class Code Register comprises 24 bits. This register is used to identify the generic function of the adapter. The register is broken down into three byte-size fields. One of these fields, the Subclass Register, is reloadable from the VPD serial EEPROM.

Table 32: Programming Interface Register, Lower Byte
Offset: 0x09

Bits	Field	Type/ Init Val	Description
7:0		RO 0x01	Specifies the programming interface. Fixed Value = 0x01

Table 33: Sub-Class Register, Middle Byte
Offset: 0x0A

Bits	Field	Type/ Init Val	Description
7:0		RO Function 0: 0x01 Function 1: 0x05 Function 2: 0x00	Identifies the Function0 Controller 0x01 = Identified as Flash memory Controller 0x05 = Identified as SD Host controller 0x00 = Identified as Video Controller

Table 34: Base-Class Register, Upper Byte
Offset: 0x0B

Bits	Field	Type/ Init Val	Description
7:0		RO Function 0: 0x05 Function 1: 0x08 Function 2: 0x04	Broadly classifies the functions of the adapter Fixed Value = 0x05 for Function0 (NAND Flash) Fixed Value = 0x08 for Function1 (SD) Fixed Value = 0x04 for Function2 (Camera)

3.2.2.7 Cache Line Register

The Cache Line Register comprises 8 bits. The register is reloadable from the VPD serial EEPROM (not recommended).

Table 35: Cache Line Size Register
Offset: 0x0C

Bits	Field	Type/ Init Val	Description
7:0	Cache line size	RW 0	Specifies the system cache line in units of 32-bit words. The adapter supports cache line sizes of 4, 8, 16, 32, 64 or 128 dwords. Setting this register to 1, 2, or 3 is treated like being set to 0. The Cache Line Size is restricted to be a power of two. The most significant 1 in this register is used to set the Cache Line Size. Any other 1's are ignored. The adapter as bus master uses this field as criteria for starting transfers from/to complete cache lines with the Memory Write and Invalidate, Read Line, and Read Multiple commands. It also uses it to determine the disconnection of burst accesses at cache line boundaries.

3.2.2.8 Latency Timer Register

The Latency Timer Register comprises 8 bits and is reloadable from the VPD serial EEPROM (not recommended).

Table 36: Latency Timer Register
Offset: 0x0D

Bits	Field	Type/ Init Val	Description
7:0	Latency Timer	RW 0	Specifies the maximum time the adapter can continue with bus master transfers after the system arbiter has removed GNTn. The time is specified in units of PCI bus clocks. The working copy of the Timer starts counting down when the adapter asserts FRAMEn for the first time during a bus mastership period. The Timer freezes at ZERO. When the Timer is ZERO and GNTn is deasserted by the system arbiter, the adapter finishes the current data phase and then immediately releases the bus.

3.2.2.9 Header Type Register

The header type register comprises 8 bits. This register describes the format of the PCI configuration space locations 0x10 to 0x3c and states whether the PCI device is a single function or multi function device.

Table 37: Base-Class Register
Offset: 0x0E

Bits	Field	Type/ Init Val	Description
7		RO 1	Single function/multi function device Fixed value = 1, the adapter is a multi function device.
6:0		RO 0	PCI configuration space layout Fixed value = 0, the layout of the PCI configuration space locations 0x10 to 0x3c is as shown in the table above.

3.2.2.10 Built-in Self Test Register

The optional Built-in Self Test Register comprises 8 bits.

Table 38: Built-in Self Test Register
Offset: 0x0F

Bits	Field	Type/ Init Val	Description
7:0	Built-in Self Test	RO 0	BIST is not supported (optional) Fixed value = 0

3.2.2.11 Base Address Register (1st)

The 1st Base Address Register is a 32-bit register that determines the location of the adapter in the memory space, if memory mapping is used.

The base address register is reloadable from the VPD serial EEPROM.

Table 39: Base Address Register (1st)
Offset: 0x10

Bits	Field	Type/ Init Val	Description
31:14	Lower MEMBASE	RW 0	Lower 18 bits of most significant bits of memory base address.
13:4	MEMSIZE	RO 0	Memory size requirements Fixed value, indicates memory space requirement of 16384 bytes.
3	PREFEN	RO 0	Prefetch Enable Fixed value, indicates that prefetching is not allowed.

Table 39: Base Address Register (1st) (Continued)
Offset: 0x10

Bits	Field	Type/ Init Val	Description
2:1	Memory Type	RO 0x0	Memory Type 00 = Base register is 32 bits wide, and mapping can be done anywhere in the 32-bit memory space. 10 = Base register is 64 bits wide and can be mapped anywhere in the 64-bit address space. Memory Type may be reloaded out of the VPD TWSI EEPROM (further memory types). NOTE: PCI Specification Rev. 2.2 does not allow mappings below 1MB.
0	MEMSPACE	RO 0	Memory Space Indicator Fixed value, indicates that this Base Address Register describes a memory base address.

3.2.2.12 Subsystem Vendor ID Register

The Subsystem Vendor ID Register comprises 16 bits and can be used for customizing OEM versions. The unique vendor ID of the OEM allocated by the PCI SIG may be provided here.

It is reloadable from the VPD serial EEPROM.

Table 40: Subsystem Vendor ID Register
Offset: 0x2C

Bits	Field	Type/ Init Val	Description
15:0	Subsystem Vendor ID	RO 0x11AB	Identifies the subsystem vendor ID. Must be a valid non-zero value.

3.2.2.13 Subsystem ID Register

The Subsystem ID Register comprises 16 bits and can be used for customizing OEM versions.

It is reloadable from the VPD serial EEPROM.

Table 41: Subsystem ID Register
Offset: 0x2E

Bits	Field	Type/ Init Val	Description
15:0	Subsystem ID	RO 0x4100	Identifies the subsystem. Must be a valid non-zero value.

3.2.2.14 New Capabilities Pointer

The New Capabilities Pointer Register comprises 8 bits that points to the New Capabilities List. This pointer register is reloadable from the VPD serial EEPROM.

Table 42: New Capabilities Pointer Register
Offset: 0x34

Bits	Field	Type/ Init Val	Description
7:0	New Capabilities Pointer	RO 0x88	Points to the New Capabilities List

3.2.2.15 Interrupt Line Register

The Interrupt Line Register comprises 8 bits.

Table 43: Interrupt Line Register
Offset: 0x3C

Bits	Field	Type/ Init Val	Description
7:0		RW 0	The Interrupt Line Register is used to communicate interrupt line routing information. POST software writes the routing information into this register as it initializes and configures the system. The value in this register indicates, to which input of the system interrupt controller(s) the device's interrupt pin is connected. Device drivers and operating systems can use this information to determine priority and vector information. The Interrupt Line Register is not modified by the adapter. It has no effect on the operation of the device.

3.2.2.16 Interrupt Pin Register

The Interrupt Pin Register comprises 8 bits.

Table 44: Interrupt Pin Register
Offset: 0x3D

Bits	Field	Type/ Init Val	Description
7:0	Interrupt Pin	RO 0x01	Fixed value, the adapter uses the interrupt pin INTAn.

3.2.2.17 Min_Gnt Register

The Minimum Grant Time (Min_GNT) Register comprises 8 bits. It is reloadable from the VPD serial EEPROM.

Table 45: Min_Gnt Register
Offset: 0x3E

Bits	Field	Type/ Init Val	Description
7:0	Min_Gnt	RO 0x08	This read-only register specifies the adapter's desired settings for Latency Timer Value. The value specifies, in units of 1/4 microseconds, the burst period needed by the adapter assuming a clock rate of 33 MHz.

3.2.2.18 Max_Lat Register

The Maximum Latency (Max_Lat) Register comprises 8 bits and is reloadable from the VPD serial EEPROM.

Table 46: Max_Lat Register
Offset: 0x3F

Bits	Field	Type/ Init Val	Description
7:0	Max_Lat	RO 0x08	This read-only register specifies the adapter's desired settings for Latency Timer Value. The value specifies, in units of 1/4 microseconds, how often the adapter needs to gain access to the PCI bus assuming a clock rate of 33 MHz.

3.2.2.19 Expansion ROM Base Address Register

Expansion ROM is not supported, this location is treated like reserved locations.

3.2.3 Device Dependent Region

Control Access Register and VPD Control Register are the first two used locations in the "device dependent region" of the 256-byte configuration space. The default values are chosen for the most common environments.

Modifications may be handled as manufacturing option, driver options, or dedicated configuration software.

3.2.3.1 SD Slot Information Register

The SD Slot Information Register is only used for function 1.

Table 47: SD Slot Information Register

Offset: 0x40

Bits	Field	Type/ Init Val	Description
7	Reserved	RSVD	Reserved for future use
6:4	Number of Slots	RO 0x0	Number of Slots These statuses indicate the number of slots the Host Controller supports. 000 = 1 slot All other values are reserved.
3	Reserved	RSVD	Reserved for future use
2:0	First Base Address Register Number	RO 0x0	First Base Address Register Number These bits indicate the first Base Address register number assigned for the SD Host Controller register set. 000 = Base address 0x10 (BAR0) All other values are reserved.

3.2.3.2 Access Control and VPD Control Registers

Control Access Register and VPD Control Register are 32-bit registers. Both are reloadable from the VPD serial EEPROM.

Most of the switches in Access Control and VPD Control are not intended for use at run time. Manufactured adapters may come up with different settings than defined as Reset Value (if reloaded from the VPD serial EEPROM).

The fields marked with “RO” in column “Write” are writable only in test mode. The fields marked with “RW” are writable in configuration space and with normal accesses to the Control Register File.

Table 48: Access Control Register

Offset: 0x80

Bits	Field	Type/ Init Val	Description
31	Reserved	RSVD	Reserved for future use
30	DLL_DIS	RW 0x0	Disable DLL
29:24	Reserved	RSVD	Reserved for future use
23	En IO Mapping	RO 0x0	Controls mapping of the Control Register File to the I/O space (manufacturing option). 1 = Address decoding for I/O accesses enabled 0 = Any address decoding for I/O accesses is disabled
22:14	Reserved	RSVD	Reserved for future use

Table 48: Access Control Register (Continued)
Offset: 0x80

Bits	Field	Type/ Init Val	Description
13	Dis MRL	RW 0x0	Conventional PCI: 1 = Disable command Memory Read Line 0 = Enable command Memory Read Line
12	Dis MRM	RW 0x0	Conventional PCI: 1 = Disable command Memory Read Multiple 0 = Enable command Memory Read Multiple
11	Dis MWI	RW 0x0	Conventional PCI: 1 = Disable Command Memory Write and Invalidate 0 = Enable command Memory Write and Invalidate
10:3	Reserved	RSVD	Reserved for future use
2	En Rd15	RW 0x0	Conventional PCI: 1 = Enables BIU master "read 1.5" feature
1	En Wr Comb	RW 0x0	Conventional PCI: 1 = Write combining is enabled
0	En Rd Comb	RW 0x0	Conventional PCI: 1 = Read combining is enabled

Table 49: VPD Control Register
Offset: 0x84

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
31:24	Reserved_RW		
23:17	VPD Devsel	RO 0x50	Defines the Device Select Byte for the serial EEPROM used for VPD storage. Default value is 0b1010000. NOTE: VPD Devsel must not be overwritten via serial EEPROM! This may lead to a complete damage of the board (Serial EEPROM must be changed afterwards)!
16:14	VPD ROM Size	RO 0x3	Defines the size of the assembled serial EEPROM in Bytes. 0x0 = 256 Bytes 0x1 = 512 Bytes 0x2 = 1024 Bytes 0x3 = 2048 Bytes 0x4 = 4096 Bytes 0x5 = 8192 Bytes 0x6 = 16384 Bytes 0x7 = 32768 Bytes Default value is 2048 Bytes. If any other size is used, this field must be reprogrammed out of the SPI Flash Memory. Due to currently used addressing procedure via TWSI bus only applications up to size 2048 Bytes are supported.

Table 49: VPD Control Register (Continued)

Offset: 0x84

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
13:0	Reserved	RSVD	Reserved for future use

3.2.3.3

Power Management Capability ID Register

The Power Management Capability ID comprises 8 bits. Power Management is the first “New Capability” in the New Capabilities list. The New Capabilities pointer at address 0x34 contains the address 0x48 for the first entry in the New Capabilities list. The Next Item Pointer at address 0x49 holds the address of the next entry in the New Capabilities list. For 88ALP01 this is the Vital Product Data VPD New Capability ID. The attached Next Item Pointer holds a 0x0 in 88ALP01 indicating the end of the New Capabilities list.

The New Capabilities linked list uses New Capability IDs for the unique identification of the capability. New Capability IDs are assigned by the PCI SIG. The structure of New Capability information is also specified by the PCI SIG, e.g. Power Management has a New Capability ID of 0x01. The structure of the related information is specified in the PCI Power Management Interface Specification. The ID for VPD is 0x03. The structure of New Capability information is defined in the PCI Specification Rev. 2.2.

The Power Management New Capability ID Register is reloadable from the VPD serial EEPROM.

Table 50: Power Management Capability ID Register

Offset: 0x88

Bits	Field	Type/ Init Val	Description
7:0	Cap ID	RO 0x01	Power Management Capabilities ID

3.2.3.4

Power Management Next Item Pointer

The Power Management Next Item Pointer comprises 8 bits. It is reloadable from the VPD serial EEPROM.

Table 51: Power Management Next Item Pointer

Offset: 0x89

Bits	Field	Type/ Init Val	Description
7:0	Next Item Ptr	RO 0x9C	Pointer to the Next Item in the capabilities list

3.2.3.5 Power Management Capabilities Register

The Power Management Capabilities Register comprises 16 bits. It is reloadable from the VPD serial EEPROM.

Table 52: Power Management Capabilities Register
Offset: 0x8A

Bits	Field	Type/ Init Val	Description
15	PME Support	RO 0 (0 if no Vaux)	Power Management Event Support: Specifies power state in which the signal PMEn may be asserted. If no VAUX is available, this bit is forced to ZERO, signalling no PMEn support in D3 _{cold} . 1 = PMEn can be asserted from D3 _{cold} , if Vaux is available 0 = PMEn cannot be asserted from D3 _{cold} , if Vaux is not available
14		RO Function 0 and 2: 0 Function 1: 1	Power Management Event Support: Specifies power state in which the signal PMEn may be asserted. 1 = PMEn can be asserted from D3 _{hot}
13		RO Function 0 and 2: 0 Function 1: 1	Power Management Event Support: Specifies power state in which the signal PMEn may be asserted. 1 = PMEn can be asserted from D2
12		RO 0	Power Management Event Support: Specifies power state in which the signal PMEn may be asserted. 1 = PMEn can be asserted from D1
11		RO Function 0 and 2: 0 Function 1: 1	Power Management Event Support: Specifies power state in which the signal PMEn may be asserted. 1 = PMEn can be asserted from D0
10	D2 Support	RO Function 0 and 2: 0 Function 1: 1	D2 Support 0 = The adapter does not support D2 Power Management State. 1 = The adapter supports D2 Power Management State.
9	D1 Support	RO Function 0 and 2: 0 Function 1: 1	D1 Support 0 = The adapter does not support D1 Power Management State. 1 = The adapter supports D1 Power Management State.
8:6	Reserved	RO 0b000	Reserved, but reloadable from the VPD serial EEPROM for changes in the PCI Specification.
5	DSI	RO 0	Device Specific Initialization: 1 = The adapter requires device specific initialization. 0 = The adapter does not require device specific initialization.
4	Reserved	RSVD	Reserved for future use
3	PME Clock	RO 0	Power Management Event Clock: The adapter does not need PCI Clock for PMEn generation.

Table 52: Power Management Capabilities Register (Continued)
Offset: 0x8A

Bits	Field	Type/ Init Val	Description
2:0	Version	RO 0x02	The adapter complies with Revision 1.1 of the PCI Power Management Interface Specification.

3.2.3.6 Power Management Control/Status Register

The Power Management Control/Status Register comprises 16 bits and is reloadable from the VPD serial EEPROM.

Table 53: Power Management Control/Status Register
Offset: 0x8C

Bits	Field	Type/ Init Val	Description
15	PME Status	SH 0	Indicates that PMEn has been asserted by the adapter. Reset by Power on reset and when written with 1.
14:13	Data Scale	RO 0b01	Indicates the scaling factor to be used when interpreting the value of the Data Register. The read value depends on the setting of the Data Select field.
12:9	Data Select	RW 0	This 4-bit field is used to select which data is to be reported through the Data Register and Data Scale field.
8	PME En	RW 0	Enables PMEn generation. Reset by Power on reset.
7:2	Reserved	RSVD	Reserved for future use
1:0	Power State	RW 0	Controls the Power Management State of the adapter. The adapter supports all power management states.

The 16 2-bit Data_Scale fields and the 16 8-bit Data Register values that can be selected by the Data_Select field, are reloadable from the VPD serial EEPROM by writing complete 32-bit wide sets of Data Select, Data Scale, and Data to the Power Management Control/Status and Data Register.



Caution

To modify the contents of any Data Scale or Data field, the Data Select field **MUST** always be written with the desired Data Select value in the same 32-bit access!

3.2.3.7 Power Management Data Register

The Power Management Data Register comprises 8 bits and is reloadable from the VPD serial EEPROM.

Table 54: Power Management Data Register
Offset: 0x8F

Bits	Name	Type/ Init Val	Description
7:0	Data	RO See Table 55	This read-only register is used to report the state dependent data requested by the Data Select field. The value of this register is scaled by the value reported by the Data Scale field.

3.2.3.8 Power Management Data Table

Data and Data Scale are hidden registers accessible through the Power Management Control/Status Register selected by Data Select. Data Scale is writable from the VPD serial EEPROM loader by writing to Power Management Control/Status Register. Data is writable from the VPD serial EEPROM loader by writing to Power Management Data Register. Data and Data Scale are reloaded from the VPD serial EEPROM with values matching the manufacturing option.

Table 55: Power Management Data Table

Value in Data Select	Meaning	Data (8 bit) Reset Value	Data Scale (2 bit) Reset Value	[Watt] with Reset Values
0	D0 Power consumed	0x3	0x1	0.3
1	Reserved			
2				
3	D3 Power consumed	0x3	0x1	0.3
4	D0 Power dissipated	0x3	0x1	0.3
5	Reserved			
6				
7	D3 Power dissipated	0x3	0x1	0.3
8	Common logic power consumption	0x1	0x1	0.1
9:15	Reserved	0x0	0x0	0x0

3.2.3.9 VPD Capability ID Register

The VPD Capability ID Register comprises 8 bits and is reloadable from the VPD serial EEPROM. It contains the New Capability ID for VPD as specified by the PCI SIG. By default, the VPD capability is turned off. To enable this capability, the default value of the Power Management Next Item Pointer (Table 51 p. 71) must be changed from 0x5C to 0x50 through the initial loading from serial EEPROM.

Table 56: VPD Capability ID Register

Offset: 0x90

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
7:0	Cap ID	RO 0x03	VPD Capabilities ID

3.2.3.10 VPD Next Item Pointer

The VPD Next Item Pointer comprises 8 bits is reloadable from the VPD serial EEPROM.

Table 57: VPD Next Item Pointer

Offset: 0x91

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
7:0	Next Item Ptr	RO 0x9C	Pointer to the next item in the capabilities list.

3.2.3.11 VPD Address Register

The VPD Address & Data Registers control a TWSI, which runs a 100 kHz protocol to an external TWSI EEPROM. The interface signals are routed through the pins VPD_CLK and VPD_DATA. The TWSI clock and data port pins are pulled high by a pull up resistor to VDDO of the TWSI device.

The VPD Address Register comprises 16 bits and is reloadable from the VPD serial EEPROM and is also writable in I/O space.

Table 58: VPD Address Register

Offset: 0x92

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
15	Flag	EXEC 0	Starts the VPD transfers, determines its direction, and signals its completion by being toggled by HW. If written 1, a VPD write is started. Set to 0 after completion. If written 0, a VPD read is started. Set to 1 after completion.
14:0	VPD Address	RW 0x00	Address of the VPD contents to be written / read.

3.2.3.12 VPD Data Register

The VPD Data Register comprises 32 bits and is reloadable from the VPD serial EEPROM and is also writable in I/O space.

Table 59: VPD Data Registers
Offset: 0x94

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
31:0	VPD Data	RW 0x00	Must be written before VPD Address Register for VPD Write. Contains VPD Read Data after completion of VPD Read.

3.2.3.13 VPD Serial EEPROM Loader Control Register

The VPD Serial EEPROM Control Register comprises 16 bits and controls the VPD serial EEPROM Loader. It can be written in test mode.

Table 60: VPD Serial EEPROM Loader Control Register
Offset: 0x9A

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
15	Flag	RO 0	Starts and stops the data transfer. If written 1, the Serial EEPROM Loader is started. If written 0, the Serial EEPROM Loader is stopped.
14:0	Serial EEPROM Address	RO 0x200	Start address for Serial EEPROM Loader. Should be min. 256 and in 8 byte steps.

3.2.3.14 MSI Capability ID Register (MSI Cap ID)

The 88ALP01 is capable of Message Signaled Interrupt (MSI) handling.
Reloadable out of the VPD TWSI EEPROM.

Table 61: MSI Capability ID Register (MSI Cap ID)
Offset: 0x9C

NOTE: This register is only applicable to function 0 (NAND Flash Controller).

Bits	Field	Type/ Init Val	Description
7:0	Cap ID	RO 0x05	MSI Capabilities ID

3.2.3.15 MSI Next Item Pointer

Reloadable out of the VPD TWSI EEPROM.

Table 62: MSI Next Item Pointer Register

Offset: 0x9D

Bits	Field	Type/ Init Val	Description
7:0	Next Item Ptr	RO 0x0	Pointer to the next item in the capabilities list.

3.2.3.16 MSI Message Control

Reloadable out of the VPD TWSI EEPROM.

Table 63: MSI Message Control Register

Offset: 0x9E

Bits	Field	Type/ Init Val	Description
15:8	Reserved	RO 0x0	Reserved for future use
7	64 Bit Addr capable	RO 0x1	1 = The device is capable of generating a 64-bit message address 0 = The device is not capable of generating a 64-bit message address
6:4	Multiple Message Enable	RW 0x0	Defines the number of allocated messages 0b000 = 1 0b001 = 2 (not supported) 0b010 = 4 (not supported) 0b011 = 8 (not supported) 0b100 = 16 (not supported) 0b101 = 32 (not supported) 0b110 = Reserved 0b111 = Reserved This implementation supports one allocated message.
3:1	Multiple Message Capable	RO 0x0	System software reads this field to determine the number of requested messages. 0b000 = 1 0b001 = 2 (not supported) 0b010 = 4 (not supported) 0b011 = 8 (not supported) 0b100 = 16 (not supported) 0b101 = 32 (not supported) 0b110 = Reserved 0b111 = Reserved There is one requested message.

Table 63: MSI Message Control Register (Continued)
Offset: 0x9E

Bits	Field	Type/ Init Val	Description
0	MSI Enable	RW 0x0	1 = MSI is used to request service. INTAn is disabled. 0 = INTAn is used to request service. MSI is disabled Reset by D3 to D0 reset.

3.2.3.17 MSI Message Address

Reloadable out of the VPD TWSI EEPROM.

Table 64: MSI Message Lower Address Register
Offset: 0xA0

Bits	Field	Type/ Init Val	Description
31:2	MSI Message Lower Address	RW 0x00	System-specified message address If the <MSI Enable> field in the MSI Message Control Register (Table 63 p. 78) is set, the contents of this register specify the DWORD aligned address for the MSI memory write transaction.
1:0	Reserved	RSVD	Reserved for future use

Table 65: MSI Message Upper Address Register
Offset: 0xA4

Bits	Field	Type/ Init Val	Description
31:0	MSI Message Upper Address	RW 0x00	System-specified message upper address If the <MSI Enable> field in the MSI Message Control Register (Table 63 p. 78) is set, the contents of this register (if non-zero) specify the upper 32-bits of a 64-bit message address (AD[63:32]). If the contents of this register are zero, the device uses the 32 bit address specified by the MSI Message Lower Address Register (Table 64 p. 78).

3.2.3.18 MSI Message Data

Reloadable out of the VPD TWSI EEPROM.

Table 66: MSI Message Data Register
Offset: 0xA8

Bits	Field	Type/ Init Val	Description
31:16	Reserved	RSVD	Reserved for future use
15:0	Message Data	RW 0x00	System-specified message If the <MSI Enable> field in the MSI Message Control Register (Table 63 p. 78) is set, the Message Data is driven onto the lower word (AD[15:00]) of the memory write transaction's data phase. The <Multiple Message Enable> field in the MSI Message Control Register (Table 63 p. 77) defines the number (only one message supported by the chip).

3.2.3.19 Calibration Control Register

Reloadable out of the TWSI EEPROM.

Table 67: Calibration Control Register
Offset: 0xB4

Bits	Field	Type/ Init Val	Description
15:10	Reserved	RSVD	Reserved for future use
9	Cal Test	RO 0x0	1 = Force PCI buffer strength calibration to the maximum value
8	Cal En	RO 0x1	1 = Enable PCI buffer strength calibration 0 = Force PCI buffer strength according to the calibration control register
7:4	Cal P[3:0]	RO 0x0	Force value/p transistors
3:0	Cal N[3:0]	RO 0x0	Force value/n transistors

3.2.3.20 Calibration Status Register

Reloadable out of the TWSI EEPROM.

Table 68: Calibration Status Register
Offset: 0xB6

Bits	Field	Type/ Init Val	Description
15:8	Reserved	RSVD	Reserved for future use
7:4	CalP[3:0]	RO	Calibration result (number of p-channel fingers)
3:0	Cal N[3:0]	RO	Calibration result (number of n-channel fingers)

3.2.3.21 Discard Counter Register

Reloadable out of the TWSI EEPROM.

Table 69: Discard Counter Register
Offset: 0xB8

Bits	Field	Type/ Init Val	Description
15:0	Dis Cnt	RW 0x0000	Discard Counter Conventional PCI: Number of cycles BIU target waits for transaction retry before giving up and discarding the read data. 0x0000 = Discard Counter is not activated

3.2.3.22 Retry Counter Register

Table 70: Retry Counter Register
Offset: 0xBA

Bits	Field	Type/ Init Val	Description
7:0	Retry Cnt	RW 0x00	Retry counter Number of times BIU master (also target in case of PCI-X) retries a transaction before giving up. 0 = Retry forever

3.3 Global Control Registers

These registers can be accessed from all three functions.

3.3.1 Register Map

Table 71: Global Control Register Map

Register Name	Offset	Table and Page
Reserved	0x3000	--
Control/Status Register	0x3004	Table 72, p. 81
Interrupt Source Register	0x3008	Table 73, p. 83
Interrupt Mask Register	0x300C	Table 74, p. 83
Interrupt HW Error Source Register	0x3010	Table 75, p. 84
Interrupt HW Error Mask Register	0x3014	Table 76, p. 85
Reserved	0x3018 to 0x302C	--
PLL Control Register	0x3030	Table 77, p. 85
Block Control Register	0x3034	Table 78, p. 86
GPIO Functional Control Register	0x3038	Table 79, p. 86
Reserved	0x303C to 0x3154	--
Test Control Register	0x3158	Table 80, p. 87
General Purpose I/O Register	0x315C	Table 81, p. 87
VPD TWSI (HW) Control Register	0x3160	Table 82, p. 88
VPD TWSI (HW) Data Register	0x3164	Table 83, p. 89
VPD TWSI (HW) IRQ Register	0x3168	Table 84, p. 89
VPD TWSI (SW) Register	0x316C	Table 85, p. 90

3.3.2 Register Descriptions

3.3.2.1 Control/Status

Table 72: Control/Status Register
Offset: 0x3004

Bits	Field	Type/ Init Val	Description
Status			
23:16	Reserved	RSVD	Reserved for future use
Commands			
15	Reserved	RSVD	Reserved for future use

Table 72: Control/Status Register (Continued)
Offset: 0x3004

Bits	Field	Type/ Init Val	Description
14	CCIC Clock Enable	RW 0x1	CCIC Module Clock Enable This bit is only writable from function 2 (CMOS Camera Interface Controller). 0 = Clock is disabled 1 = Clock is enabled
13	SDH Clock Enable	RW 0x1	SDH Module Clock Enable This bit is only writable from function 1 (SD/SDIO). 0 = Clock is disabled 1 = Clock is enabled
12	NAND Clock Enable	RW 0x1	NAND Controller Module Clock Enable This bit is only writable from function 0 (NAND Flash Controller). 0 = Clock is disabled 1 = Clock is enabled
11	ClkRun Enable Set	EXEC 0	Sets and clears ClkRunEnable
10	ClkRun Enable Clear	EXEC 1	
9:8	Reserved	RSVD	Reserved for future use
7	Set IRQ SW	EXEC 0	Sets and clears Interrupt Request from SW
6	Clear IRQ SW	EXEC 1	
5	Stop Master Done	RO 0	As soon as the Master Statemachine is in the idle state after Stop Master is set, Stop Master Done is asserted. Stop Master Done is reset to 0 by resetting Stop Master.
4	Stop Master	RW 0 (HW)	If Stop Master is set, all requests from the BMUs except for the one being serviced at the moment, are masked. The Master Statemachine reaches the idle state after the current request is serviced. Stop Master has to be reset by the SW after the BMUs are reset. If the BMUs are not reset, the 88ALP01 resumes master action at the point when it was interrupted by Stop Master.
3	Master Reset Clear	EXEC 1	Set/Clear Master Reset If Master Reset is set, all devices related to the master interface (BMUs, FIFOs, State machines) are in their reset state. Executed, if appropriate bit is set to 1.
2	Master Reset Set	EXEC 0 (SW)	
1	SW Reset Clear	EXEC 1	Set/Clear SW Reset Executed if appropriate bit is set to 1.
0	SW Reset Set	EXEC 0 (HW)	If SW Reset is set, all internal and external devices are in their reset state.

3.3.2.2 Interrupt Source Register

Table 73: Interrupt Source Register
Offset: 0x3008

Bits	Field	Type/ Init Val	Description
31	PCI Error Interrupt	RO 0x0	PCI Error Interrupt 1 = At least one of the HW Interrupts occurred (Interrupt HW Error Source Register (Table 75 p. 84)) 0 = No HW interrupt active
30:27	Reserved	RSVD	Reserved for future use
26	IRQ VPD TWSI Ready	RO 0x0	Interrupt on completion of VPD TWSI transfer 0 = Interrupt is not pending 1 = Interrupt is pending
25:3	Reserved	RSVD	Reserved for future use
2	IRQ CCIC	RO 0x0	CCIC Interrupt 0 = Interrupt is not pending 1 = Interrupt is pending
1	IRQ SDH	RO 0x0	SDIO Interrupt 0 = Interrupt is not pending 1 = Interrupt is pending
0	IRQ NAND	RO 0x0	NAND Flash Interrupt 0 = Interrupt is not pending 1 = Interrupt is pending

3.3.2.3 Interrupt Mask Register

Each bit position defines, if the dedicated interrupt is propagated to the internal interrupt line irq. The enable bits have the same bit positions as in the Interrupt Source Register (Table 73 p. 83). Unused bit positions are treated like reserved.

Table 74: Interrupt Mask Register
Offset: 0x300C

Bits	Field	Type/ Init Val	Description
31	En IRQ HW Interrupt	RW 0 (SW)	Enable Interrupt HW Interrupt 0 = Interrupt disabled 1 = Interrupt enabled
30:27	Reserved	RSVD	Reserved for future use
26	En IRQ VPD TWSI Ready	RO 0x0	Enable Interrupt on Completion of VPD TWSI Transfer 0 = Interrupt disabled 1 = Interrupt enabled
25:3	Reserved	RSVD	Reserved for future use

Table 74: Interrupt Mask Register (Continued)
Offset: 0x300C

Bits	Field	Type/ Init Val	Description
2	En IRQ CCIC	RW 0 (SW)	Enable CCIC Interrupt This bit is only writable from function 2 (CMOS Camera Interface Controller). 0 = Interrupt disabled 1 = Interrupt enabled
1	En IRQ SDH	RW 0 (SW)	Enable SDIO Interrupt This bit is only writable from function 1 (SD/SDIO). 0 = Interrupt disabled 1 = Interrupt enabled
0	En IRQ NAND	RW 0 (SW)	Enable NAND Flash Interrupt This bit is only writable from function 0 (NAND Flash Controller). 0 = Interrupt disabled 1 = Interrupt enabled

3.3.2.4 Interrupt HW Error Source Register

Table 75: Interrupt HW Error Source Register
Offset: 0x3010

Bits	Field	Type/ Init Val	Description
General Interrupts			
31:28	Reserved	RSVD	Reserved for future use
27	IRQ Master Error	RO 0 (SW)	Interrupt Master Error detected on master accesses Set if <DATAPERR>, <RTABORT>, or <RMABORT> are set in the Status Register (Table 30 p. 62).
26	IRQ Status	RO 0 (SW)	Interrupt Status Exception Set if <PERR>, <RMABORT>, <RTABORT>, or <DATAPERR> are set in the Status Register (Table 30 p. 62).
25:0	Reserved	RSVD	Reserved for future use

3.3.2.5 Interrupt HW Error Mask Register

Each bit position defines if the dedicated interrupt is propagated to the Interrupt Line INTAn. The enable bits have the same bit positions as in the Interrupt HW Error Source Register (Table 75 p. 84). Unused bit positions are treated like reserved.

Table 76: Interrupt HW Error Mask Register
Offset: 0x3014

Bits	Field	Type/ Init Val	Description
General Interrupts			
31:28	Reserved	RSVD	Reserved for future use
27	En IRQ Master Error	RW 0 (SW)	Enable Interrupt Master Error Detected on Master Accesses 0 = Interrupt disabled 1 = Interrupt enabled
26	En IRQ Status	RW 0 (SW)	Enable Interrupt Status Exception 0 = Interrupt disabled 1 = Interrupt enabled
25:0	Reserved	RSVD	Reserved for future use

3.3.2.6 PLL Control Register

Table 77: PLL Control Register
Offset: 0x3030

Bits	Field	Type/ Init Val	Description
31:20	Reserved	RSVD	Reserved for future use
19:17	ICHP	RW 0x0	PLL ICHP Value
16	DIS_PLL_CLK	RW 0	Disable PLL Clock Output 0 = Enabled 1 = Disabled
15:8	PLL_N	RW 0x3E	PLL N Value
7:0	PLL_M	RW 0x6	PLL M Value

3.3.2.7 Block Control Register

Table 78: Block Control Register
Offset: 0x3034

Bits	Field	Type/ Init Val	Description
31:3	Reserved	RSVD	Reserved for future use
2	CCIC Soft Reset	RW 0x0	CCIC Soft Reset This bit is only writable from function 2 (CMOS Camera Interface Controller). 0 = CCIC block not in reset 1 = CCIC block in reset
1	SDH Soft Reset	RW 0x0	SDIO Soft Reset This bit is only writable from function 1 (SD/SDIO). 0 = SDH block not in reset 1 = SDH block in reset
0	NFU Soft Reset	RW 0x0	NAND Flash Soft Reset This bit is only writable from function 0 (NAND Flash Controller). 0 = NFU block not in reset 1 = NFU block in reset

3.3.2.8 GPIO Functional Control Register

Table 79: GPIO Functional Control Register
Offset: 0x3038

Bits	Field	Type/ Init Val	Description
31:4	Reserved	RSVD	Reserved for future use
3	GPIO Function Control[3]	RW 0x1	GPIO Function Control [3] 0 = Functional mode 1 = GPIO mode NOTE: This bit is only accessible from Function 2.
2	GPIO Function Control[2]	RW 0x0	GPIO Function Control [2] 0 = Functional mode 1 = GPIO mode NOTE: This bit is only accessible from Function 1.
1	GPIO Function Control[1]	RW 0x0	GPIO Function Control [1] 0 = Functional mode 1 = GPIO mode NOTE: This bit is only accessible from Function 1.
0	GPIO Function Control[0]	RW 0x0	GPIO Function Control [0] 0 = Functional mode 1 = GPIO mode NOTE: This bit is only accessible from Function 1.

3.3.2.9 Test Control Register

Reset by SW Reset.

Table 80: Test Control Register
Offset: 0x3158

Bits	Field	Type/ Init Val	Description
7:2	Reserved	RSVD	Reserved for future use
1	En Config Write On	EXEC 0x01	Enables write accesses to the Configuration Registers over the Control Register File. The whole VPD TWSI EEPROM is writable when En Config Write is set. Enables write access to some of the write protected Control Registers and the functionality is mentioned explicitly within the description of these registers.
0	En Config Write Off		

3.3.2.10 General Purpose I/O Register

Table 81: General Purpose I/O Register
Offset: 0x315C

Bits	Field	Type/ Init Val	Description
31:20	Reserved	RSVD	Reserved for future use
19	GPIO Dir[3]	RW 0x0	GPIO Dir[3] Defines the type of GPIO pins 0 = Input 1 = Output NOTE: This bit is only accessible from Function 2.
18	GPIO Dir[2]	RW 0x1	GPIO Dir[2] Defines the type of GPIO pins 0 = Input 1 = Output NOTE: This bit is only accessible from Function 1.
17	GPIO Dir[1]	RW 0x0	GPIO Dir[1] Defines the type of GPIO pins 0 = Input 1 = Output NOTE: This bit is only accessible from Function 1.
16	GPIO Dir[0]	RW 0x1	GPIO Dir[0] Defines the type of GPIO pins 0 = Input 1 = Output NOTE: This bit is only accessible from Function 1.
15:4	Reserved	RSVD	Reserved for future use
3	GPIO[3]	RW 0x0	These bits are routed to the chip's pins for future external options. NOTE: This bit is only accessible from Function 2.

Table 81: General Purpose I/O Register (Continued)
Offset: 0x315C

Bits	Field	Type/ Init Val	Description
2	GPIO[2]	RW 0x0	These bits are routed to the chip's pins for future external options. NOTE: This bit is only accessible from Function 1.
1	GPIO[1]	RW 0x0	These bits are routed to the chip's pins for future external options. NOTE: This bit is only accessible from Function 1.
0	GPIO[0]	RW 0x0	These bits are routed to the chip's pins for future external options. NOTE: This bit is only accessible from Function 1.

3.3.2.11 VPD TWSI (HW) Registers

These registers implement a serial TWSI to the optional temperature/voltage sensor. Hardware runs the 100 kHz serial TWSI protocol to obtain data.



Caution

The hardware controlled TWSI and the software controlled TWSI are connected to the same TWSI bus (pins VPD_DATA and VPD_CLK). They must not be used in parallel.

If the hardware controlled TWSI is used, the VPD TWSI (SW) Register (Table 85 p. 90) has to be set to inactive values (Reset values).

If the software controlled VPD TWSI is used, the hardware controlled VPD TWSI MUST NOT be started (<Flag> field in the VPD TWSI (HW) Control Register (Table 82 p. 88)).

The VPD TWSI clock and data port pins are pulled high by a pull up resistor to VDDO of the TWSI device.

Table 82: VPD TWSI (HW) Control Register
Offset: 0x3160

Bits	Field	Type/ Init Val	Description
31	Flag	EXEC 0x0	Starts the TWSI data transfers, determines its direction and signals its completion by being toggled by hardware. 1 = TWSI write is started and set back to 0 after completion 0 = TWSI read is started and set back to 1 after completion Generates an interrupt upon completion.
30:16	TWSI Address	RW 0x00	Address of the TWSI device register to be written/read.
15:9	TWSI Devsel	RW 0x00	Devsel Byte of the TWSI device to be written/read.
8:5	Reserved	RSVD	Reserved for future use
4	TWSI Burst	RW 0x0	0 = Single byte transfers 1 = 7 byte Page Mode write transfers with fixed page size of 8 bytes assumed

Table 82: VPD TWSI (HW) Control Register (Continued)
Offset: 0x3160

Bits	Field	Type/ Init Val	Description
3:1	VPD TWSI Device Size	RW 0x00	Defines the size of the addressed TWSI Device in bytes 0 = 256 bytes and smaller 1 = 512 bytes 2 = 1024 bytes 3 = 2048 bytes 4 = 4096 bytes 5 = 8192 bytes 6 = 16384 bytes 7 = 32768 bytes
0	TWSI Stop	EXEC 0	A written 1 interrupts the current VPD TWSI transfer at the next byte boundary with a stop condition and signals end of TWSI transfer by toggling <Flag>.

Table 83: VPD TWSI (HW) Data Register
Offset: 0x3164

Bits	Field	Type/ Init Val	Description
31:0	TWSI Data	RW 0x00	Must be written before TWSI Address Register for TWSI write. Contains TWSI read data after completion of TWSI read.

Table 84: VPD TWSI (HW) IRQ Register
Offset: 0x3168

Bits	Field	Type/ Init Val	Description
31:1	Reserved	RSVD	Reserved for future use
0	Clear IRQ VPD TWSI	EXEC 0x0	Clears Interrupt Request from TWSI hardware interface

3.3.2.12 VPD TWSI (SW) Register

This register implements a serial TWSI to the optional temperature/voltage sensor. SW has to run the serial TWSI protocol to obtain data.

As output, the Data Port must simulate an open collector output in order to obtain a 0.7 VDDO signal level at the TWSI device.

Driving to low level:

- TWSI Data = 0
- TWSI Data Dir = 1

Floating to high level:

- TWSI Data = x
- TWSI Data Dir = 0

! The hardware controlled TWSI and the software controlled TWSI are connected to the same TWSI bus (pins VPD_DATA and VPD_CLK). They must not be used in parallel.

Caution If the hardware controlled TWSI is used, the VPD TWSI (SW) Register ([Table 85 p. 90](#)) has to be set to inactive values (Reset values).

If the software controlled TWSI is used, the hardware controlled TWSI must not be started (<Flag> field in the VPD TWSI (HW) Control Register ([Table 82 p. 88](#))).

The TWSI clock and data port pins are pulled high by a pull up resistor to VDDO of the TWSI device.

Table 85: VPD TWSI (SW) Register
Offset: 0x316C

Bits	Field	Type/ Init Val	Description
31:3	Reserved	RSVD	Reserved for future use
2	TWSI Data Dir	RW 0x0 (SW)	Defines direction of TWSI Data Port: 0 = Input 1 = Output
1	TWSI Data	RW 0x0 (SW)	TWSI Data Port
0	TWSI Clock	RW 1 (SW)	TWSI Clock

3.4 NAND Flash Unit

3.4.1 Register Map

Table 86: NAND Flash Unit Registers

Register Name	Offset	Table and Page
Control Register	0x00	Table 87, p. 91
Control Register 2	0x04	Table 88, p. 92
Control Register 3	0x08	Table 89, p. 93
Status Register	0x0C	Table 90, p. 93
Interrupt Register	0x10	Table 91, p. 93
Interrupt Mask Register	0x14	Table 92, p. 94
Data Length Register	0x18	Table 93, p. 94
Address Register	0x1C	Table 94, p. 94
Address Register 2	0x20	Table 95, p. 95
Timing Parameter Register 1	0x24	Table 96, p. 95
Timing Parameter Register 2	0x28	Table 97, p. 96
Timing Parameter Register 3	0x2C	Table 98, p. 96
Non-Memory Read Data Register	0x30	Table 99, p. 97
Read ECC Generated Code Register	0x34	Table 100, p. 97

Table 86: NAND Flash Unit Registers (Continued)

Register Name	Offset	Table and Page
Read ECC Read Code Register	0x38	Table 101, p. 97
Read ECC Result Register	0x3C	Table 102, p. 97
DMA Control Register	0x40	Table 103, p. 98
DMA Address Register 0	0x44	Table 104, p. 98
Reserved	0x48	--
RS ECC Decode CRC Register	0x4C	Table 105, p. 98
RS ECC Decode Syndrome 0 and 1 Register	0x50	Table 106, p. 99
RS ECC Decode Syndrome 2 and 3 Register	0x54	Table 107, p. 99
RS ECC Decode Syndrome 4 and 5 Register	0x58	Table 108, p. 99
RS ECC Decode Syndrome 6 and 7 Register	0x5C	Table 109, p. 100
Control Register 4	0x60	Table 110, p. 100
NAND I/O Drive Strength Register	0x64	Table 111, p. 100
Read Data Registers	0x1000 to 0x183C	Table 112, p. 100
Reserved	0x1840 to 0x1FFC	--
Write Data Registers	0x2000 to 0x283C	Table 113, p. 101
Reserved	0x2840 to 0x2FFC	--

3.4.2 Registers

Table 87: Control Register
Offset: 0x00

Bits	Field	Type/ Init Val	Description
31	cmd_vld	RW 0x0	Command Valid (clear on write)
30	do_addr_cyc	RW 0x0	0 = No operation 1 = Command sequence has address cycle
29:27	num_addr_cyc	RW 0x0	Number of Address Cycle 0b000 = 1 cycle (Default) 0b001 = 2 cycles ... 0b111 = 8 cycles
26	rd	RW 0x0	0 = No operation 1 = Command sequence read data from NAND Flash memory cell
25	wr	RW 0x0	0 = No operation 1 = Command writes data to NAND Flash memory cell
24:22	num_nonmem_rd [3:1]	RW 0x0	These bits are for use in commands such as status read and id read. 0 = Data operation 1 = Number of non-memory cell reads (read ID or read status commands)

Table 87: Control Register (Continued)
Offset: 0x00

Bits	Field	Type/ Init Val	Description
21	wait_bsy_aft_seq	RW 0x0	Wait Busy After Sequence After the command sequence is done, the command waits for trp, then returns to idle. 0 = Enabled 1 = Disabled
20	num_nonmem_rd [0]	RW 0x0	These bits are for use in commands such as status read and id read. 0 = Data operation 1 = Number of non-memory cell reads (read ID or read status commands)
19	use_ce_1	RW 0x0	0 = Use CE[0]n 1 = Use CE[1]n
18:8	Reserved	RSVD 0x0	Reserved
7:0	cmd	RW 0x0	Command This is the value driven on NF_IO[7:0] when NF_CLE is asserted.

Table 88: Control Register 2
Offset: 0x04

Bits	Field	Type/ Init Val	Description
31	Reserved	RW 0x0	Reserved for future use
30	auto_wr_ecc2bfr	RW 0x0	0 = No operation 1 = Automatic generate and write ECC to write buffer
29:28	pg_size	RW 0x0	Page Size 0b00 = 512 bytes (Default) 0b10 = 2 KBs
27	ecc_sel	RW 0x0	ECC Select 0 = Hamming code 1 = Reed-Solomon code
27:9	Reserved	RSVD	Reserved for future use
8	cmd2_vld	RW 0x0	0 = No operation 1 = Second command valid
7:0	cmd2	RW 0x0	Second Command This is the value driven on NF_IO[7:0] during the second NF_CLE. NOTE: For read operation, the second command comes right after address cycles. For write command, the second command comes after data out cycles.

Table 89: Control Register 3
Offset: 0x08

Bits	Field	Type/ Init Val	Description
31	rd_bsy_rst	RW 0x0	Read Busy Reset 1 = Send reset command to NAND device when device rdy==0.
30	wp_val	RW 0x0	0 = No operation 1 = Write protect bar to NAND device
29:0	Reserved	RSVD	Reserved for future use

Table 90: Status Register
Offset: 0x0C

Bits	Field	Type/ Init Val	Description
31	nand_dev_bsy	RO 0x0	0 = No operation 1 = NAND device is busy
30	nand_dev_rdy	RO	0 = No operation 1 = NAND Flash device is ready
29:0	Reserved	RSVD	Reserved for future use

Table 91: Interrupt Register
Offset: 0x10

Bits	Field	Type/ Init Val	Description
31	cmd_done	RW 0x0	Command Done 1 = Write 1 to clear interrupt
30	flash_rdy	RW 0x0	Flash is Ready 1 = Write 1 to clear interrupt
29	Reserved	RW 0x0	Reserved for future use
28	dma_done	RW 0x0	DMA Done Interrupt 1 = Write 1 to clear interrupt
27	boot_done	RW 0x0	Auto Boot Load Done Interrupt 1 = Write 1 to clear interrupt
26:0	Reserved	RSVD 0x0	Reserved for future use

Table 92: Interrupt Mask Register
Offset: 0x14

Bits	Field	Type/ Init Val	Description
31	cmd_done_mask	RW 0x1	Command Done Interrupt Mask 1 = Masked (Default) 0 = Not masked
30	flash_rdy_mask	RW 0x1	Flash Ready Interrupt Mask 1 = Masked (Default) 0 = Not masked
29	Reserved	RW 0x1	Reserved for future use
28	dma_done_int_mask	RW 0x1	DMA Done Interrupt Mask 1 = Masked (Default) 0 = Not masked
27	boot_done_int_mask	RW 0x1	Boot Done Interrupt Mask 1 = Masked (Default) 0 = Not masked
26:0	Reserved	RSVD 0x1	Reserved for future use

Table 93: Data Length Register
Offset: 0x18

Bits	Field	Type/ Init Val	Description
31:12	Reserved	RSVD 0x0	Reserved for future use
11:0	num_bytes	RW 0x0	Number of Bytes to Read/Write

Table 94: Address Register
Offset: 0x1C

Bits	Field	Type/ Init Val	Description
31:16	Reserved	RSVD 0x0	Reserved for future use
15:8	addr_1	RW 0x0	Address 1 This is the value driven on NF_IO[7:0] during the second NF_ALE.
7:0	addr_0	RW 0x0	Address 0 This is the value driven on NF_IO[7:0] during the first NF_ALE.

Table 95: Address Register 2
Offset: 0x20

Bits	Field	Type/ Init Val	Description
31:24	Reserved	RSVD 0x0	Reserved for future use
23:16	addr_4	RW 0x0	Address 4 This is the value driven on NF_IO[7:0] during the fifth NF_ALE.
15:8	addr_3	RW 0x0	Address 3 This is the value driven on NF_IO[7:0] during the fourth NF_ALE.
7:0	addr_2	RW 0x0	Address 2 This is the value driven on NF_IO[7:0] during the third NF_ALE.

Table 96: Timing Parameter Register 1
Offset: 0x24

NOTE: The bits in this register are NAND Flash part-dependent timing parameters specified in number of internal NAND Flash clock. For descriptions of these bits, refer to documentation on the NAND Flash part that is being implemented.

Bits	Field	Type/ Init Val	Description
31:28	tcls	RW 0x0	CLE Setup Time
27:24	tclh	RW 0x0	CLE Hold Time
23:20	tals	RW 0x0	ALE Setup Time
19:16	talh	RW 0x0	ALE Hold Time
15:8	twb	RW 0x0	WE High to Busy
7:0	trb	RW 0x0	Amount of time needed to wait to validate ready before starting to sample

Table 97: Timing Parameter Register 2
Offset: 0x28

NOTE: The bits in this register are NAND Flash part-dependent timing parameters specified in number of internal NAND Flash clock. For descriptions of these bits, refer to documentation on the NAND Flash part that is being implemented.

Bits	Field	Type/ Init Val	Description
31:28	trr	RW 0x0	Ready to REn Low
27:24	trea	RW 0x0	REn Access Time
23:20	tdh	RW 0x0	Data Hold Time
19:16	tds	RW 0x0	Data Setup Time
15:12	trh	RW 0x0	RE Pulse Width High
11:8	trp	RW 0x0	RE Pulse Width Low This bit must be >=1
7:4	twh	RW 0x0	WEn High Hold Time
3:0	twp	RW 0x0	WEn Pulse Width This bit must be >= 2

Table 98: Timing Parameter Register 3
Offset: 0x2C

NOTE: The bits in this register are NAND Flash part-dependent timing parameters specified in number of internal NAND Flash clock. For descriptions of these bits, refer to documentation on the NAND Flash part that is being implemented.

Bits	Field	Type/ Init Val	Description
31:28	tar	RW 0x0	ALE to REn Delay
27:24	tclr	RW 0x0	CLE to REn Delay
23:0	Reserved	RSVD 0x0	Reserved for future use

Table 99: Non-Memory Read Data Register
Offset: 0x30

Bits	Field	Type/ Init Val	Description
31:0	read data	RO 0x0	Returns Non-Memory Read Data

Table 100: Read ECC Generated Code Register
Offset: 0x34

Bits	Field	Type/ Init Val	Description
31:28	Reserved	RSVD 0x0	Reserved for future use
27:0	gen_code	RO 0x0	Hardware Generated ECC on Read

Table 101: Read ECC Read Code Register
Offset: 0x38

Bits	Field	Type/ Init Val	Description
31:28	Reserved	RSVD 0x0	Reserved for future use
27:0	rd_code	RO 0x0	ECC Read from NAND Device

Table 102: Read ECC Result Register
Offset: 0x3C

Bits	Field	Type/ Init Val	Description
31:18	Reserved	RSVD 0x0	Reserved for future use
18	RS ECC result	RO 0x0	Reed-Solomon ECC Result 0 = No errors 1 = Errors
17:16	result	RO 0x0	ECC Check Result 0b00 = No error 0b01 = Error, but correctable 0b10 = Error, but not correctable 0b11 = Reserved
15:14	Reserved	RSVD 0x0	Reserved for future use

Table 102: Read ECC Result Register (Continued)
Offset: 0x3C

Bits	Field	Type/ Init Val	Description
13:0	fail bit location	RO 0x0	Failed Bit Location

Table 103: DMA Control Register
Offset: 0x40

Bits	Field	Type/ Init Val	Description
31	DMA active	RW 0x0	DMA Active 1 = DMA is active (nanf_dma has sole access to rd and wr buffer in nanf_if) 0 = DMA is not active (nanf_ahb_slv has sole access to rd and wr buffer)
30	Reserved	RSVD	Reserved for future use
29	DMA op	RW 0x0	DMA Operation 0 = Transfer data out of NAND controller 1 = Transfer data into NAND controller
28:12	Reserved	RSVD 0x0	Reserved for future use
11:0	DMA dlen	RW 0x0	DMA Data Length (in bytes, limited to page size) 0x0 = 0 bytes 0x1 = 1 bytes 0x2 = 2 bytes ... 0x840 = 2112 bytes

Table 104: DMA Address Register 0
Offset: 0x44

Bits	Field	Type/ Init Val	Description
31:0	DMA addr	RW 0x0	DMA Address [31:0] (4-byte aligned) Address to/from which data is to transfer

Table 105: RS ECC Decode CRC Register
Offset: 0x4C

Bits	Field	Type/ Init Val	Description
31:16	Reserved	RSVD	Reserved for future use
15:8	crc_1	RO 0x0	CRC 1

Table 105: RS ECC Decode CRC Register (Continued)
Offset: 0x4C

Bits	Field	Type/ Init Val	Description
7:0	crc_0	RO 0x0	CRC 0

Table 106: RS ECC Decode Syndrome 0 and 1 Register
Offset: 0x50

Bits	Field	Type/ Init Val	Description
31:28	Reserved	RSVD	Reserved for future use
27:16	syndrome 1	RO 0x0	Syndrome 1
15:12	Reserved	RSVD	Reserved for future use
11:0	syndrome 0	RO 0x0	Syndrome 0

Table 107: RS ECC Decode Syndrome 2 and 3 Register
Offset: 0x54

Bits	Field	Type/ Init Val	Description
31:28	Reserved	RSVD	Reserved for future use
27:16	syndrome 3	RO 0x0	Syndrome 3
15:12	Reserved	RSVD	Reserved for future use
11:0	syndrome 2	RO 0x0	Syndrome 2

Table 108: RS ECC Decode Syndrome 4 and 5 Register
Offset: 0x58

Bits	Field	Type/ Init Val	Description
31:28	Reserved	RSVD	Reserved for future use
27:16	syndrome 5	RO 0x0	Syndrome 5
15:12	Reserved	RSVD	Reserved for future use
11:0	syndrome 4	RO 0x0	Syndrome 4

Table 109: RS ECC Decode Syndrome 6 and 7 Register

Offset: 0x5C

Bits	Field	Type/ Init Val	Description
31:28	Reserved	RSVD	Reserved for future use
27:16	syndrome 7	RO 0x0	Syndrome 7
15:12	Reserved	RSVD	Reserved for future use
11:0	syndrome 6	RO 0x0	Syndrome 6

Table 110: Control Register 4

Offset: 0x60

Bits	Field	Type/ Init Val	Description
31:9	Reserved	RSVD	Reserved for future use
8	Rd_Dly_n	RW 0x0	Read Delay 1 = Do not delay read to meet NAND data out setup time requirement 0 = Delay read to meet NAND data out setup time requirement
7:0	Reserved	RSVD	Reserved for future use

Table 111: NAND I/O Drive Strength Register

Offset: 0x64

Bits	Field	Type/ Init Val	Description
31:5	Reserved	RSVD	Reserved for future use
4:0	Drive_strength	RW 0xF	Drive Strength

Table 112: Read Data Registers

Offset: 0x1000 to 0x183C

Bits	Field	Type/ Init Val	Description
31:0	read data	RO 0x0	Read Data Each read retrieves 4 bytes from the read buffer. The total memory is 2112 bytes.

Table 113: Write Data Registers
Offset: 0x2000 to 0x283C

Bits	Field	Type/ Init Val	Description
31:0	write data	WO 0x0	Write Data Each write inputs 4 bytes to the write buffer. The total memory is 2112 bytes.

3.5 SDIO Host Controller Registers



Note

For the programmer:

- The DMA system buffer starting byte address in System Address Low Register (Table 115 p. 103) must be word (4 byte) aligned.
- The Block Size Register (Table 117 p. 103) only supports multiples of 4 byte block sizes (such as 4, 8, 12, 16, etc.).
- Once after reset, for proper set up of the I/Os, set the `<data3_iddqn>` field in the I/O Control Register (Table 154 p. 123) to 0x0.
- Once after reset, to enable data CRC checking, set the `<crc16_chk_en>` field in the Command 1 Register (Table 155 p. 123) to 0x1.
- The timeout value (`<Timeout_value>` field in the Timeout Control/Software Reset Register (Table 138 p. 113)) is off by 1. If you set this value to 0xA, it actually calculates the timeout value as if it were set to 0x9.
- The `<sd_bus_power>` and `<sd_bus_vlt>` fields in the Host Control Register (Table 135 p. 110) must be set by two different write actions. First set the `<sd_bus_vlt>` field to the correct value and then enable `<sd_bus_power>` by setting it to 0x1.
- Whenever the `<host_dma_bdry>` field in the Block Size Register (Table 117 p. 103) causes an interrupt and if this interrupt is not serviced within the data timeout intervals as specified in `<Timeout_value>` field in the Timeout Control/Software Reset Register (Table 138 p. 113), a timeout interrupt will occur.
- The SDIO registers included in this section match those provided in the SD Specification. For more information, refer to the specification:
Technical Committee SD Association. SD Specifications Part A2 SD Host Controller Standard Simplified Specification Version 1.00. San Ramon, CA: SD Association, 2006.
- Do not write to the reserved registers in the 0x50 to 0xFA offset range.

3.5.1 Register Map

Table 114: SDIO Host Controller Register Map

Register Name	Offset	Table and Page
System Address Low Register	0x00	Table 115, p. 103
System Address High Register	0x02	Table 116, p. 103
Block Size Register	0x04	Table 117, p. 103
Block Count Register	0x06	Table 118, p. 104

Table 114: SDIO Host Controller Register Map (Continued)

Register Name	Offset	Table and Page
Argument Low Register	0x08	Table 119, p. 104
Argument High Register	0x0A	Table 120, p. 104
Transfer Mode Register	0x0C	Table 121, p. 104
Command Register	0x0E	Table 122, p. 105
Response Register 0	0x10	Table 123, p. 106
Response Register 1	0x12	Table 124, p. 106
Response Register 2	0x14	Table 125, p. 106
Response Register 3	0x16	Table 126, p. 106
Response Register 4	0x18	Table 127, p. 107
Response Register 5	0x1A	Table 128, p. 107
Response Register 6	0x1C	Table 129, p. 107
Response Register 7	0x1E	Table 130, p. 107
Buffer Data Port0 Register	0x20	Table 131, p. 107
Buffer Data Port1 Register	0x22	Table 132, p. 108
Present State Register 0	0x24	Table 133, p. 108
Present State Register 1	0x26	Table 134, p. 109
Host Control Register	0x28	Table 135, p. 110
Block Gap Control Register	0x2A	Table 136, p. 111
Clock Control Register	0x2C	Table 137, p. 112
Timeout Control/Software Reset Register	0x2E	Table 138, p. 113
Normal Interrupt Status Register	0x30	Table 139, p. 114
Error Interrupt Status Register	0x32	Table 140, p. 115
Normal Interrupt Status Enable Register	0x34	Table 141, p. 116
Error Interrupt Status Enable Register	0x36	Table 142, p. 117
Normal Interrupt Status Interrupt Enable Register	0x38	Table 143, p. 118
Error Interrupt Status Interrupt Enable Register	0x3A	Table 144, p. 119
Auto CMD12 Error Status Register	0x3C	Table 145, p. 120
Capabilities Register	0x40	Table 146, p. 120
Capabilities Register 1	0x42	Table 147, p. 121
Capabilities Register 2	0x44	Table 148, p. 121
Capabilities Register 3	0x46	Table 149, p. 121
Maximum Current Register 0	0x48	Table 150, p. 122
Maximum Current Register 1	0x4A	Table 151, p. 122
Maximum Current Register 2	0x4C	Table 152, p. 122
Maximum Current Register 3	0x4E	Table 153, p. 122
Reserved	0x50 to 0x5C	--
I/O Control Register	0x60	Table 154, p. 123
Reserved	0x64 to 0x68	--
Command 1 Register	0x6A	Table 155, p. 123

Table 114: SDIO Host Controller Register Map (Continued)

Register Name	Offset	Table and Page
Slot Interrupt Status Register	0xFC	Table 157, p. 123
Host Control Version Register	0xFE	Table 158, p. 124

Table 115: System Address Low Register

Offset: 0x00

Bits	Field	Type/ Init Val	Description
15:0	Dma_addr_l	RW 0	16 LSB of DMA system buffer starting byte address NOTE: The DMA system buffer starting byte address must be word (4 byte) aligned.

Table 116: System Address High Register

Offset: 0x02

Bits	Field	Type/ Init Val	Description
15:0	Dma_addr_h	RW 0	16 MSB of DMA system buffer starting byte address

Table 117: Block Size Register

Offset: 0x04

Bits	Field	Type/ Init Val	Description
15	Reserved	RSVD	Reserved for future use
14:12	host_dma_bdry	RW	Host DMA buffer boundary. This field specifies the host memory buffer boundary. If this boundary is crossed then an interrupt(dma_int) is generated. This interrupt is reflected in <Tx_rdy> field in the Normal Interrupt Status Register (Table 139 p. 114). 0x0 = 4 KB 0x1 = 8 KB 0x2 = 16 KB 0x3 = 32 KB 0x4 = 64 KB 0x5 = 128 KB 0x6 = 256 KB 0x7 = 512 KB
11:0	Block Size	RW 0	Block Size NOTE: Block size must be a multiple of 4 bytes.

Table 118: Block Count Register
Offset: 0x06

Bits	Field	Type/ Init Val	Description
15:0	Block_count	RW 0	The Host controller decrements the block count after each block transfer 0x1 = 1 block ... 0xFFFF = 65535 blocks The current value of block count is reflected in the Current Block Count Register.

Table 119: Argument Low Register
Offset: 0x08

Bits	Field	Type/ Init Val	Description
15:0	Arg_l	RW 0	16 LSB of Command Argument This value is inserted into 48 bits command token bits[23:8].

Table 120: Argument High Register
Offset: 0x0A

Bits	Field	Type/ Init Val	Description
15:0	Arg_h	RW 0	16 MSB of Command Argument This value is inserted into 48 bits command token bits[39:24].

Table 121: Transfer Mode Register
Offset: 0x0C

Bits	Field	Type/ Init Val	Description
15:6	Reserved	RSVD	Reserved for future use
5	multi_blk_sel	RW 0	This bit should be set to 1 only when multiple blocks are to be transferred.
4	To_host_dir	RW 0	Data transfer direction select This bit defines the direction of the DAT line data transfer. The bit is set to 1 by the Host Driver to transfer data from the SD card to the SD host controller, and it is set to 0 for all other commands.
3	Reserved	RSVD	Reserved for future use

Table 121: Transfer Mode Register (Continued)
Offset: 0x0C

Bits	Field	Type/ Init Val	Description
2	Auto_cmd12_en	RW 0	Multiple block transfer for memory require CMD12 to stop the transaction. 1 = Host controller will automatically issue CMD12 when the last block transfer is completed 0 = Software is responsible for issuing cmd12 to stop the transfer and soft reset the host controller
1	blk_cnt_en	RW 0	This bit validates the value in the Block Count Register (Table 118 p. 104).
0	dma_en	RW 1	If PIO mode is required, this bit should be reset to 0.

Table 122: Command Register
Offset: 0x0E

Bits	Field	Type/ Init Val	Description
15:14	Reserved	RSVD	Reserved for future use
13:8	Cmd_index	RW 0	Command index These bits will be inserted into Command token bits[45:40]
7:6	cmd_type	RW 0	These bits specify the command type. 0x0 = Normal command 0x1 = Suspend command 0x2 = Resume command 0x3 = Abort command
5	Data_present	RW 0	1 = Indicates that data is present and will be transferred using the DAT line. 0 = commands using only CMD lines or commands with no data transfer but using busy signal on DAT[0] line (ex. CMD 38)
4	Cmd_index_chk_en	RW 0	Command index check enable 1 = Host controller checks the index field in the response to see if it has the same value as the command index. If it is not, it is reported as a Command Index Error.
3	Cmd_crc_chk_en	RW 0	Command CRC check enable 1 = Host controller checks the CRC field in the response. If an error is detected, it is reported as a command CRC error. The number of bits checked by the CRC field value changes according to the length of response
2	Reserved	RSVD	Reserved for future use

Table 122: Command Register (Continued)
Offset: 0x0E

Bits	Field	Type/ Init Val	Description
1:0	Resp_type	RW 0	Response type select 0 = No response 1 = response length is 136 bits 2 = response length is 48 bits 3 = response length is 48 bits and check busy after resp CRC field for R3 and R4 is expected to be all 1 bits. CRC check should be disabled for these response types.

Table 123: Response Register 0
Offset: 0x10

Bits	Field	Type/ Init Val	Description
15:0	Resp0	RO 0	This register contains bits[23:8] of response token.

Table 124: Response Register 1
Offset: 0x12

Bits	Field	Type/ Init Val	Description
15:0	Resp1	RO 0	This register contains bits[39:24] of response token.

Table 125: Response Register 2
Offset: 0x14

Bits	Field	Type/ Init Val	Description
15:0	Resp2	RO 0	For 48 bits response token, don't care For 136 bits response token, this register contains bits[55:40] of response token.

Table 126: Response Register 3
Offset: 0x16

Bits	Field	Type/ Init Val	Description
15:0	Resp3	RO 0	For 48 bits response token, don't care For 136 bits response token, this register contains bits[71:56] of response token.

Table 127: Response Register 4
Offset: 0x18

Bits	Field	Type/ Init Val	Description
15:0	Resp4	RO 0	For 48 bits response token, don't care For 136 bits response token, this register contains bits[87:72] of response token.

Table 128: Response Register 5
Offset: 0x1A

Bits	Field	Type/ Init Val	Description
15:0	Resp5	RO 0	For 48 bits response token, don't care For 136 bits response token, this register contains bits[103:88] of response token.

Table 129: Response Register 6
Offset: 0x1C

Bits	Field	Type/ Init Val	Description
15:0	Resp6	RO 0	For 48 bits response token, don't care For 136 bits response token, this register contains bits[119:104] of response token. For Auto CMD12 response, this register contains bits[23:8] of response token.

Table 130: Response Register 7
Offset: 0x1E

Bits	Field	Type/ Init Val	Description
15:0	Resp7	RO 0	For 48 bits response token, don't care For 136 bits response token, this register contains bits[127:120] of response token. For Auto CMD12 response, this register contains bits[39:24] of response token.

Table 131: Buffer Data Port0 Register
Offset: 0x20

Bits	Field	Type/ Init Val	Description
15:0	Cpu_data0	RW 0	16 LSB of the buffer

Table 132: Buffer Data Port1 Register
Offset: 0x22

Bits	Field	Type/ Init Val	Description
15:0	cpu_data1	RW 0	16 MSB of the buffer

Table 133: Present State Register 0
Offset: 0x24

Host driver can get status of the Host controller from this 16-bit

Bits	Field	Type/ Init Val	Description
15:12	Reserved	RSVD	Reserved for future use
11	buffer_rd_en	RO 0	This bit changes from 0x0 to 0x1 when block data is ready in the buffer. This bit changes from 0x1 to 0x0 when all the block data is read from the buffer.
10	buffer_wr_en	RO 1	This bit changes from 0x0 to 0x1 when block data can be written to the buffer. So if this bit is set to 0x1, the entire block can be written to the buffer. This bit changes from 0x1 to 0x0 when all the block data is written to the buffer.
9	rx_active	RO 0	Indicates read transfer is active 1 = Set: - after the end bit of the read command - when writing 1 to <Cont_req> field in the Block Gap Control Register (Table 136 p. 112) to restart a read transfer 0 = Set: - When the last data block (as specified by block length) is transferred to the system. Transfer complete status is set to 1 if this bit is changed from 1 to 0. - When all valid data blocks have been transferred to the system and no current block transfers are being sent as a result of the <Stop_at_block_gap_req> field in the Block Gap Control Register (Table 136 p. 112) being set to 1. The <Stop_at_block_gap_req> status is set to 1 if this bit is changed from 1 to 0.

Table 133: Present State Register 0 (Continued)

Offset: 0x24

Host driver can get status of the Host controller from this 16-bit

Bits	Field	Type/ Init Val	Description
8	tx_active	RO 0	Indicates write transfer is active. If this bit is 0, it means no valid write data exists in the Host controller. 1 = Set: - after the end bit of the write command - when writing a 1 to <Cont_req> field in the Block Gap Control Register (Table 136 p. 112) to restart a write transfer. This bit is cleared in the following cases: - After getting the CRC status of the last data block as specified by the transfer count (single and multiple) - After getting the CRC status of any block where data transmission is about to be stopped by a <Stop_at_block_gap_req> field in the Block Gap Control Register (Table 136 p. 112). A transfer complete interrupt is generated when all write data is out. Besides, during a write transaction, a Block Gap Event interrupt is generated when this bit is changed to 0, as result of the <Stop_at_block_gap_req> being set. This status is useful for the Host driver in determining when to issue commands during write busy.
7:3	Reserved	RSVD	Reserved for future use
2	dat_active	RO 0	This bit provides the status of the data line. 1 = Data line is in use.
1	cmd_inhibit_dat	RO 0	This bit provides the status for the driver whether it can issue a data command. 1 = It cannot issue a command that uses the data line.
0	Cmd_inhibit_cmd	RO 0	If this bit is 0, it indicates the CMD line is not in use, and the Host controller can issue a command using CMD line. This bit is set after the command register is written. This bit is cleared when the command response is received. Even if the cmd_inhibit_dat is set to 1, commands using only the CMD line can be issued if this bit is 0. Changing from 1 to 0 generates a command complete interrupt in the Normal Interrupt Status Register (Table 139 p. 114). If the Host controller cannot issue the command because of a command conflict err, this bit remains 1, and the command complete is not set.

Table 134: Present State Register 1

Offset: 0x26

Bits	Field	Type/ Init Val	Description
15:9	Reserved	RSVD	Reserved for future use

Table 134: Present State Register 1 (Continued)
Offset: 0x26

Bits	Field	Type/ Init Val	Description
8	Cmd_level	RO 1	CMD line Signal Level This status is used to check the CMD line level to recover from errors and for debugging.
7:4	Dat_level	RO 0xF	DAT[3:0] Line signal level This status is used to check the DAT line level to recover from errors and for debugging. This is especially useful in detecting the busy signal level from DAT[0].
3	write_prot	RO 0	This bit reflects the position of the write_protect latch on the SD card. This bit should be ignored if there is no such feature being provided by the card in use.
2	card_det	RO 0	Reflects the value of pin1 dat[3] line. This bit is used only for testing. 0 = Card not detected 1 = Card detected
1	card_stable	RO 0	This bit is also used for testing. This bit indicates the debounced value of the card present condition. 0 = Card unstable 1 = Card stable
0	card_inserted	RO 0	Indicates the presence of a SD card 0 = Card not inserted 1 = Card inserted

Table 135: Host Control Register
Offset: 0x28

Bits	Field	Type/ Init Val	Description
15:12	Reserved	RSVD	Reserved for future use
11:9	sd_bus_vlt	RW 0x6	These bits reflect the voltage at operating conditions. 0x7 = 3.3V 0x6 = 3.0V 0x5 = 1.8V 0x0 to 0x4 = Reserved
8	sd_bus_power	RW 0	This bit controls the power going out to the SD card. It will be cleared if one of the following occurs: the sd_bus_vlt and the voltage support in the Capabilities Register (Table 146 p. 120) do not match or if a card removal state was detected.
7:3	Reserved	RSVD	Reserved for future use
2	Hi_speed_en	RW 0	Extend Data Output Enable 0 = normal 1 = CMD and DATA are driven from rising edge of clock

Table 135: Host Control Register (Continued)
Offset: 0x28

Bits	Field	Type/ Init Val	Description
1	Data_width	RW 0	1 = 4-bit data mode 0 = 1-bit data mode, using only DAT[0]
0	led_ctrl	RW 0	1 = LED on 0 = LED off

Table 136: Block Gap Control Register
Offset: 0x2A

Bits	Field	Type/ Init Val	Description
15:11	Reserved	RSVD	Reserved for future use
10	w_removal	RW 0	1 = Enable wakeup event on card removal detection 0 = No wakeup event
9	w_insertion	RW 0	1 = Enable wakeup event on card insertion detection 0 = No wakeup event
8	w_card_int	RW 0	1 = Enable wakeup event on card interrupt detection 0 = No wakeup event
7:4	Reserved	RSVD	Reserved for future use
3	int_blk_gap	RW 0	This bit is valid only for the 4-bit mode. 1 = Enables interrupt detection at block gap for multiple block transfers
2	Rd_wait_ctl	RW 0	If the card supports read wait, set this bit to enable use of the read wait protocol to stop read data using the DAT[2] line by Host hardware. Otherwise, Host controller has to stop SD clock to hold read data. When the Host driver detects a card insertion, it will set this bit according to the CCCR of the SDIO card. NOTE: This bit is looked at only at block gap. Within a block, hardware will stall the clock to stop read data if the host cannot accept any more data because of FIFO full, etc. NOTE: When this bit is cleared by software, operation continues. During read wait, software can issue a different cmd for different operation as long as it does not require DATA lines. When it wants to continue the waiting operation, software needs to write 0 to this register.

Table 136: Block Gap Control Register (Continued)
Offset: 0x2A

Bits	Field	Type/ Init Val	Description
1	Cont_req	RWAC 0	Continue Request This bit is used to restart a transaction which was stopped using the <Stop_at_block_gap_req> . To cancel stop at the block gap, set <Stop_at_block_gap_req> to 0 and set this bit to 1 to restart the transfer. Host controller automatically clears this bit in either of the following cases: - In the case of read transaction, the DAT Line Active changes from 0 to 1 as a read transaction restarts - In case of write transaction, the Write Transfer Active changes from 0 to 1 as the write transaction restarts Therefore, it is not necessary for the Host driver to set this bit to 0. If <Stop_at_block_gap_req> is set to 1, any write to this bit is ignored.
0	Stop_at_block_gap_req	RW 0	Stop At block gap request This is used to stop executing a transaction at the next block gap for both DMA and non-DMA transfers. Until the transfer complete is set to 1, indicating a transfer completion, the Host driver will leave this bit set to 1. Clearing both the this bit and <Cont_req> will not cause the transaction to restart. Read Wait is used to stop the read transaction at the block gap. The Host controller will stop the clock At Block Gap Request for write transfer, but for read transfer, it will stop the clock if <Rd_wait_ctl> is 0. Otherwise, the host controller issues a Read Wait command to stop read data.

Table 137: Clock Control Register
Offset: 0x2C

Bits	Field	Type/ Init Val	Description
15:8	sd_freq_sel	RW 0x01	This register selects the SD_CLK frequency. 0x00 = Use crystal clock 0x01 = Divide by 2 0x02 = Divide by 4 ... 0x80 = Divide by 256
7:3	Reserved	RSVD	Reserved for future use
2	sd_clk_en	RW 0	This bit controls the SD_CLK to the card. So before using the card, this bit should be set during the init phase.
1	int_clk_stable	RO 0	This bit is set to 1, once the controller detects that the internal clock is stable after setting of <int_clk_en> .
0	int_clk_en	RW 0	This bit controls the SD_CLK of which the internal logic works on. 1 = enable clock 0 = disable

Table 138: Timeout Control/Software Reset Register
Offset: 0x2E

Bits	Field	Type/ Init Val	Description
15:11	Reserved	RSVD	Reserved for future use
10	sw_rst_dat	RWAC 0	Soft reset for the data part of logic
9	sw_rst_cmd	RWAC 0	Soft reset for the cmd part of logic
8	sw_rst_all	RWAC 0	Software Reset For All This reset affects the status, state machine, and FIFOs synchronously.
7:4	Reserved	RSVD	Reserved for future use
3:0	Timeout_value	RW 0xE	Determines the interval by which DAT line timeouts are detected. This timeout is initiated in the following cases: For read transaction, waiting for data from cards. This is referred to as N_{AC} timing value in the SD specification, which specifies the maximum timing from read command to read data (card data access time). For write transaction, waiting for data from IMB slave, IMB Master, or CPU. 0x0 = $SD_CLK \times 2^{13}$ 0x1 = $SD_CLK \times 2^{14}$... 0xE = $SD_CLK \times 2^{27}$ 0xF = Reserved For other transactions, there are fixed timeouts defined as follows (unit in TIMEOUT_CLK cycles) On the card: $N_{CR} = 64$, maximum timing value from command to response. $N_{ID} = 64$ (5 in specification), maximum timing value from command to OCR response On the Host: $N_{RC} = 8$, minimum timing value from response to next command $N_{CC} = 8$, minimum timing value from command to next command. $N_{WR} = 2$, minimum timing value from data CRC status (from card in write transaction) to next write data in multiple write blocks $N_{ST} = 2$, minimum timing from STOP command to end of write data Refer to the SD specification for more information on these fixed values.

Table 139: Normal Interrupt Status Register

Offset: 0x30

Bits	Field	Type/ Init Val	Description
15	Err_int	RO 0	Error interrupt If any of bits in the Error Interrupt Status Register (Table 140 p. 115) are set, then this bit is set.
14:9	Reserved	RSVD	Reserved for future use
8	Card_int	RW1C 0	Card interrupt 1 = Host controller detects an interrupt from the Card
7	card_rem_int	RW1C 0	This bit is set when a card removal event is detected.
6	card_ins_int	RW1C 0	This bit is set when a card insertion event is detected.
5	Rx_rdy	RW1C 0	This status is set if the <buffer_rd_en> field in the Present State Register 0 (Table 133 p. 108) changes from 0x0 to 0x1.
4	Tx_rdy	RW1C 1	This status is set if the <buffer_wr_en> field in the Present State Register 0 (Table 133 p. 108) changes from 0x0 to 0x1.
3	Dma_int	RW1C 0	DMA interrupt This status is set if the Host Controller detects DMA crossing over the host_dma_buf_bndry as specified in Block Size Register (Table 117 p. 103).
2	Block_gap_evt	RW1C 0	Block Gap Event If the <Stop_at_block_gap_req> field in the Block Gap Control Register (Table 136 p. 112) is set, this bit is set when both a read/write transaction is stopped at a block gap. If the <Stop_at_block_gap_req> field is not set to 1, this bit is not set to 1.
1	Xfer_complete	RW1C 0	Transfer Complete This bit is set when a read/write transaction is completed For read transaction, this bit is set at the falling edge of Read Transfer Active Status. There are two cases in which this occurs: - data transfer is completed as specified by data length. - data stopped at the block gap and completed data transfer by setting the <Stop_at_block_gap_req> field in the Block Gap Control Register (Table 136 p. 112) field. For write transaction, this bit is set at the falling edge of the DAT Line Active status. There are two cases in which this occurs: - data transfer is completed as specified by data length and the busy signal released. - data stopped at the block gap and completed data transfer by setting the <Stop_at_block_gap_req> field

Table 139: Normal Interrupt Status Register (Continued)
Offset: 0x30

Bits	Field	Type/ Init Val	Description
0	Cmd_complete	RW1C 0	Command Complete This bit is set when the end bit of the command response (Except Auto CMD12) is received. Note that Command Timeout Error has higher priority than Command complete.

Table 140: Error Interrupt Status Register
Offset: 0x32

Bits	Field	Type/ Init Val	Description
15	CRC status err	RW1C 0	CRC status returned from card is not good in write transaction.
14	Crc_start_bit_err	RW1C 0	CRC status s start bit is not at expected logic level in write transaction
13	Crc_end_bit_err	RW1C 0	CRC status s end bit is not at expected logic level in write transaction
12	Resp_t_bit_err	RW1C 0	Response Transmission bit error
11:9	Reserved	RSVD	Reserved for future use
8	Auto_cmd12_err	RW1C 0	Auto CMD12 Error Occurs when detecting that one of the bits in Auto CMD12 Error Status Register (Table 145 p. 120) has changed from 0 to 1.
7	cur_limit_err	RW1C 0	This feature is not supported and this bit will always be read as 0.
6	Rd_Data_end_bit_err	RW1C 0	ReadData End Bit Error 1 = 0 detected at the end bit position of read data which uses the DAT line or at the end bit position of the CRC status
5	Rd_Data_crc_err	RW1C 0	Read Data CRC error 1 = read data which uses the DAT line transferred or Write CRC status having a value other than 010 detected
4	Data_timeout_err	RW1C 0	Data timeout Error This bit is set when one of the following is detected: • Busy timeout after Write CRC status • Write CRC status timeout • Read Data timeout
3	Cmd_index_err	RW1C 0	Command Index Error This bit is set when a command index error occurs in the command response

Table 140: Error Interrupt Status Register (Continued)
Offset: 0x32

Bits	Field	Type/ Init Val	Description
2	Cmd_end_bit_err	RW1C 0	Command End Bit Error This bit is set when detecting that the end bit of a command response is 0.
1	Cmd_crc_err	RW1C 0	Command CRC Error This bit is set in two cases: - A CRC error is detected in the command response - The Host controller detects a CMD line conflict by monitoring the CMD line when a command is issued. The Host controller will abort the command (stops driving CMD line). The <Cmd_timeout_err> will also be set to 1 to distinguish CMD line conflict.
0	Cmd_timeout_err	RW1C 0	Command Timeout Error This bit is set when no response is returned within 64 SD_CLK cycles from the end bit of the command.

Table 141: Normal Interrupt Status Enable Register
Offset: 0x34

Bits	Field	Type/ Init Val	Description
15:9	Reserved	RSVD	Reserved for future use
8	Card_int_en	RW 0	Card interrupt enable 0 = disabled 1 = enabled
7	card_rem_en	RW 0	Card removal status enable
6	card_ins_en	RW 0	Card insertion status enable
5	rd_rdy_en	RW 0	Buffer Read Ready Enable 0 = disabled 1 = enabled
4	tx_rdy_en	RW 0	Buffer Write Ready Enable 0 = disabled 1 = enabled
3	Dma_int_en	RW 0	DMA interrupt Enable 0 = disabled 1 = enabled
2	Block_gap_evt_en	RW 0	Block Gap Event Enable 0 = disabled 1 = enabled
1	Xfer_complete_en	RW 0	Transfer Complete Enable 0 = disabled 1 = enabled

Table 141: Normal Interrupt Status Enable Register (Continued)
Offset: 0x34

Bits	Field	Type/ Init Val	Description
0	Cmd_complete_en	RW 0	Command Complete Enable 0 = disabled 1 = enabled

Table 142: Error Interrupt Status Enable Register
Offset: 0x36

Bits	Field	Type/ Init Val	Description
15	CRC_status_err_en	RW 0	CRC_status_err Enable 0 = disabled 1 = enabled
14	Crc_start_err_en	RW 0	CRC status start bit err Enable 0 = disabled 1 = enabled
13	Crc_end_err_en	RW 0	CRC status end bit err Enable 0 = disabled 1 = enabled
12	Resp_t_bit_err_en	RW 0	Response Transmission bit error Enable 0 = disabled 1 = enabled
11:9	Reserved	RSVD	Reserved for future use
8	Auto_cmd12_err_en	RW 0	Auto CMD12 Error Enable 0 = disabled 1 = enabled
7	cur_lim_err_en	RW 0	Current limit error enable
6	Rd_Data_end_bit_err_en	RW 0	Data End Bit Error Enable 0 = disabled 1 = enabled
5	Rd_data_crc_err_en	RW 0	Data CRC error Enable 0 = disabled 1 = enabled
4	Data_timeout_err_en	RW 0	Data Timeout Error Enable 0 = disabled 1 = enabled
3	Cmd_index_err_en	RW 0	Command Index Error Enable 0 = disabled 1 = enabled
2	Cmd_end_bit_err_en	RW 0	Command End Bit Error Enable 0 = disabled 1 = enabled

Table 142: Error Interrupt Status Enable Register (Continued)
Offset: 0x36

Bits	Field	Type/ Init Val	Description
1	Cmd_crc_err_en	RW 0	Command CRC Error Enable 0 = disabled 1 = enabled
0	Cmd_timeout_err_en	RW 0	Command Timeout Error Enable 0 = disabled 1 = enabled

Table 143: Normal Interrupt Status Interrupt Enable Register
Offset: 0x38

Bits	Field	Type/ Init Val	Description
15:9	Reserved	RSVD	Reserved for future use
8	Card_int_int_en	RW 0	Card interrupt Interrupt Enable 0 = disabled 1 = enabled
7	card_rem_int_en	RW 0	Card removal interrupt enable
6	card_ins_int_en	RW 0	Card insertion interrupt enable
5	rx_rdy_int_en	RW 0	Buffer Read Ready Interrupt Enable 0 = disabled 1 = enabled
4	tx_rdy_int_en	RW 0	Buffer Write Ready Interrupt Enable 0 = disabled 1 = enabled
3	Dma_int_int_en	RW 0	DMA interrupt Interrupt Enable 0 = disabled 1 = enabled
2	Block_gap_evt_int_en	RW 0	Block Gap Event Interrupt Enable 0 = disabled 1 = enabled
1	Xfer_complete_int_en	RW 0	Transfer Complete Interrupt Enable 0 = disabled 1 = enabled
0	Cmd_complete_int_en	RW 0	Command Complete Interrupt Enable 0 = disabled 1 = enabled

Table 144: Error Interrupt Status Interrupt Enable Register
Offset: 0x3A

Bits	Field	Type/ Init Val	Description
15	CRC status err_int_en	RW 0	CRC status err interrupt Enable 0 = disabled 1 = enabled
14	Crc_start_bit_err_ int_en	RW 0	CRC status start bit err interrupt Enable 0 = disabled 1 = enabled
13	Crc_end_bit_err_i nt_en	RW 0	CRC status end bit err interrupt Enable 0 = disabled 1 = enabled
12	Resp_t_bit_err_in t_en	RW 0	Response Transmission bit error interrupt Enable 0 = disabled 1 = enabled
11:9	Reserved	RSVD	Reserved for future use
8	Auto_cmd12_err_ int_en	RW 0	Auto CMD12 Error Interrupt Enable 0 = disabled 1 = enabled
7	cur_lim_err_int_e n	RW 0	Current limit error interrupt enable.
6	Rd_Data_end_bit_ _err_int_en	RW 0	Data End Bit Error Interrupt Enable 0 = disabled 1 = enabled
5	Rd_Data_crc_err_ _int_en	RW 0	Data CRC error Interrupt Enable 0 = disabled 1 = enabled
4	Data_timeout_err_ _int_en	RW 0	Data Timeout Error Interrupt Enable 0 = disabled 1 = enabled
3	Cmd_index_err_i nt_en	RW 0	Command Index Error Interrupt Enable 0 = disabled 1 = enabled
2	Cmd_end_bit_err_ _int_en	RW 0	Command End Bit Interrupt Error Enable 0 = disabled 1 = enabled
1	Cmd_crc_err_int_ en	RW 0	Command CRC Error Interrupt Enable 0 = disabled 1 = enabled
0	Cmd_timeout_err_ _int_en	RW 0	Command Timeout Error Interrupt Enable 0 = disabled 1 = enabled

Table 145: Auto CMD12 Error Status Register
Offset: 0x3C

Bits	Field	Type/ Init Val	Description
15:8	Reserved	RSVD	Reserved for future use
7	cmd_not_issued	ROC 0	Command not issued because of auto_cmd12 error.
6:5	Reserved	RSVD	Reserved for future use
4	Auto_cmd12_ind ex_err	RW1C 00	Occurs if the command index error occurs in response to a command 0 = disabled 1 = enabled
3	Auto_cmd12_end _bit_err	RW1C 00	Occurs when detecting that the end bit of command response is 0 0 = disabled 1 = enabled
2	Auto_cmd12_crc _err	RW1C 0	Occurs when detecting CRC error in the command response 0 = disabled 1 = enabled
1	Auto_cmd12_tim eout_err	RW1C 0	Occurs if no response is returned within 64 SD_CLK cycles from the end bit of command. 0 = disabled 1 = enabled
0	Auto_cmd12_not _exe	RW1C 0	Occurs when host controller cannot issue Auto cmd12 to stop multiple block data transfer due to some errors. 0 = disabled 1 = enabled

Table 146: Capabilities Register
Offset: 0x40

Bits	Field	Type/ Init Val	Description
15:14	Reserved	RSVD	Reserved for future use
13:8	base_freq	RW 0x30	The base clock frequency for SD_CLK
7	timeout_unit	RW 1	The unit of base clock used to detect timeouts. 1 = MHz 0 = kHz
6	Reserved	RSVD	Reserved for future use
5:0	timeout_freq	RW 0x30	This value indicates the base clock frequency used to detect timeouts.

Table 147: Capabilities Register 1

Offset: 0x42

NOTE: The values in this register are initialized by hardware. Use caution when writing to these bits.

Bits	Field	Type/ Init Val	Description
15:11	Reserved	RSVD	Reserved for future use
10	vlt_18	RW 0	1.8V support 1 = 1.8V supported 0 = 1.8V not supported
9	vlt_30	RW 1	3.0V support 1 = 3.0V supported 0 = 3.0V not supported.
8	vlt_33	RW 1	3.3V support 1 = 3.3V supported 0 = 3.3V not supported
7	sus_res_support	RW 1	Suspend/Resume support 1 = Supported 0 = Not supported.
6	dma_support	RW 1	DMA Support 1 = Supported 0 = Not supported
5	Hi_spd_support	RW 1	High Speed support 1 = Supported 0 = Not supported
4:2	Reserved	RSVD	Reserved for future use
1:0	max_blk_len	RW 00	Maximum block length supported by controller 0x0 = 512 bytes 0x1 = 1024 bytes 0x2 = 2048 bytes 0x3 = Reserved

Table 148: Capabilities Register 2

Offset: 0x44

Bits	Field	Type/ Init Val	Description
15:0	Reserved	RSVD	Reserved for future use

Table 149: Capabilities Register 3

Offset: 0x46

Bits	Field	Type/ Init Val	Description
15:0	Reserved	RSVD	Reserved for future use

Table 150: Maximum Current Register 0

Offset: 0x48

NOTE: The values in this register are initialized by hardware. Use caution when writing to these bits.

Bits	Field	Type/ Init Val	Description
15:8	max_cur_30	RW 0	Maximum current for 3.0V 0x0 = Get information via another method. 0x1 = 4 ma 0x2 = 8 ma ... 0xF = 1020 ma
7:0	max_cur_33	RW 0	Maximum current for 3.3V 0x0 = Get information via another method. 0x1 = 4 ma 0x2 = 8 ma ... 0xF = 1020 ma

Table 151: Maximum Current Register 1

Offset: 0x4A

Bits	Field	Type/ Init Val	Description
15:8	Reserved	RSVD	Reserved for future use
7:0	max_cur_18	RW 0	Maximum current for 3.3V 0 = Get information via another method. 1 = 4ma 2 = 8ma ... 255 = 1020ma

Table 152: Maximum Current Register 2

Offset: 0x4C

Bits	Field	Type/ Init Val	Description
15:0	Reserved	RSVD	Reserved for future use

Table 153: Maximum Current Register 3

Offset: 0x4E

Bits	Field	Type/ Init Val	Description
15:0	Reserved	RSVD	Reserved for future use

Table 154: I/O Control Register
Offset: 0x60

Bits	Field	Type/ Init Val	Description
15	data3_iddq_n	RW 1	Data 3 Pull Up/Pull Down 0 = Disable 1 = Enable
14:0	Reserved	RSVD	Reserved for future use

Table 155: Command 1 Register
Offset: 0x6A

Bits	Field	Type/ Init Val	Description
15:3	Reserved	RSVD	Reserved for future use
2	crc16_chk_en	RW 0	Enable data crc16 check 0 = Data crc16 check disabled 1 = Data crc16 check enabled
1:0	Reserved	RSVD	Reserved for future use

Table 156: SD Drive Strength Register
Offset: 0x7C

Bits	Field	Type/ Init Val	Description
15:11	Reserved	RSVD	Reserved for future use
10:8	SD_Drive_Strengh_P	RW 0x7	P Level Drive Strength Value
7:3	Reserved	RSVD	Reserved for future use
2:0	SD_Drive_Strengh_N	RW 0x7	N Level Drive Strength Value

Table 157: Slot Interrupt Status Register
Offset: 0xFC

Bits	Field	Type/ Init Val	Description
15:1	Reserved	RSVD	Reserved for future use
0	slot_int	RO 0	Interrupt line

Table 158: Host Control Version Register
Offset: 0xFE
NOTE: The values in this register are initialized by hardware. Use caution when writing to these bits.

Bits	Field	Type/ Init Val	Description
15:8	vendor_ver	RW 0	Marvell specific version number
7:0	sd_ver	RW 0x0	SD Host specification number 0 = Supports version 1.0 All other values are reserved.

3.6 CMOS Camera Interface Controller

3.6.1 Register Map

Table 159: CMOS Camera Interface Controller Register Map

Register Name	Offset	Table and Page
Y0-Base Address Register	0x00	Table 160, p. 125
Y1-Base Address Register	0x04	Table 161, p. 125
Y2-Base Address Register	0x08	Table 162, p. 125
U0-Base Address Register	0x0C	Table 163, p. 126
U1-Base Address Register	0x10	Table 164, p. 126
U2-Base Address Register	0x14	Table 165, p. 126
V0-Base Address Register	0x18	Table 166, p. 126
V1-Base Address Register	0x1C	Table 167, p. 127
V2-Base Address Register	0x20	Table 168, p. 127
Image Pitch Register	0x24	Table 169, p. 127
IRQ RAW Status Register	0x28	Table 170, p. 127
IRQ Mask Register	0x2C	Table 171, p. 128
IRQ Status Register	0x30	Table 172, p. 129
Image Size Register	0x34	Table 173, p. 131
Image Offset Register	0x38	Table 174, p. 131
Control 0 Register	0x3C	Table 175, p. 132
Control 1 Register	0x40	Table 176, p. 135
Reserved	0x44 to 0x84	--
Clock Control Register	0x88	Table 177, p. 136
SRAM TC0 Register (Test Only)	0x8C	Table 178, p. 137
SRAM TC1 Register (Test Only)	0x90	Table 179, p. 137
Reserved	0x88 to 0xB0	--
General Purpose (GPR) Register	0xB4	Table 180, p. 137
TWSI Control 0 Register	0xB8	Table 181, p. 138

Table 159: CMOS Camera Interface Controller Register Map (Continued)

Register Name	Offset	Table and Page
TWSI Control 1 Register	0xBC	Table 182, p. 139
Reserved	0xC0	--

3.6.2 Register Descriptions



Note

- When the output format is RGB or YCbCr packed, only the following registers must be programmed: [Y0-Base Address Register](#), [Y1-Base Address Register](#), and [Y2-Base Address Register](#).
- When the output format is YCbCr planar, [Y0-Base Address Register](#) through [Y2-Base Address Register](#) must be programmed.

Table 160: Y0-Base Address Register

Offset: 0x00

Bits	Field	Type/ Init Val	Description
31:2	YBASE0	RW 0x0	Y0 Base Address bit [31:2]
1:0	YBASE0	RO 0x0	Y0 Base Address bit [1:0]

Table 161: Y1-Base Address Register

Offset: 0x04

Bits	Field	Type/ Init Val	Description
31:2	YBASE1	RW 0x0	Y1 Base Address bit [31:2]
1:0	YBASE1	RO 0x0	Y1 Base Address bit [1:0]

Table 162: Y2-Base Address Register

Offset: 0x08

Bits	Field	Type/ Init Val	Description
31:2	YBASE2	RW 0x0	Y2 Base Address bit [31:2]
1:0	YBASE2	RO 0x0	Y2 Base Address bit [1:0]

Table 163: U0-Base Address Register

Offset: 0x0C

Bits	Field	Type/ Init Val	Description
31:2	UBASE0	RW 0x0	U0 Base Address bit [31:2]
1:0	UBASE0	RO 0x0	U0 Base Address bit [1:0]

Table 164: U1-Base Address Register

Offset: 0x10

Bits	Field	Type/ Init Val	Description
31:2	UBASE1	RW 0x0	U1 Base Address for bit [31:2]
1:0	UBASE1	RO 0x0	U1 Base Address for bit [1:0]

Table 165: U2-Base Address Register

Offset: 0x14

Bits	Field	Type/ Init Val	Description
31:2	UBASE2	RW 0x0	U2 Base Address bit [31:2]
1:0	UBASE2	RO 0x0	U2 Base Address bit [1:0]

Table 166: V0-Base Address Register

Offset: 0x18

Bits	Field	Type/ Init Val	Description
31:2	VBASE0	RW 0x0	V0 Base Address bit [31:2]
1:0	VBASE0	RO 0x0	V0 Base Address bit [1:0]

Table 167: V1-Base Address Register
Offset: 0x1C

Bits	Field	Type/ Init Val	Description
31:2	VBASE1	RW 0x0	V1 Base Address bit [31:2]
1:0	VBASE1	RO 0x0	V1 Base Address bit [1:0]

Table 168: V2-Base Address Register
Offset: 0x20

Bits	Field	Type/ Init Val	Description
31:2	VBASE2	RW 0x0	V2 Base Address bit [31:2]
1:0	VBASE2	RO 0x0	V2 Base Address bit [1:0]

Table 169: Image Pitch Register
Offset: 0x24

Bits	Field	Type/ Init Val	Description
31:30	Reserved	RO 0x0	Reserved
29:18	UVPITCH	RW(0x0	UV Pitch (distance in unit of 32-bit between two vertically adjacent pixels). Must be programmed when output format is YUV Planar.
17:14	Reserved	RO(0x0	Reserved
13:2	YPITCH	RW 0x0	Y Pitch (distance in unit of 32-bit between two vertically adjacent pixels).
1:0	Reserved	RO 0x0	Reserved

Table 170: IRQ RAW Status Register
Offset: 0x28

Bits	Field	Type/ Init Val	Description
31:19	Reserved	RO 0x0	Reserved

Table 170: IRQ RAW Status Register (Continued)
Offset: 0x28

Bits	Field	Type/ Init Val	Description
18	TWSIEIRQR	RO 0x0	TWSI Error IRQ 0 = No interrupt (Default) 1 = TWSI Error
17	TWSIRIRQR	RO 0x0	TWSI Read IRQ 0 = No interrupt (Default) 1 = Read data from Sensor is available
16	TWSIWIRQR	RO 0x0	TWSI Write IRQ 0 = No interrupt (Default) 1 = Write to Sensor is done
15:7	Reserved	RO 0x0	Reserved
6	FIFOFULLIRQR	RO 0x0	FIFO Full (Overflow) IRQ 0 = No interrupt (Default) 1 = FIFO Overflow occurs
5	SOF2IRQR	RO 0x0	Start of Frame 2 IRQ 0 = No interrupt (Default) 1 = Starting to write frame #2
4	SOF1IRQR	RO 0x0	Start of Frame 1 IRQ 0 = No interrupt (Default) 1 = Starting to write frame #1
3	SOF0IRQR	RO 0x0	Start of Frame 0 IRQ 0 = No interrupt (Default) 1 = Starting to write frame #0
2	EOF2IRQR	RO 0x0	End of Frame 2 IRQ 0 = No interrupt (Default) 1 = Done writing complete frame #2
1	EOF1IRQR	RO 0x0	End of Frame 1 IRQ 0 = No interrupt (Default) 1 = Done writing complete frame #1
0	EOF0IRQR	RO 0x0	End of Frame 0 IRQ 0 = No interrupt (Default) 1 = Done writing complete frame #0

Table 171: IRQ Mask Register
Offset: 0x2C

Bits	Field	Type/ Init Val	Description
31:19	Reserved	RW 0x0	Reserved

Table 171: IRQ Mask Register (Continued)
Offset: 0x2C

Bits	Field	Type/ Init Val	Description
18	TWSIEIRQM	RW 0x0	TWSI Error IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
17	TWSIRIRQM	RW 0x0	TWSI Read IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
16	TWSIWIRQM	RW 0x0	TWSI Write IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
15:7	Reserved	RW 0x0	Reserved
6	FIFOFULLIRQM	RW 0x0	FIFO Full (Overflow) IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
5	SOF2IRQM	RW 0x0	Start of Frame 2 IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
4	SOF1IRQM	RW 0x0	Start of Frame 1 IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
3	SOF0IRQM	RW 0x0	Start of Frame 0 IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
2	EOF2IRQM	RW 0x0	End of Frame 2 IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
1	EOF1IRQM	RW 0x0	End of Frame 1 IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt
0	EOF0IRQM	RW 0x0	End of Frame 0 IRQ 0 = Disable Interrupt (Default) 1 = Enable Interrupt

Table 172: IRQ Status Register
Offset: 0x30

Bits	Field	Type/ Init Val	Description
31:19	Reserved	RO 0x0	Reserved

Table 172: IRQ Status Register (Continued)
Offset: 0x30

Bits	Field	Type/ Init Val	Description
18	TWSIEIRQS	RO 0x0	TWSI Error IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
17	TWSIRIRQS	RO 0x0	TWSI Read IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
16	TWSIWIRQS	RO 0x0	TWSI Write IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
15:7	Reserved	RO 0x0	Reserved
6	FIFOFULLIRQS	RO 0x0	FIFO Full (Overflow) IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
5	SOF2IRQS	RO 0x0	Start of Frame 2 IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
4	SOF1IRQS	RO 0x0	Start of Frame 1 IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
3	SOF0IRQS	RO 0x0	Start of Frame 0 IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
2	EOF2IRQS	RO 0x0	End of Frame 2 IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt

Table 172: IRQ Status Register (Continued)
Offset: 0x30

Bits	Field	Type/ Init Val	Description
1	EOF1IRQS	RO 0x0	End of Frame 1 IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt
0	EOF0IRQS	RO 0x0	End of Frame 0 IRQ read 0 = No interrupt read 1 = Interrupt is asserted write 0 = No effect write 1 = Clear interrupt

Table 173: Image Size Register
Offset: 0x34

Bits	Field	Type/ Init Val	Description
31:29	Reserved	RO 0x0	Reserved
28:16	VSIZE	RW 0x0	Image length in scanline
15:14	Reserved	RO 0x0	Reserved
13:0	HSIZE	RW 0x0	Image width in PIXCLK unit

Table 174: Image Offset Register
Offset: 0x38

Bits	Field	Type/ Init Val	Description
31:29	Reserved	RO 0x0	Reserved
28:16	VOFF	RW 0x0	Image line offset in scanline Starts capturing external CMOS sensor image at VOFF line. 0 = CCIC starts capturing at line #0 for every frame
15:14	Reserved	RO 0x0	Reserved
13:0	HOFF	RW 0x0	Image pixel offset in PIXCLK Starts capturing external CMOS sensor image at HOFF pixel. 0 = CCIC starts capturing at pixel #0 for every line in the frame.

Table 175: Control 0 Register
Offset: 0x3C

Bits	Field	Type/ Init Val	Description
31:30	SIFMODE	RW 0x0	Sensor Interface Mode 00 = Master mode with hsync/vsync (Default) 01 = Master mode without hsync/vsync (BT 656) Others = Reserved
29:27	DSCALE	RW 0x0	Down Scaler 000 = Disable (Default) 001 = 1:2 scale down Others = Reserved Down Scale is not supported when <DOUTFMT> = 00 (YCbCr) and <YUVOUTFMT> = 100 (YCbCr 422).
26	VCLKPOL	RW 0x0	VCLK Polarity with respect to data sampling 0 = Sample CMOS Sensor Data at rising-edge of VCLK (Default) 1 = Sample CMOS Sensor Data at falling-edge of VCLK
25	VPOL	RW 0x0	CMOS Sensor VSYNC Polarity 0 = Active high (Default) 1 = Active low
24	HPOL	RW 0x0	CMOS Sensor HSYNC Polarity 0 = Active high (Default) 1 = Active low
23:18	Reserved	RSVD	Reserved for future use
17:16	YUVENDFMT	RW 0x0	YCbCr Endianness Format when <YUVOUTFMT> = 101, this bit defines the Endianness of the external CMOS sensor's output (CCIC's input). {MSB:LSB}: 00 = Y1CbY0Cr (Default) 01 = Y1CrY0Cb 10 = CrY1CbY0 11 = CbY1CrY0 when <YUVOUTFMT> = 100, this bit controls byte swapping before data is written to memory: 00 = no byte swapping 01 = swap 1st and 3rd byte 10 = swap 2nd and 4th byte 11 = swap 1st and 3rd byte, 2nd and 4th byte
15:13	YUVOUTFMT	RW 0x0	YCbCr Output Format 000 = 422 8 bpp planar (Default) 100 = 422 8 bpp packed 101 = 420 8 bpp planar Others = Reserved

Table 175: Control 0 Register (Continued)
Offset: 0x3C

Bits	Field	Type/ Init Val	Description
12	RGBOUTEND	RW 0x0	RGB Output Endianness 0 = MSB: Blue, LSB: Red (Default) 1 = MSB: Red, LSB: Blue
11:9	RGBINOUTFMT	RW 0x0	RGB Input and Output Format (when <DOUTFMT> = RGB) Defines the CCIC's input (CMOS Sensor's output) and the CCIC's output RGB format. 000 = 565 (Default) 001 = 555 100 = 444 Others = Reserved
8:7	DOUTFMT	RW 0x0	CCIC's Output Data Format 00 = YCbCr (Default) 01 = RGB 10 = Bayer 11 = Reserved NOTE: Possible values of DOUTFMT based on <DINFMT>: DINFMT = 00, DOUTFMT = 00 DINFMT = 01, DOUTFMT = 01 DINFMT = 10, DOUTFMT = 10
6:5	DINFMT	RW 0x0	CCIC's Input Data Format (CMOS Sensor's Output Data Format) 00 = YCbCr (Default) 01 = RGB 10 = Bayer 11 = Reserved
4	Reserved	RW(0x0	Reserved

Table 175: Control 0 Register (Continued)
Offset: 0x3C

Bits	Field	Type/ Init Val	Description																	
3:2	RGBENDFMT	RW 0x0	RGB Endianness Format When <RGBINOUTFMT> = 000 (RGB 565)																	
			<table><tr><th><RGBENDFMT></th><th colspan="2">CMOS Sensor Output</th></tr><tr><th>First Byte</th><th>Second Byte</th></tr><tr><td>00</td><td>{Red[7:3], Green[7:5]}</td><td>{Green[4:2], Blue[7:3]}</td></tr><tr><td>01</td><td>{Green[4:2], Red[7:3]}</td><td>{Blue[7:3], Green[7:5]}</td></tr><tr><td>10</td><td>{Green[4:2], Blue[7:3]}</td><td>{Red[7:3], Green[7:5]}</td></tr><tr><td>11</td><td>{Blue[7:3], Green[7:5]}</td><td>{Green[4:2], Red[7:3]}</td></tr></table>	<RGBENDFMT>	CMOS Sensor Output		First Byte	Second Byte	00	{Red[7:3], Green[7:5]}	{Green[4:2], Blue[7:3]}	01	{Green[4:2], Red[7:3]}	{Blue[7:3], Green[7:5]}	10	{Green[4:2], Blue[7:3]}	{Red[7:3], Green[7:5]}	11	{Blue[7:3], Green[7:5]}	{Green[4:2], Red[7:3]}
			<RGBENDFMT>	CMOS Sensor Output																
			First Byte	Second Byte																
			00	{Red[7:3], Green[7:5]}	{Green[4:2], Blue[7:3]}															
			01	{Green[4:2], Red[7:3]}	{Blue[7:3], Green[7:5]}															
			10	{Green[4:2], Blue[7:3]}	{Red[7:3], Green[7:5]}															
			11	{Blue[7:3], Green[7:5]}	{Green[4:2], Red[7:3]}															
			When <RGBINOUTFMT> = 100 (RGB 444)																	
			<table><tr><th><RGBENDFMT></th><th colspan="2">CMOS Sensor Output</th></tr><tr><th>First Byte</th><th>Second Byte</th></tr><tr><td>00</td><td>{Red[7:4], Green[7:4]}</td><td>{Blue[7:4], 0000}</td></tr><tr><td>01</td><td>{0000, Red[7:4]}</td><td>{Green[7:4], Blue[7:4]}</td></tr><tr><td>10</td><td>{Blue[7:4], Green[7:4]}</td><td>{Red[7:4], 0000}</td></tr><tr><td>11</td><td>{0000, Blue[7:4]}</td><td>{Green[7:4], Red[7:4]}</td></tr></table>	<RGBENDFMT>	CMOS Sensor Output		First Byte	Second Byte	00	{Red[7:4], Green[7:4]}	{Blue[7:4], 0000}	01	{0000, Red[7:4]}	{Green[7:4], Blue[7:4]}	10	{Blue[7:4], Green[7:4]}	{Red[7:4], 0000}	11	{0000, Blue[7:4]}	{Green[7:4], Red[7:4]}
			<RGBENDFMT>	CMOS Sensor Output																
			First Byte	Second Byte																
00	{Red[7:4], Green[7:4]}	{Blue[7:4], 0000}																		
01	{0000, Red[7:4]}	{Green[7:4], Blue[7:4]}																		
10	{Blue[7:4], Green[7:4]}	{Red[7:4], 0000}																		
11	{0000, Blue[7:4]}	{Green[7:4], Red[7:4]}																		
When <RGBINOUTFMT> = 001 (RGB 555)																				
<table><tr><th><RGBENDFMT></th><th colspan="2">CMOS Sensor Output</th></tr><tr><th>First Byte</th><th>Second Byte</th></tr><tr><td>00</td><td>{Red[7:3], Green[7:5]}</td><td>{Green[4:3], Blue[7:3], 0}</td></tr><tr><td>01</td><td>{0, Red[7:3], Green[7:6]}</td><td>{Green[5:3], Blue[7:3]}</td></tr><tr><td>10</td><td>{Blue[7:3], Green[7:5]}</td><td>{Green[4:3], Red[7:3], 0}</td></tr><tr><td>11</td><td>{0, Blue[7:3], Green[7:6]}</td><td>{Green[5:3], Red[7:3]}</td></tr></table>	<RGBENDFMT>	CMOS Sensor Output		First Byte	Second Byte	00	{Red[7:3], Green[7:5]}	{Green[4:3], Blue[7:3], 0}	01	{0, Red[7:3], Green[7:6]}	{Green[5:3], Blue[7:3]}	10	{Blue[7:3], Green[7:5]}	{Green[4:3], Red[7:3], 0}	11	{0, Blue[7:3], Green[7:6]}	{Green[5:3], Red[7:3]}			
<RGBENDFMT>	CMOS Sensor Output																			
First Byte	Second Byte																			
00	{Red[7:3], Green[7:5]}	{Green[4:3], Blue[7:3], 0}																		
01	{0, Red[7:3], Green[7:6]}	{Green[5:3], Blue[7:3]}																		
10	{Blue[7:3], Green[7:5]}	{Green[4:3], Red[7:3], 0}																		
11	{0, Blue[7:3], Green[7:6]}	{Green[5:3], Red[7:3]}																		
1	DSTOPSEL	RW 0x0	Panasonic DSTOP Select Reserved																	

Table 175: Control 0 Register (Continued)
Offset: 0x3C

Bits	Field	Type/ Init Val	Description
0	EN	RW 0x0	CCIC Enable Write 1 only after all registers have been initialized to proper values. 0 = Disable (Default) 1 = Enable

Table 176: Control 1 Register
Offset: 0x40

Bits	Field	Type/ Init Val	Description
31:30	Reserved	RW 0x0	Reserved
29	BUSCLKG	RW 0x0	Bus Clock gating control (test only) 0 = CCIC's DMA Clock is always free running (Default) 1 = CCIC's DMA Clock is automatically gated when not in use
28	PWRDNEN	RW 0x1	Power Down Enable 0 = Normal Operation 1 = Power Down. External Sensor is assumed to be in power-off state. All CCIC's output PADs are tristated. All CCIC's input PADs are gated. The actual tristating and gating of the PADs is only done when external sensor power is off, which is controlled by GPIO.
27	FRMNUMSEL	RW 0x0	Frame Number Select Controls the number of CCIC's "ping-pong" buffers. 0 = 3 Frames 1 = 2 Frames
26:25	DMABRSTSEL	RW(0x0	DMA Burst Size Select 00 = Burst of 32-byte 01 = Burst of 16-byte 10 = Burst of 64-byte (Recommended) 11 = Reserved
24	YUV420SEL	RW(0x0	YUV 420 Select 0 = Drop Odd Line 1 = Drop Even Line When down-scale is enabled (<DSCALE> field in the Control 0 Register (Table 175 p. 132)), this bit must be programmed to 1.
23:20	RGBALPHA	RW 0x0	Defines the Alpha Blending value when <RGBINOUTFMT> is set to the following values: 001 = ARGB 1555, <RGBALPHA> bit [0] is used as Alpha value 100 = aRGB 4444, <RGBALPHA> bit [3:0] are used as Alpha value

Table 176: Control 1 Register (Continued)
Offset: 0x40

Bits	Field	Type/ Init Val	Description
19	VCLKG	RW 0x0	Internal vclk gating control (test only) 0 = internal vclk is always free running (Default) 1 = internal vclk is gated during horizontal and vertical blanking
18	Reserved	RW	Reserved for future use
17	GCEN	RW 0x0	Gamma Correction Reserved
16	SCEN	RW 0x0	Shading Correction Reserved
15:0	Reserved	RSVD	Reserved for future use

Table 177: Clock Control Register
Offset: 0x88

Bits	Field	Type/ Init Val	Description
31	Reserved	RW 0x0	Reserved
30:29	INTPIXCLKSEL	RW 0x0	Internal PIXCLK Select 00 = PIXMCLK 01 = PIXCLK 10 = PCI Clock 11 = Core clock
28	Reserved	RW 0x0	Reserved
27:16	CLKFT	RW 0x0	Clock Fine Tune NOTE: Suppose the desired PIXMCLK frequency = FREQ. Program CLKDIV and CLKFT such that: CLKDIV = floor(core clock / FREQ) CLKFT = [((core clock/CLKDIV) - FREQ)/(core clock/CLKDIV)] * 0xFFF For example: When the clock source is 48 MHz and the sensor requires 8 MHz clock: set <CLKDIV> = 0x0006 and <CLKFT> = 0x000 When the clock source is 48 MHz and the sensor requires 10 MHz clock: set <CLKDIV> = 0x0004 and <CLKFT> = 0x2AB

Table 177: Clock Control Register (Continued)
Offset: 0x88

Bits	Field	Type/ Init Val	Description
15:0	CLKDIV	RW 0x0	Clock Divider Value for PIXMCLK 0 = PIXMCLK is gated (no clock) Other = PIXMCLK is core clock divided by CLKDIV and CLKFT NOTE: Suppose the desired PIXMCLK frequency = FREQ. Program CLKDIV and CLKFT such that: $CLKDIV = \text{floor}(\text{core clock} / \text{FREQ})$ $CLKFT = [((\text{core clock} / CLKDIV) - \text{FREQ}) / (\text{core clock} / CLKDIV)] * 0xFFF$ For example: When the clock source is 48 MHz and the sensor requires 8 MHz clock: set <CLKDIV> = 0x0006 and <CLKFT> = 0x000 When the clock source is 48 MHz and the sensor requires 10 MHz clock: set <CLKDIV> = 0x0004 and <CLKFT> = 0x2AB

Table 178: SRAM TC0 Register (Test Only)
Offset: 0x8C

Bits	Field	Type/ Init Val	Description
31:0	SRAMTC0	RW 0x0	SRAM Timing Control 0

Table 179: SRAM TC1 Register (Test Only)
Offset: 0x90

Bits	Field	Type/ Init Val	Description
31:0	SRAMTC1	RW 0x0	SRAM Timing Control 1

Table 180: General Purpose (GPR) Register
Offset: 0xB4

Bits	Field	Type/ Init Val	Description
15:6	Reserved	RSVD	Reserved
5	CTL1PADEN	RW 0x0	SENSOR_CTL1 Pad Enable 0 = SENSOR_CTL1 Pad is tristated 1 = CTL1 drives SENSOR_CTL1 Pad

Table 180: General Purpose (GPR) Register (Continued)
Offset: 0xB4

Bits	Field	Type/ Init Val	Description
4	CTL0PADEN	RW 0x0	SENSOR_CTL0 Pad Enable 0 = SENSOR_CTL0 Pad is tristated 1 = CTL0 drives SENSOR_CTL0 Pad
3:2	Reserved	RSVD	Reserved
1	CTL1	RW 0x0	Sensor Control 1 Controls SENSOR_CTL1 Pad.
0	CTL0	RW 0x0	Sensor Control 0 Controls SENSOR_CTL0 Pad.

Table 181: TWSI Control 0 Register
Offset: 0xB8

Bits	Field	Type/ Init Val	Description
31:25	Reserved	RO 0x0	Reserved
24	TWSI_DRIVE_SEL	RW 0x0	Select the way TWSI_SDATA pad is driven. 0 = CCIC drives pad enable only 1 = CCIC drives both pad enable and pad input In both cases, external resistor pull-up is required.
23	TWSI_RDSTP	RW 0x0	Insert Stop before re-start during TWSI read access This bit must be set when using Omnivision sensor. 0 = No Stop before re-start during read access 1 = Stop is inserted before re-start during read access
22	TWSI_MASKACK	RW 0x0	TWSI Acknowledge Mask When enabled, allow CCIC's TWSI controller to ignore the Ack bit driven by the TWSI slave. 0 = Ack from slave is not masked 1 = Ack from slave is masked
21	TWSI_SWMD_DATA	RW 0x1	TWSI Software Mode Data When <TWSI_SWMD_EN> = 1, this bit controls TWSI_SDATA PAD.
20	TWSI_SWMD_CLK	RW 0x1	TWSI Software Mode CLK When <TWSI_SWMD_EN> = 1, this bit controls TWSI_SCLK PAD.
19	TWSI_SWMD_EN	RW 0x0	TWSI Software Mode Enable 0 = Hardware mode 1 = TWSI PADs (TWSI_SCLK and TWSI_SDATA) are controlled by TWSI_SWMD_CLK and TWSI_SWMD_DATA
18:10	TWSI_CLKDIV	RW 0x0	Defines the divider value for TWSI_SCLK TWSI_SCLK frequency = PCI Clock / (4*(TWSI_CLKDIV+1))

Table 181: TWSI Control 0 Register (Continued)
Offset: 0xB8

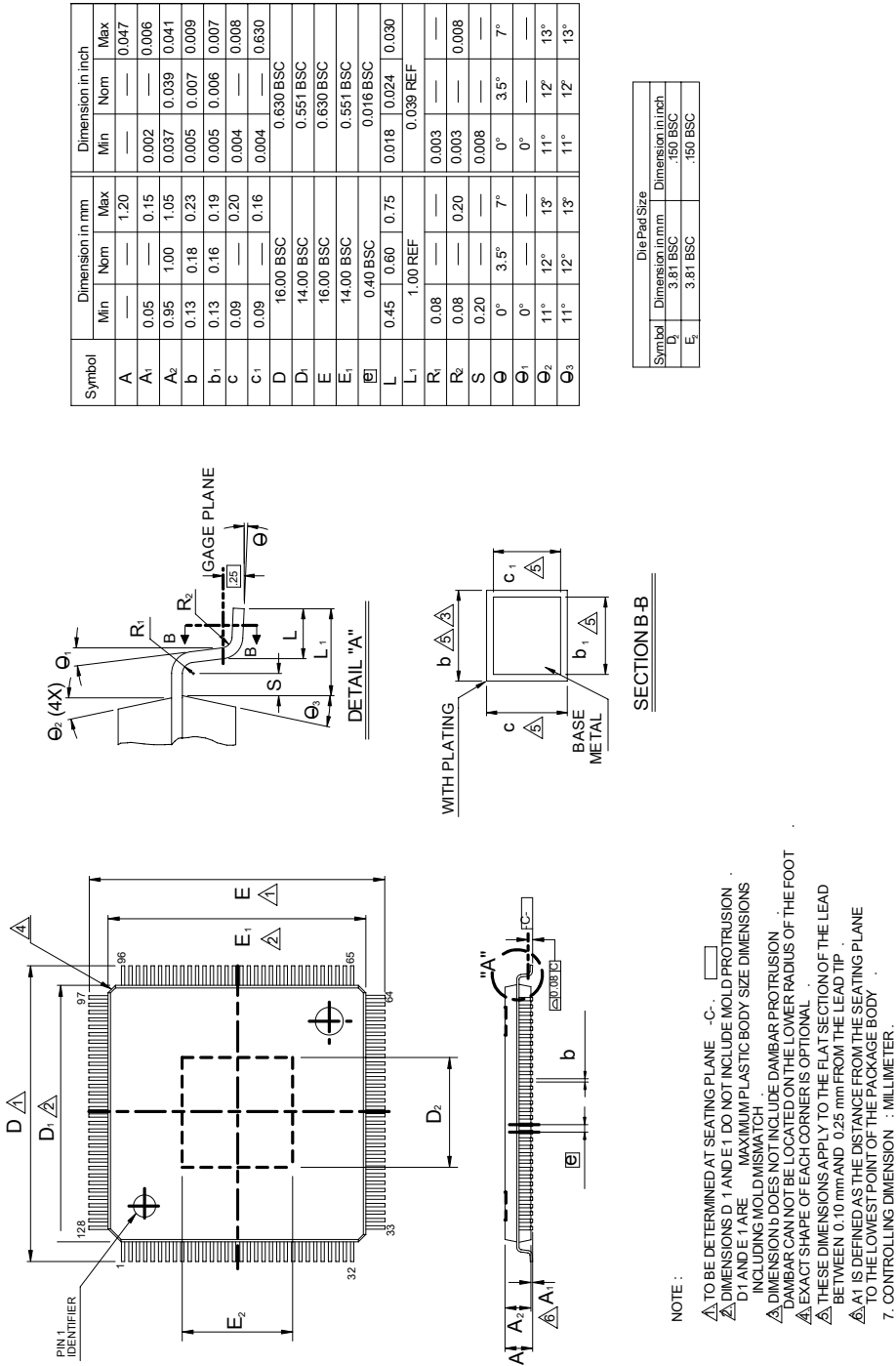
Bits	Field	Type/ Init Val	Description
9:2	TWSIID	RW 0x0	Slave ID Register
1	TWSIMODE	RW 0x0	TWSI Mode 0 = 8-bit (Default) 1 = 16-bit
0	TWSIEN	RW 0x0	TWSI Enable 0 = Disable (Default) 1 = Enable

Table 182: TWSI Control 1 Register
Offset: 0xBC

Bits	Field	Type/ Init Val	Description
31:28	Reserved	RO 0x0	Reserved
27	TWSIERR	RW 0x0	TWSI Error indication, due to NACK by CMOS sensor 0 = No error (Default) 1 = Error Write 0 to clear.
26	TWSIRVLD	RO 0x0	0 = Read data (bit [15:0]) is not ready (Default) 1 = Read data (bit [15:0]) is ready TWSIRVLD is immediately reset to 0 following a write to this register.
25	TWSIWSTAT	RO 0x0	0 = No write or write is done (Default) 1 = Write is in progress. TWSIWSTAT is immediately set to 1 following a write to this register with <TWSIRnW> = 0.
24	TWSIRnW	RW 0x0	0 = Write (Default) 1 = Read
23:16	TWSIADDR	RW 0x0	TWSI Address
15:0	TWSIDATA	RW 0x0	A write to this register triggers TWSI access

4 Mechanical Drawings

Figure 21: 128-pin TQFP Mechanical Drawing



- All dimensions in mm.
- See Section 6, Part Order Numbering/Package Marking, on page 156 for package marking information and pin 1 location on package.

Note

5 Electrical Specifications

5.1 Absolute Maximum Ratings

Table 183: Absolute Maximum Ratings

Symbol	Parameter	Min	Typ	Max	Units
VDD ¹	Power supply voltage with respect to VSS 88ALP01 pins: VDD	-0.5	1.2	+1.5 or VDDO+0.5, whichever is less	V
VDDO	Power supply voltage with respect to VSS 88ALP01 pins: VDDO	-0.5	3.3	+4.0	V
VDDOC	Power supply voltage with respect to VSS 88ALP01 pins: VDDOC	-0.5	2.5 to 3.3	+4.0	V
T _{STORAGE}	Storage temperature	-55	--	+125	°C

1. VDD must never be more than 0.5V greater than VDDO or damage results. This implies that power must be applied to VDDO before or at the same time as VDD.

5.2 Recommended Operating Conditions

Table 184: Recommended Operating Conditions

Symbol	Parameter	Condition	Min	Typ	Max	Units
AVDD_PLL	3.3V PLL Power		3.14	3.3	3.46	V
T _A	Ambient operating temperature		0	--	70	°C
T _J	Maximum junction temperature		--	--	125	°C
VDD	Core power supply		1.14	1.20	1.26	V
VDDO	3.3V digital I/O power supply	VDDO	3.14	3.3	3.46	V
VDDOC	Digital 2.5 to 3.3V power supply for camera interface		2.38	2.5 to 3.3	3.46	V

5.3 Package Thermal Conditions

Table 185: 14 x 14 mm TQFP Package

Symbol	Parameter	Condition	Min	Typ	Max	Units
θ_{JA}	Thermal resistance. Junction to ambient of device package. $\theta_{JA} = (T_J - T_A) / P$ P = total power dissipation	Joint Electronic Device Engineering Council (JEDEC) 3 in. x 4.5 in. 4-layer Printed Circuit Board (PCB) with no air flow	--	32.60	--	°C/W
		JEDEC 3 in. x 4.5 in. 4-layer PCB with 1 m/s air flow	--	29.50	--	°C/W
		JEDEC 3 in. x 4.5 in. 4-layer PCB with 2 m/s air flow	--	28.40	--	°C/W
		JEDEC 3 in. x 4.5 in. 4-layer PCB with 3 m/s air flow	--	27.80	--	°C/W
ψ_{JT}	Thermal characteristic parameter. Junction to ambient of device package. $\psi_{JT} = (T_J - T_{TOP}) / P$ T_{TOP} = temperature on top center of package P = total power dissipation	JEDEC 3 in. x 4.5 in. 4-layer PCB with no air flow	--	0.24	--	°C/W
		JEDEC 3 in. x 4.5 in. 4-layer PCB with 1 m/s air flow	--	0.44	--	°C/W
		JEDEC 3 in. x 4.5 in. 4-layer PCB with 2 m/s air flow	--	0.56	--	°C/W
		JEDEC 3 in. x 4.5 in. 4-layer PCB with 3 m/s air flow	--	0.65	--	°C/W
θ_{JC}	Thermal resistance. Junction to ambient of device package. $\theta_{JC} = (T_J - T_C) / P_{TOP}$ P_{TOP} = power dissipation from top of package	JEDEC with no air flow	--	12.40	--	°C/W
θ_{JB}	Thermal resistance. Junction to ambient of device package. $\theta_{JB} = (T_J - T_B) / P_{BOTTOM}$ P_{BOTTOM} = power dissipation from bottom of package to PCB surface	JEDEC with no air flow	--	23.10	--	°C/W

5.4 DC Electrical Characteristics

5.4.1 Current Consumption AVDD_PLL

Table 186: Current Consumption AVDD_PLL

Over full range of values listed in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Pins	Condition	Min	Typ	Max	Units
I_{AVDD_PLL}	3.3V power to analog PLL	AVDD_PLL		--	1	--	mA

5.4.2 Current Consumption VDD

Table 187: Current Consumption VDD

Over full range of values listed in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Pins	Condition	Min	Typ	Max	Units
I _{VDD}	Core power (1.2V)	VDD		--	50	--	mA

5.4.3 Current Consumption VDDO

Table 188: Current Consumption VDDO

Over full range of values listed in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Pins	Condition	Min	Typ	Max	Units
I _{VDDO}	I/O power (3.3V)	VDDO		--	20	--	mA

5.4.4 Current Consumption VDDOC

Table 189: Current Consumption VDDOC

Over full range of values listed in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Pins	Condition	Min	Typ	Max	Units
I _{VDDOC}	I/O power for camera interface (2.5 to 3.3V)	VDDOC		--	4	--	mA

5.5 Input Clock Specifications

Table 190: 24 MHz Reference Clock Timing

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
T _{P_REF_CLK}	REF_CLK period		41.667 - 50 ppm	41.667	41.667 + 25 ppm	ns
T _{H_REF_CLK}	REF_CLK high time		18.75	20.833	22.917	ns
T _{L_REF_CLK}	REF_CLK low time		18.75	20.833	22.917	ns
T _{R_REF_CLK}	REF_CLK rise time		--	--	3	ns
T _{R_REF_CLK}	REF_CLK rise time		--	--	5	ns
T _{F_REF_CLK}	REF_CLK fall time		--	--	3	ns

5.6 Internal Resistors

Table 191: Internal Resistors

Resistor Strength	Pin Name	Pin #
NAND Flash		
800 k Ω Internal pull-up	NF_ALE	50
	NF_CEn[1:0]	48, 52
	NF_CLE	51
	NF_WEn	49
	NF_IO[7:0]	36, 31, 38, 39, 40, 41, 42, 46
	NF_RDY	54
	NF_REn	53
	NF_WPn	47
VPD TWSI		
100 k Ω Internal pull-up	VPD_CLK	10
	VPD_DATA	9

5.7 PCI Bus Interface Unit

5.7.1 DC Electricals

Table 192: PCI Bus Interface Unit DC Specifications

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
C _{CLK}	CLK pin capacitance		5	--	12	pF
C _{IDSEL}	IDSEL pin capacitance		--	--	8	pF
C _{IN}	Input pin capacitance		--	--	10	pF
I _{IL}	Input leakage current	0 < V _{IH} < VDDO	--	--	±10	μA
I _{OFF}	PMEn input leakage	VDDO ≤ 3.6V, VDDO off or floating	--	--	1	μA
V _{IH}	Input high voltage		0.5VDDO	--	VDDO+0.5	V
V _{IL}	Input low voltage		-0.5	--	0.3VDDO	V
V _{IPU}	Input pull-up voltage		0.7VDDO	--	--	V
V _{OH}	Output high voltage	I _{OUT} = -500 μA	0.9VDDO	--	--	V
V _{OL}	Output low voltage	I _{OUT} = 1500 μA	--	--	0.1VDDO	V

5.7.2 AC Electricals

Table 193: PCI Bus Interface Unit AC Specifications

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
I_{CH}	High clamp current	$V_{DDO} + 4 > V_{IN} \geq V_{DDO} + 1$	$25 + (V_{IN} - V_{DDO} - 1) / 0.015$	--	--	mA
I_{CL}	Low clamp current	$-3 < V_{IN} \leq -1$	$+25 + (V_{IN} + 1) / 0.015$	--	--	mA
$I_{OH(AC)}$	Switching current high	$0 < V_{OUT} \leq 0.3V_{DDO}$	$-12V_{DDO}$	--	--	mA
		$0.3V_{DDO} < V_{OUT} < 0.9V_{DDO}$	$-17.1 (V_{DDO} - V_{OUT})$	--	--	mA
		$0.7V_{DDO} < V_{OUT} < V_{DDO}$		--	1	
	(Test point)	$V_{OUT} = 0.7V_{DDO}$		--	$-32V_{DDO}$	mA
$I_{OL(AC)}$	Switching current low	$V_{DDO} > V_{OUT} \geq 0.6V_{DDO}$	$16V_{DDO}$	--	--	mA
		$0.6V_{DDO} > V_{OUT} > 0.1V_{DDO}$	$26.7V_{OUT}$	--	--	mA
		$0.18V_{DDO} > V_{OUT} > 0$		--	2	
	(Test point)	$V_{OUT} = 0.18V_{DDO}$		--	$38V_{DDO}$	mA
T_{SLEW_FALL}	Output fall slew rate	$0.6V_{DDO} - 0.2V_{DDO}$ I load	1	--	4	V/ns
T_{SLEW_RISE}	Output rise slew rate	$0.2V_{DDO} - 0.6V_{DDO}$ I load	1	--	4	V/ns

1. $I_{OH} = (0.98/V_{DDO}) * (V_{OUT} - V_{DDO}) * (V_{OUT} + 0.4V_{DDO})$ for $V_{DDO} > V_{OUT} > 0.7V_{DDO}$

2. $I_{OL} = (256/V_{DDO}) * V_{OUT} * (V_{DDO} - V_{OUT})$ for $0V < V_{OUT} < 0.18V_{DDO}$

5.7.3 Protocol Timing

Table 194: 66 and 33 MHz PCI Timing

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	PCI 66		PCI 33		Units
		Min	Max	Min	Max	
T_H	Input hold time from CLK	0	--	0	--	ns
T_{OFF}	Active to float delay	--	14	--	28	ns
T_{ON}	Float to active delay	2	--	2	--	ns

Table 194: 66 and 33 MHz PCI Timing (Continued)

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	PCI 66		PCI 33		Units
		Min	Max	Min	Max	
T _{RHFA}	RSTn high to first configuration access	2 ²⁵	--	2 ²⁵	--	clocks
T _{RHFF}	RSTn high to first FRAMEn assertion	5	--	5	--	clocks
T _{RST}	Reset active time after power stable	1	--	1	--	ns
T _{RST_CLK}	Reset active time after CLK stable	100	--	100	--	ns
T _{RST_OFF}	Reset active to output float delay	--	40	--	40	ns
T _{SU}	Input setup time to CLK-based signals	3	--	7	--	ns
T _{SU(PTP)}	Input setup time to CLK-point to point signals	5	--	10, 12	--	ns
T _{VAL}	CLK to signal valid delay-based signals	2	6	2	11	ns
T _{VAL(PTP)}	CLK to signal valid delay-point to point signals	2	6	2	12	ns

5.8 NAND Flash Controller

5.8.1 DC Electricals

Table 195: NAND Flash DC Specifications

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V _{IH}	Input high voltage		--	2.6	--	V
V _{IL}	Input low voltage		--	0.6	--	V
V _{OH}	Output high voltage		--	2.4	--	V
V _{OL}	Output low voltage		--	0.4	--	V

5.8.2 Protocol Timing


Note

The following NAND Flash Controller timing parameters are achieved by setting:

- Timing Parameter Register 1 ([Table 96 p. 95](#)) to 0x10100900
- Timing Parameter Register 2 ([Table 97 p. 96](#)) to 0x00010102
- Timing Parameter Register 3 ([Table 98 p. 96](#)) to 0x10000000

Figure 22: NAND Flash Command Write

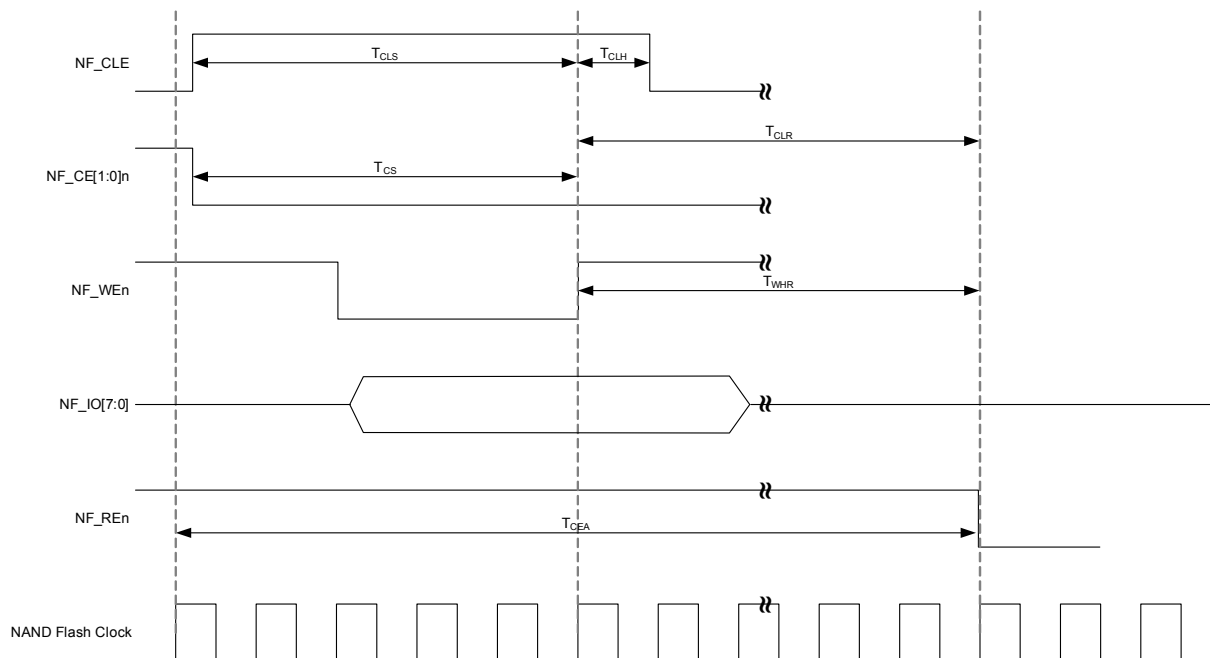


Figure 23: NAND Flash Address Write

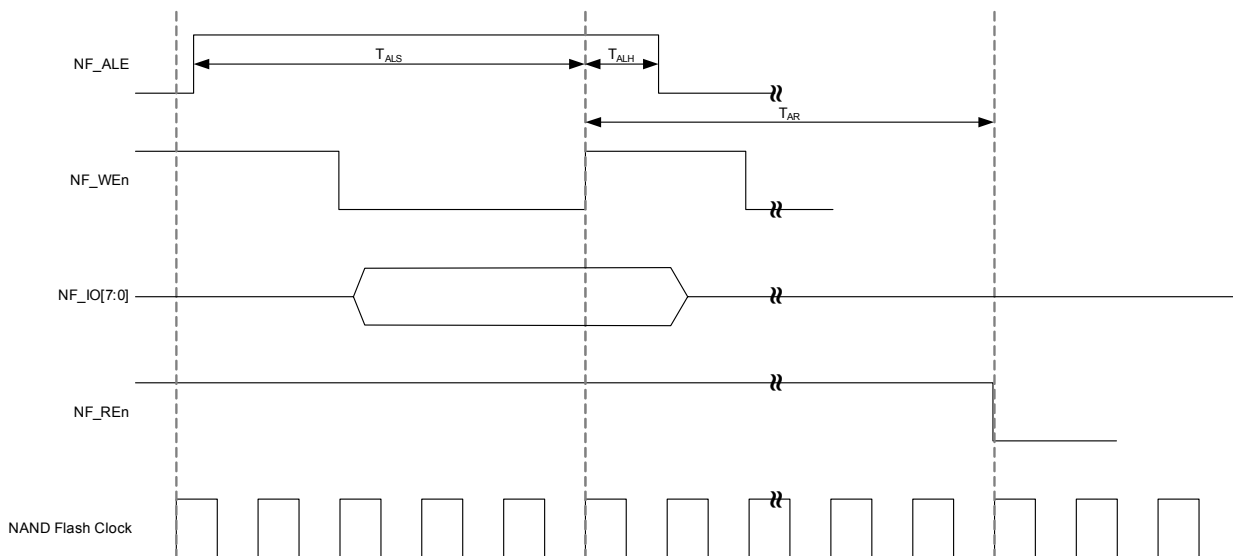


Figure 24: NAND Flash Data Write

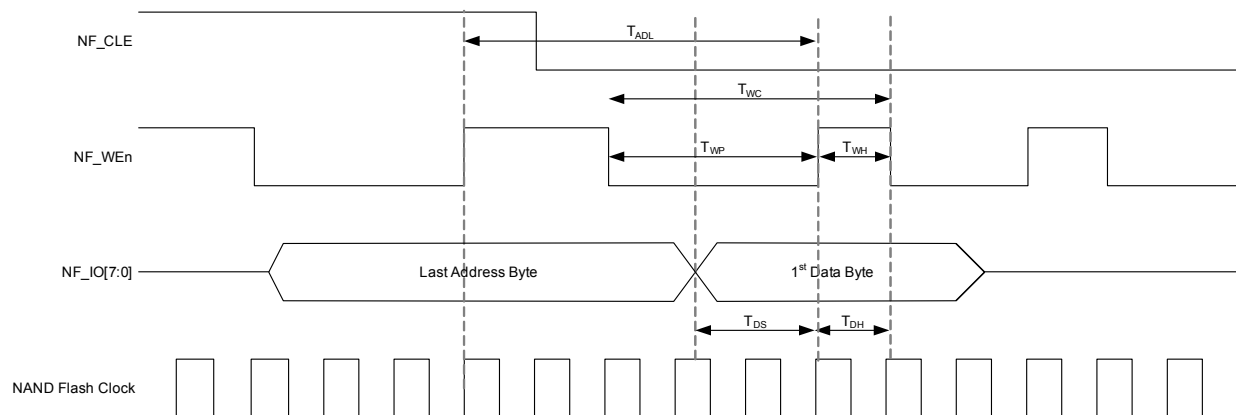


Figure 25: NAND Flash Data Read

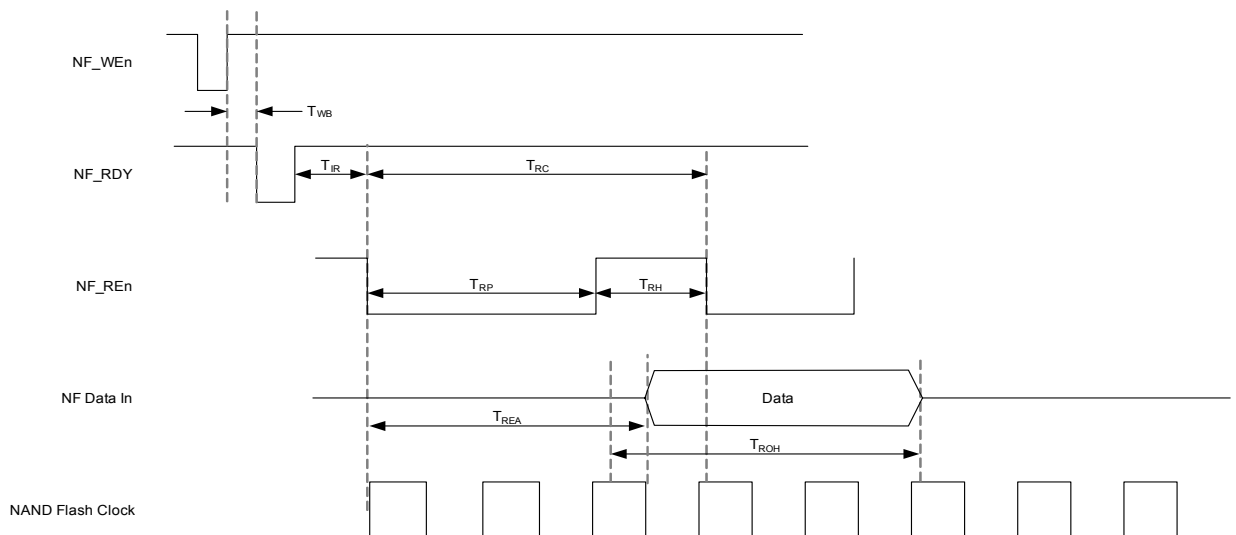


Table 196: NAND Flash Timing

Symbol	Parameter	Note	Min	Typ	Max	Units
T _{ADL}	Address to data loading time	Requires one dummy address cycle	104	--	--	ns
T _{ALH}	NF_ALE hold time		10.4	--	--	ns
T _{ALS}	NF_ALE setup time		20.8	--	--	ns
T _{AR}	NF_ALE to NF_REn delay		104	--	--	ns
T _{CEA}	NF_CE access time		--	--	260	ns
T _{CLH}	NF_CLE hold time		10.4	--	--	ns

Table 196: NAND Flash Timing (Continued)

Symbol	Parameter	Note	Min	Typ	Max	Units
T _{CLR}	NF_CLE to NF_REn delay		135	--	--	ns
T _{CLS}	NF_CLE setup time		52	--	--	ns
T _{CS}	NF_CE setup time		52	--	--	ns
T _{DH}	Data hold time		10.4	--	--	ns
T _{DS}	Data setup time		20.8	--	--	ns
T _{RC}	Read cycle time		31.2	--	--	ns
T _{REA}	NF_REn access time	Max tolerable delay = 25.5 ns	--	--	25	ns
T _{RP}	NF_REn pulse width		20.8	--	--	ns
T _{RR}	Ready to NF_REn low		31.2	--	--	ns
T _{WB}	NF_WEn high to busy		--	--	104	ns
T _{WC}	Write cycle time		41.6	--	--	ns
T _{WH}	NF_WEn high hold time		10.4	--	--	ns
T _{WHR}	NF_WEn high to NF_REn low		104	--	--	ns
T _{WP}	NF_WEn pulse width		31.2	--	--	ns

5.9 SDIO

5.9.1 DC Electricals

Table 197: SDIO DC Specifications

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V _{IH}	Input high voltage		0.625 * V _{DD}	--	V _{DD} + 0.3	V
V _{IL}	Input low voltage		VSS - 0.3	--	0.25 * V _{DD}	V
V _{OH}	Output high voltage	I _{OH} = -100 µA @ V _{DD} min	0.75 * V _{DD}	--	--	V
V _{OL}	Output low voltage	I _{OL} = 100 µA @ V _{DD} min	--	--	0.125 * V _{DD}	V

5.9.2 Protocol Timing

Figure 26: SDIO Low Speed Timing Diagram

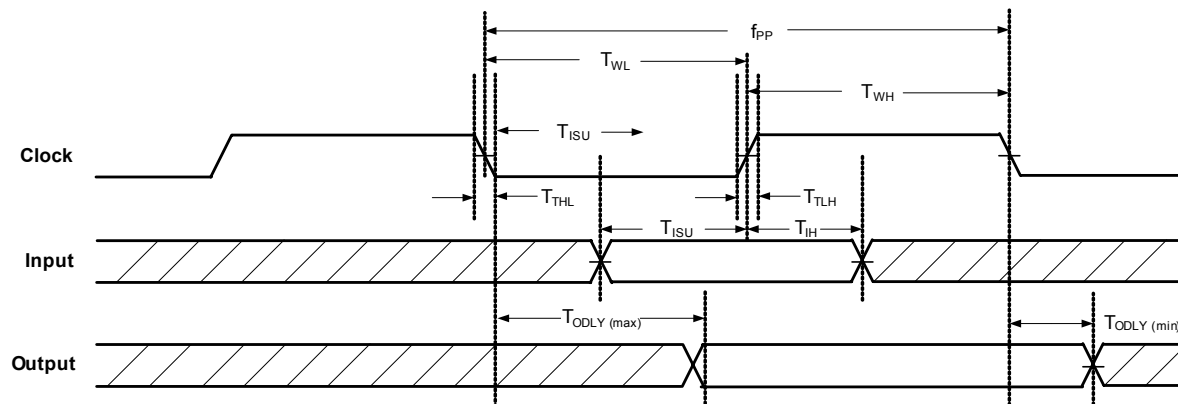


Table 198: SDIO Low Speed Timing

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

All clock values are referred to min (V_{IH}) and max (V_{IL}). All inputs and outputs are referenced to clock.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{OD}	Clock frequency identification mode (low frequency is required for MMC capability)		0/100 kHz	--	400	kHz
f_{PP}	Clock frequency data transfer mode		0	--	24	MHz
T_{IH}	Input hold time		5	--	--	ns
T_{ISU}	Input setup time		5.83	--	--	ns
T_{ODLY}	Output delay time during data transfer mode		--	--	14	ns
T_{ODLY}	Output delay time during identification mode		--	--	50	ns
T_{THL}	Clock fall time	CL $\leq$ 100 pF (7 cards)	--	--	10	ns
T_{THL}	Clock fall time		--	--	50	ns
T_{TLH}	Clock rise time	CL $\leq$ 250 pF (21 cards)	--	--	10	ns
T_{TLH}	Clock rise time	CL $\leq$ 100 pF (7 cards)	--	--	50	ns
T_{WH}	Clock high time	CL $\leq$ 100 pF (7 cards)	10	--	--	ns
T_{WH}	Clock high time	CL $\leq$ 250 pF (21 cards)	50	--	--	ns

Table 198: SDIO Low Speed Timing (Continued)

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

All clock values are referred to min (V_{IH}) and max (V_{IL}). All inputs and outputs are referenced to clock.

Symbol	Parameter	Condition	Min	Typ	Max	Units
T_{WL}	Clock low time	CL $\leq$ 100 pF (7 cards)	10	--	--	ns
T_{WL}	Clock low time	CL $\leq$ 250 pF (21 cards)	50	--	--	ns

Figure 27: SDIO High Speed Timing Diagram

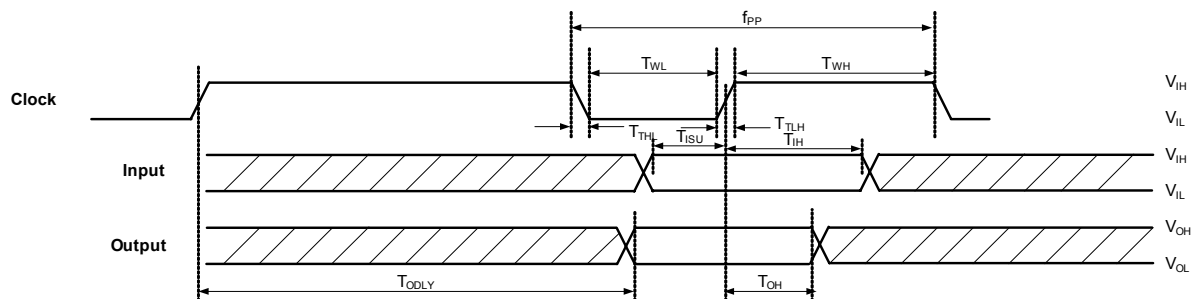


Table 199: SDIO High Speed Timing

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

All clock values are referred to min (V_{IH}) and max (V_{IL}). All inputs and outputs are referenced to clock.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{PP}	Clock frequency data transfer mode		0	--	48	MHz
T_{IH}	Input hold time		2	--	--	ns
T_{ISU}	Input setup time		6.83	--	--	ns
T_{ODLY}	Output delay time during data transfer mode		--	--	14	ns
T_{OH}	Output hold time		2.5	--	--	ns
T_{THL}	Clock fall time		--	--	3	ns
T_{TLH}	Clock rise time		--	--	3	ns
T_{WH}	Clock high time		7	--	--	ns
T_{WL}	Clock low time		7	--	--	ns

5.10 CMOS Camera Interface

5.10.1 DC Electricals

Table 200: CMOS Camera Interface DC Specifications

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{DD_IO}	DC supply voltage-I/O power		2.5	--	3.3	V
V_{IH}	Input high voltage		$0.7 \cdot V_{DD_IO}$	--	--	V
V_{IL}	Input low voltage		--	--	$0.3 \cdot V_{DD_IO}$	V
V_{OH}	Output high voltage	8 mA	$0.9 \cdot V_{DD_IO}$	--	--	V
V_{OL}	Output low voltage		--	--	$0.1 \cdot V_{DD_IO}$	V

5.10.2 Protocol Timing

Figure 28: CMOS Camera Interface TWSI Timing Diagram

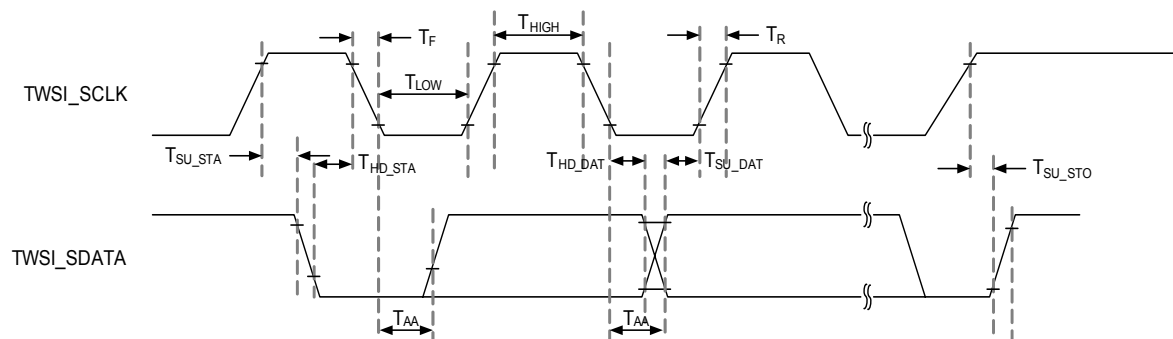


Figure 29: CMOS Camera Interface Timing Diagram

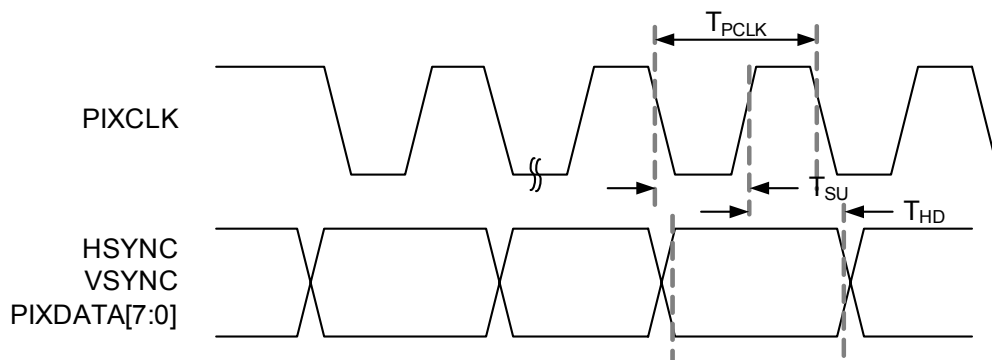


Table 201: CMOS Camera Timing

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
T _{AA}	Clock low to data out valid		--	0.25	--	clock period
T _{DH}	Data out hold time		--	0.25	--	clock period
T _{HD}	Hold time		4	--	--	ns
T _{HD_DAT}	Data in hold time		--	0.25	--	clock period
T _{HD_STA}	Start condition hold time		--	0.25	--	clock period
T _{HIGH}	Clock high period		0.13	Programmable	--	μs
T _{LOW}	Clock low period		0.13	Programmable	--	μs
T _{PIXCLK}	Input pixel clock		--	--	48	MHz
T _{PIXMCLK}	Output clock frequency		Programmable	--	48	MHz
T _{RISE_FALL}	Rise/fall times		--	--	3	ns
T _{SU}	Setup time		4	--	--	ns
T _{SU_DAT}	Data in setup time		--	0.25	--	clock period
T _{SU_STA}	Start condition setup time		--	0.25	--	clock period
T _{SU_STO}	Stop condition setup time		--	0.25	--	clock period
T _{TWSI_SCLK}	Clock frequency		--	Programmable	4 ¹	MHz

1. Clock controlled by TWSI Control 0 Register (Table 181 p. 138). Maximum TWSI clock is 4 MHz if PCI bus clock is 33 MHz.

5.11 JTAG Test Interface

5.11.1 DC Electricals

Table 202: JTAG Test Interface DC Specifications for 3.3V Signaling

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V _{OH}	Output high voltage	4 mA	2.4	--	--	V
V _{OL}	Output low voltage	4 mA	--	--	0.4	V

Table 202: JTAG Test Interface DC Specifications for 3.3V Signaling (Continued)

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IH}	Input high voltage	--	$0.6 \cdot V_{DDO}$	--	$V_{DDO} + 0.4$	V
V_{IL}	Input low voltage	--	-0.4	--	$0.3 \cdot V_{DDO}$	V

5.11.2 Protocol Timing

Figure 30: JTAG Timing Diagram

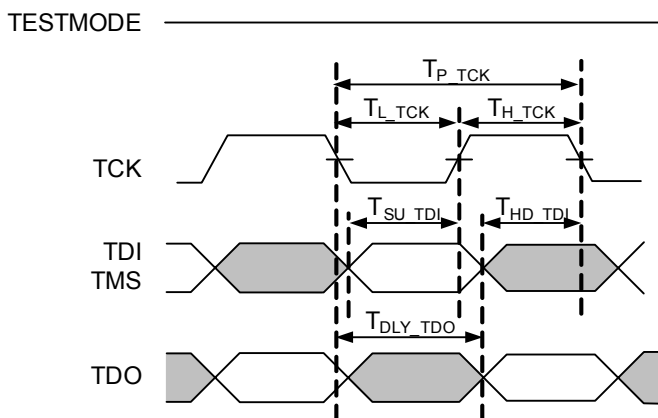


Table 203: JTAG Timing

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
T_{DLY_TDO}	TCK to TDO Delay	--	0	--	15	ns
T_{H_TCK}	TCK High	--	12	--	--	ns
T_{HD_TDI}	TDI, TMS to TCK Hold Time	--	10	--	--	ns
T_{L_TCK}	TCK Low	--	12	--	--	ns
T_{P_TCK}	TCK Period	--	40	--	--	ns
T_{SU_TDI}	TDI, TMS to TCK Setup Time	--	10	--	--	ns

5.12 GPIO

5.12.1 DC Electricals

Table 204: GPIO DC Specifications for 3.3V Signaling

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V _{IH}	Input high voltage	--	0.6*VDDO	--	VDDO+0.4	V
V _{IL}	Input low voltage	--	-0.4	--	0.3*VDDO	V
V _{OH}	Output high voltage	When I _{out} = 8 mA	2.4	--	--	V
V _{OL}	Output low voltage	When I _{out} = 8 mA	--	--	0.4	V

5.12.2 LED Mode

Table 205: LED Mode¹

Over full range of values specified in the Recommended Operating Conditions unless otherwise specified.

Symbol	Parameter	Condition	Min	Typ	Max	Units
I _{OH}	Switching current high	VDDO-0.4	25.0	--	--	mA
I _{OL}	Switching current low	0.4	25.0	--	--	mA

1. LED Mode is independently selectable for each GPIO pin.

6 Part Order Numbering/Package Marking

6.1 Part Order Numbering

Figure 31 shows the part order numbering scheme for the 88ALP01. Refer to Marvell Field Application Engineers (FAEs) or representatives for further information when ordering parts.

Figure 31: Sample Part Number

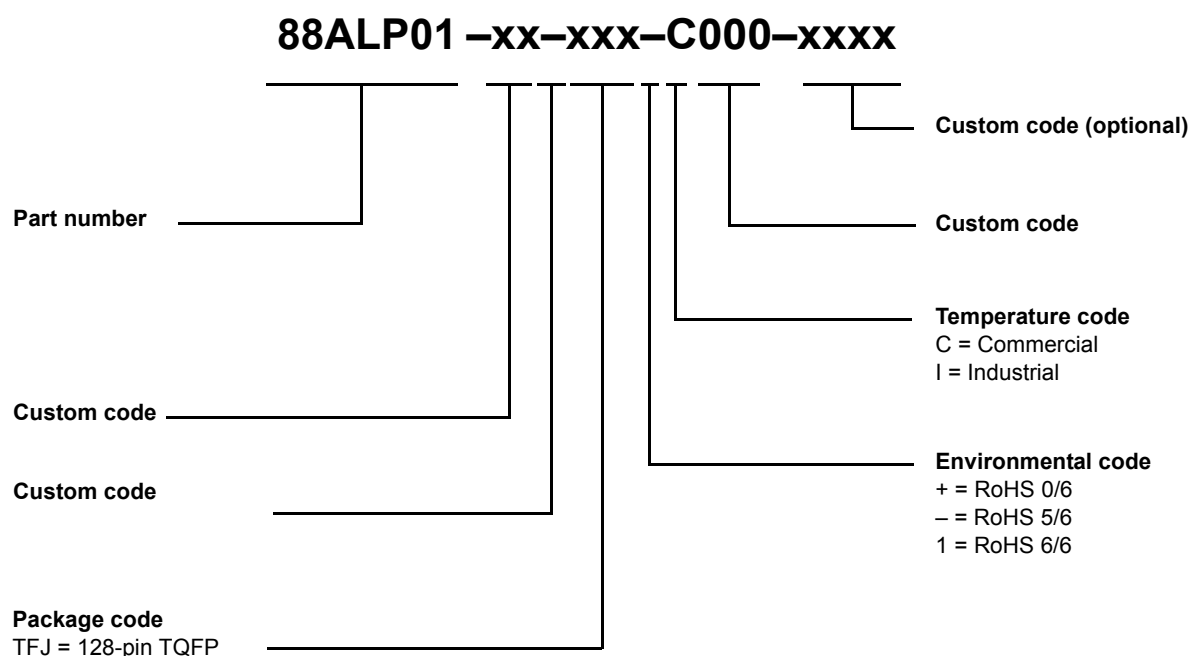


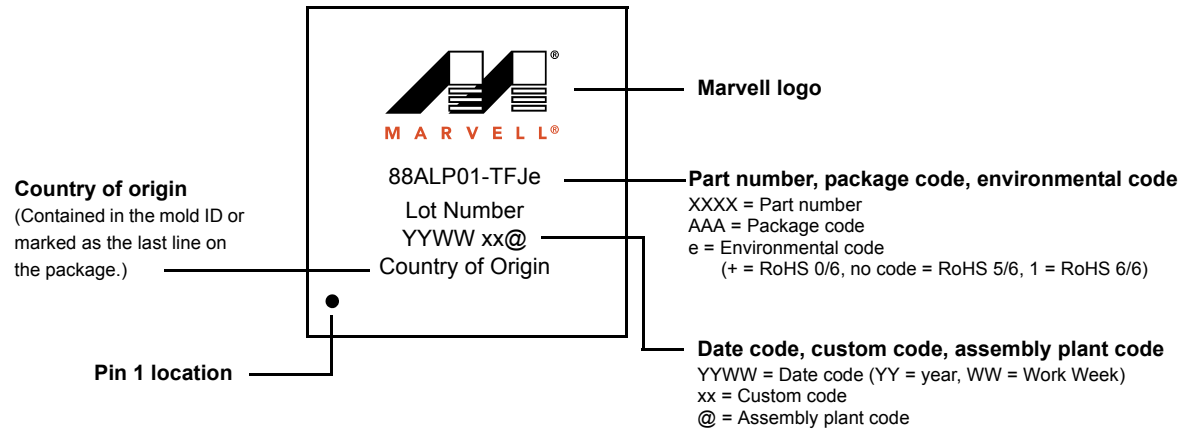
Table 206: 88ALP01 Part Order Options

Package Type	Part Order Number
128-pin TQFP with EPAD	88ALP01-xx-TFJ1C000 (RoHS 6/6 compliant package)

6.2 Package Marking

Figure 32 shows a sample Commercial package marking and pin 1 location for the 88ALP01.

Figure 32: Commercial Package Marking and Pin 1 Location



Note: The above drawing is not drawn to scale. Location of markings is approximate.

A

Acronyms and Abbreviations

Table 207: Acronyms and Abbreviations

Acronym	Definition
BIU	Bus Interface Unit
CCIC	CMOS Camera Interface Controller
CRC	Cyclic Redundancy Check
DMA	Direct Memory Address
EAV	End-of-Active-Video
ECR	Engineering Change Request
fOD	Open Drain frequency
JTAG	Joint Test Action Group
MSB	Most Significant Bit
NFC	NAND Flash Controller
PCI	Peripheral Component Interconnect
RCA	Relative Card Address
SAV	Start-of-Active-Video
SDIO	Secure Digital Input/Output
SPI	Serial Peripheral Interface
TWSI	Two-Wire Serial Interface
VPD	Vital Product Data

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